

HP ProLiant DL160 Gen8 Server User Guide

Abstract

This document is for the person who installs, administers, and troubleshoots servers and storage systems. HP assumes you are qualified in the servicing of computer equipment and trained in recognizing hazards in products with hazardous energy levels.



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Contents

Introduction	7
Server features	7
Component identification	8
Front panel components	8
Front panel LEDs and buttons	9
Rear panel components	9
Rear panel LEDs and buttons	10
System board components	11
DIMM slots	12
System maintenance switch	12
NMI jumper	13
Device numbers	13
Drive LED definitions	14
Fan modules	14
T-10/T-15 Torx screwdriver	16
Operations	17
Power up the server	17
Power down the server	17
Extend the server from the rack	17
Remove the server from the rack	18
Remove the access panel	19
Install the access panel	19
Remove the processor air baffle	19
Install the processor air baffle	20
Remove the PCI riser cage	20
Install the PCI riser cage	21
Setup	23
Optional installation services	23
Rack planning resources	23
Optimum environment	23
Space and airflow requirements	24
Temperature requirements	24
Power requirements	25
Electrical grounding requirements	25
Rack warnings	25
Contents of the server shipping carton	26
Installing hardware options	26
Installing the server into the rack	26
Powering up and configuring the server	27
Installing the operating system	28
Registering the server	28
Hardware options installation	29
Introduction	29
Processor and fan module option	29

Memory options	35
HP SmartMemory	35
Memory subsystem architecture	36
Single- and dual-rank DIMMs	37
DIMM identification.....	37
Memory configurations	38
Intel Gen8 supported memory bandwidth	38
RDIMM maximum memory configurations	39
UDIMM maximum memory configurations.....	39
Advanced ECC memory configuration.....	40
Lockstep memory configuration	40
Online Spare memory configuration.....	40
General DIMM slot population guidelines	40
Advanced ECC population guidelines	41
Lockstep Memory population guidelines.....	41
Online Spare population guidelines	42
Installing a DIMM.....	43
Hot-plug drive guidelines	44
Removing the drive blank.....	44
Installing a hot-plug drive	44
DVD-ROM and DVD-RW drive option	45
Controller options.....	49
FBWC option.....	49
FBWC capacitor pack	51
Installing the front video adapter cable.....	53
FlexibleLOM option	54
Expansion board options	56
Installing an expansion board	56
Common slot power supply option	57
Rack bezel option	59
Remove the rack bezel.....	59
Install the rack bezel.....	60
VGA power cable option	60
Mini-SAS cable option	61
Installing the 700mm mini-SAS cable	62
HP Trusted Platform Module option	62
Installing the Trusted Platform Module board	63
Retaining the recovery key/password.....	65
Enabling the Trusted Platform Module.....	65
Cabling	66
Cabling overview	66
Data cabling.....	66
P420 Smart Array Controller cabling	66
SATA cabling	67
Power cabling.....	67
Server power cabling	67
FBWC capacitor pack cabling.....	68
Front panel cabling	69
Internal USB cabling.....	69
Software and configuration utilities	71
Server mode	71
Server QuickSpecs	71

HP iLO Management Engine	71
HP iLO	71
Intelligent Provisioning	73
Scripting Toolkit	75
HP Service Pack for ProLiant	75
HP Smart Update Manager	75
HP ROM-Based Setup Utility	76
Using RBSU	76
Auto-configuration process	76
Boot options	77
Configuring AMP modes	77
Re-entering the server serial number and product ID	77
Utilities and features	78
Array Configuration Utility	78
Option ROM Configuration for Arrays	79
ROMPaq utility	79
Automatic Server Recovery	80
USB support	80
Redundant ROM support	80
Keeping the system current	81
Drivers	81
Software and firmware	81
Version control	81
HP Operating Systems and Virtualization Software Support for ProLiant Servers	82
HP Technology Service Portfolio	82
Change control and proactive notification	82
Troubleshooting	83
Troubleshooting resources	83
System battery	84
Regulatory compliance notices	86
Regulatory compliance identification numbers	86
Federal Communications Commission notice	86
FCC rating label	86
FCC Notice, Class A Equipment	86
FCC Notice, Class B Equipment	86
Declaration of conformity for products marked with the FCC logo, United States only	87
Modifications	87
Cables	87
Canadian notice (Avis Canadien)	87
European Union regulatory notice	88
Disposal of waste equipment by users in private households in the European Union	88
Japanese notice	89
BSMI notice	89
Korean notice	89
Chinese notice	90
Vietnam compliance marking notice	90
Ukraine notice	90
Laser compliance	90
Battery replacement notice	91
Taiwan battery recycling notice	91
Power cord statement for Japan	91

Acoustics statement for Germany (Geräuschemission)	92
Electrostatic discharge	93
Preventing electrostatic discharge	93
Grounding methods to prevent electrostatic discharge.....	93
Specifications	94
Environmental specifications	94
Server specifications	94
Power supply specifications.....	94
HP 460 W CS Power Supply (94%) specifications.....	95
HP 750 W CS Power Supply (94%) specifications.....	95
HP 500 W Multi-output Power Supply specifications	95
Power supply calculations	96
Technical support.....	97
Before you contact HP	97
HP contact information.....	97
Customer Self Repair	97
Acronyms and abbreviations	105
Documentation feedback	108
Index.....	109

Introduction

Server features

The HP ProLiant DL160 Gen8 Server comes with industry leading performance, efficiency, capacity, and reliability in a 1U space. The server provides enterprise-class design for performance workloads with versatile and future requirements, and it is ideal for performance-driven computing and storage in a dense rack package.

The HP ProLiant DL160 Gen8 Server is a space-conscious, dual processor performance server with industry leading feature sets. The server is built to protect your investment with reliability, accessibility, and serviceability features designed in.

The server includes the following features:

- 8 SFF or 4 LFF hot-plug drive models available for 8 TB or 12 TB capacity, with optional DVD
- Intel® Xeon® E5-2600 processor, with a choice of 2/4/6/8 cores, and speeds up to 3.0 GHz
- HP Smart Socket Guide for quick, precise intelligent processor installation
- 24 DIMM slots available for DDR3 Memory with 384 GB maximum capacity
- Maximum memory speed of 1600 MHz
- HP Smart Array P222 and P420 Controller with flash-backed write cache options
- HP FlexibleLOM options—4x1 Gb-E, 2x10 Gb-E, 2x1B and FlexFabric options
- Two PCIe 3.0 slots:
 - x16 (full height, half length)
 - x8 (low profile)
- HP iLO Management Engine (HP iLO 4) with Active Health System, HP power/cooling management, Agentless Management, and Intelligent Provisioning

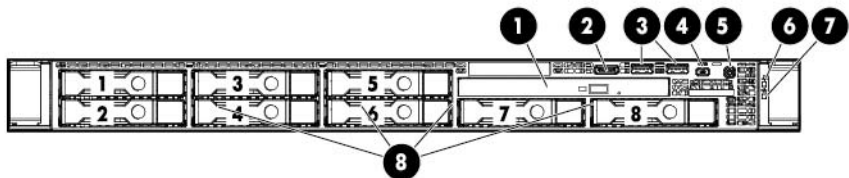
For more information about product features, specifications, options, configurations, and compatibility, see the QuickSpecs on the HP website

(<http://h18000.www1.hp.com/products/quickspecs/ProductBulletin.html>). At the website, choose the geographic region, and then locate the product by name or product category.

Component identification

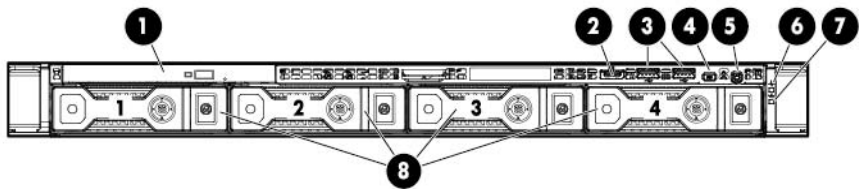
Front panel components

- SFF



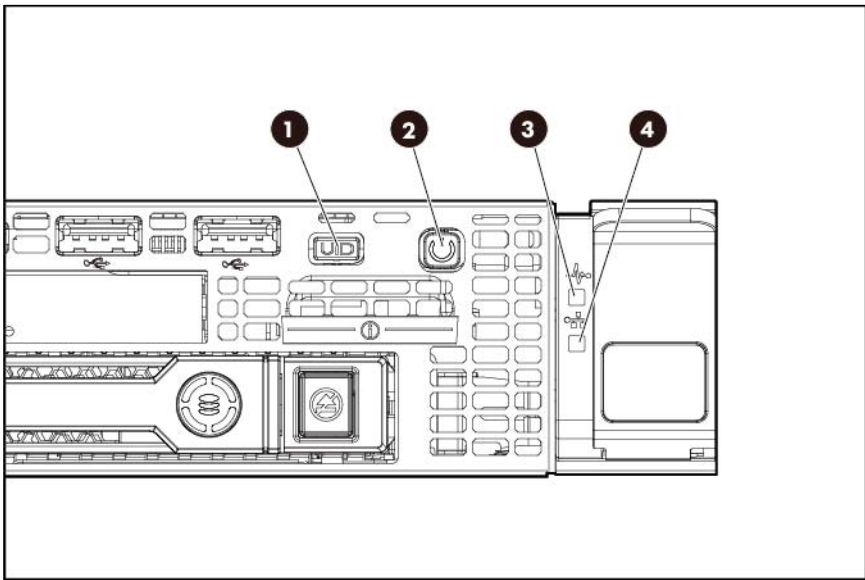
Item	Description
1	Optical drive
2	Front video connector (Front video port adapter required)
3	USB connectors (2)
4	UID LED button
5	Power on/Standby button and system power LED
6	Health LED
7	NIC status LED
8	SAS/SATA drives (8)

- LFF



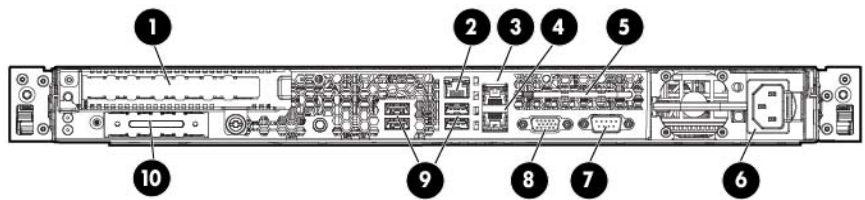
Item	Description
1	Optical drives
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3	USB connectors (2)
4	UID LED button
5	Power on/Standby button and system power LED
6	Health LED
7	NIC status LED
8	SAS/SATA drives (4)

Front panel LEDs and buttons



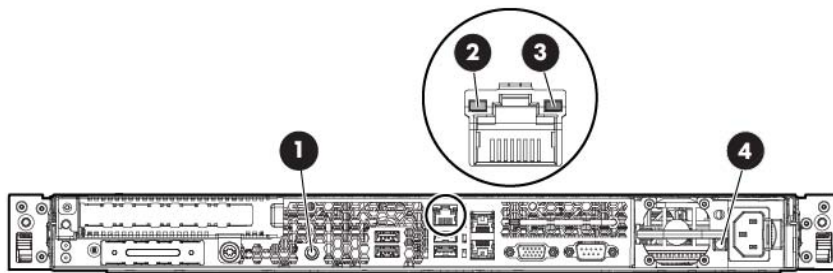
Item	Description	Status
1	UID LED/button	Blue = Identification is activated. Flashing blue = System is being managed remotely. Off = Identification is deactivated.
2	Power On/Standby button	Green = System is on. Flashing green = Waiting for power Amber = System is in standby, but power is still applied. Off = Power cord is not attached, power supply failure has occurred, no power supplies are installed, facility power is not available, or the power button cable is disconnected.
3	Health LED	Green = System health is normal. Flashing amber = System health is degraded. Flashing red = System health is critical. To identify the component in a critical state, check iLO/BIOS logs. Fast flashing red = Power fault (check system and devices)
4	NIC status LED	Green = Network link Flashing green = Network link and activity Off = No link to network

Rear panel components



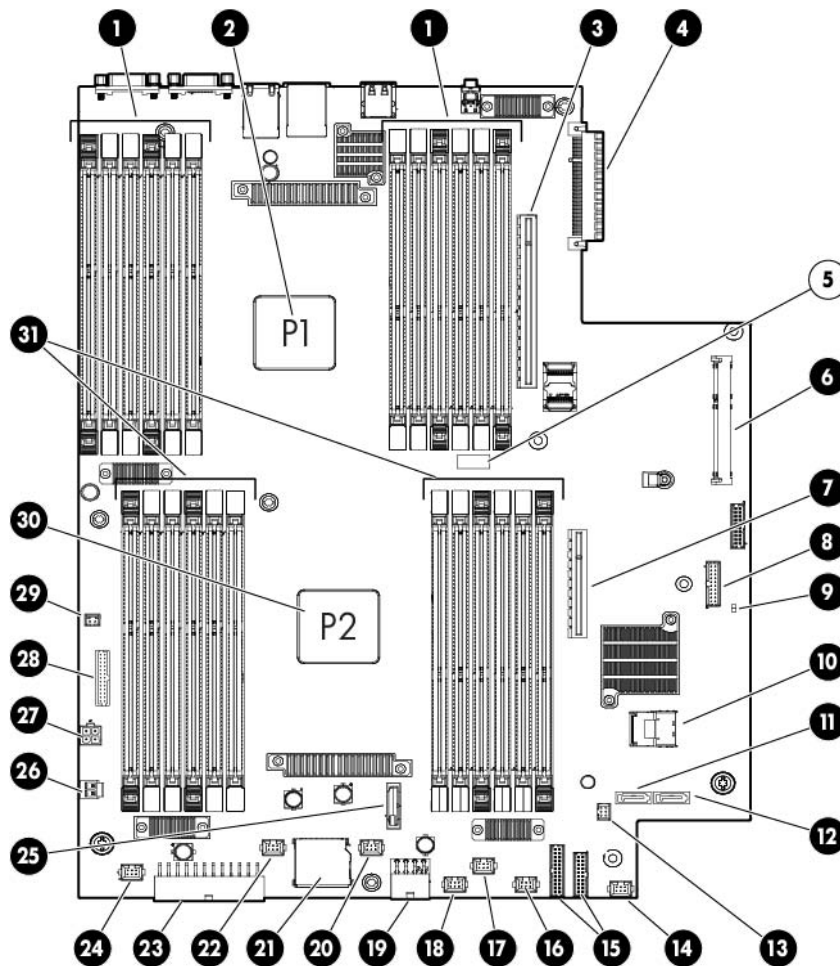
	Description
1	Slot 1 PCIe x16 (8, 4, 2, 1)
2	iLO connector
3	NIC connector 2
4	NIC connector1
5	Torx tool
6	Power supply
7	Serial connector
8	Video connector
9	USB connectors (4)
10	FlexibleLOM slot

Rear panel LEDs and buttons



Item	Description	Status
1	iLO NIC activity LED	Green = Activity exists Flashing green = Activity exists Off = No activity exists
2	iLO NIC link LED	Green = Link exists Off = No link exists
3	UID button/LED	Blue = Identification is activated Flashing blue = System is being managed remotely Off = Identification is deactivated
4	Power supply LED	Green = Normal Off = One or more of the following conditions exists: <ul style="list-style-type: none"> • AC power unavailable • Power supply failed • Power supply in standby mode • Power supply exceeded current limit

System board components

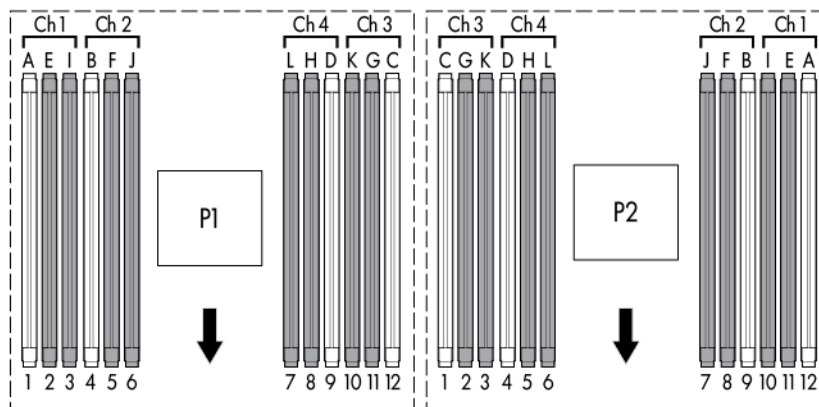


Item	Description
1	Processor 1 DIMM slots
2	Processor socket 1
3	PCI riser connector 1
4	FlexibleLOM connector
5	System maintenance switch
6	Cache module connector
7	PCI riser connector 2
8	TPM connector
9	NMI header
10	Mini-SAS connector
11	SATA connector 2
12	SATA connector 1
13	Internal USB connector
14	Fan connector 8
15	Front panel connectors
16	Fan connector 7
17	Fan connector 6

Item	Description
18	Fan connector 5
19	8-pin power connector
20	Fan connector 4
21	SD card slot
22	Fan connector 3
23	24-pin power connector
24	Fan connector 2
25	System battery
26	FlexibleLOM standby power connector
27	4-pin power connector
28	Redundant power supply connector
29	Discovery service connector
30	Processor socket 2
31	Processor 2 DIMM slots

DIMM slots

DIMM slots are numbered sequentially (1 through 12) for each processor. The supported AMP modes use the letter assignments for population guidelines.



NOTE: For proper orientation, the arrows indicate the front of the server.

System maintenance switch

Position	Default	Function
S1	Off	Off = The iLO security is enabled On = The iLO security is disabled

Position	Default	Function
S2	Off	Off = System configuration can be changed On = System configuration is locked
S3	Off	Reserved
S4	Off	Reserved
S5	Off	Off = Power-on password is enabled On = Power-on password is disabled
S6	Off	Off = No function On = Reset configuration
S7	—	Reserved
S8	—	Reserved
S9	—	Reserved
S10	—	Reserved
S11	—	Reserved
S12	—	Reserved

When the system maintenance switch position 6 is set to the On position, the system is prepared to erase all system configuration settings from both CMOS and NVRAM.

CAUTION: Clearing CMOS and/or NVRAM deletes configuration information. Be sure to properly configure the server or data loss could occur.

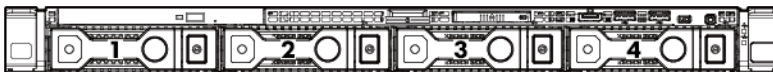
NMI jumper

The NMI jumper allows administrators to perform a memory dump before performing a hard reset. Crash dump analysis is an essential part of eliminating reliability problems, such as hangs or crashes in OSs, device drivers, and applications. Many crashes can freeze a system, requiring you to do a hard reset. Resetting the system erases any information that would support root cause analysis.

Systems running Microsoft® Windows® experience a blue-screen trap when the OS crashes. When this happens, Microsoft® recommends that system administrators perform an NMI event by temporarily shorting the NMI header with a jumper. The NMI event enables a hung system to become responsive again.

Device numbers

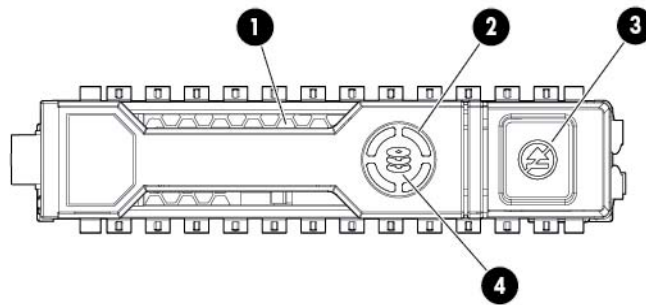
- LFF configuration



- SFF configuration



Drive LED definitions

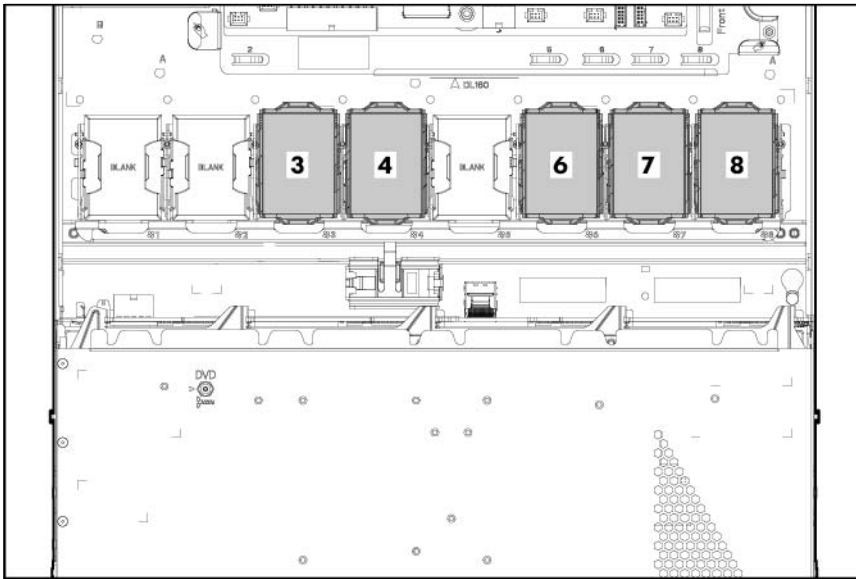


Item	LED	Status	Definition
1	Locate	Solid blue	The drive is being identified by a host application.
		Flashing blue	The drive carrier firmware is being updated or requires an update.
2	Activity ring	Rotating green	Drive activity
		Off	No drive activity
3	Do not remove	Solid white	Do not remove the drive. Removing the drive causes one or more of the logical drives to fail.
		Off	Removing the drive does not cause a logical drive to fail.
4	Drive status	Solid green	The drive is a member of one or more logical drives.
		Flashing green	The drive is rebuilding or performing a RAID migration, stripe size migration, capacity expansion, or logical drive extension, or is erasing.
		Flashing amber/green	The drive is a member of one or more logical drives and predicts the drive will fail.
		Flashing amber	The drive is not configured and predicts the drive will fail.
		Solid amber	The drive has failed.
		Off	The drive is not configured by a RAID controller.

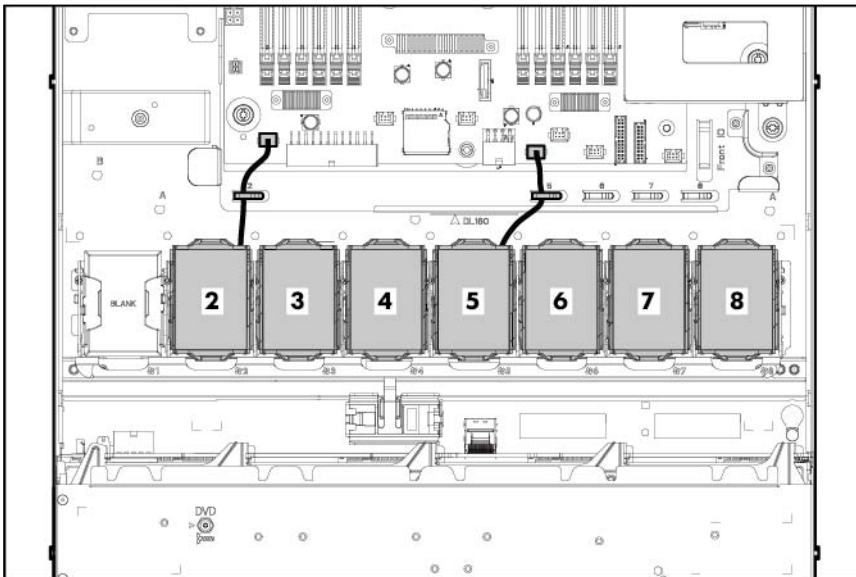
Fan modules

- One-processor configuration

When only one processor is installed, for proper cooling, make sure the fan blanks are installed in fan positions 1, 2, and 5.

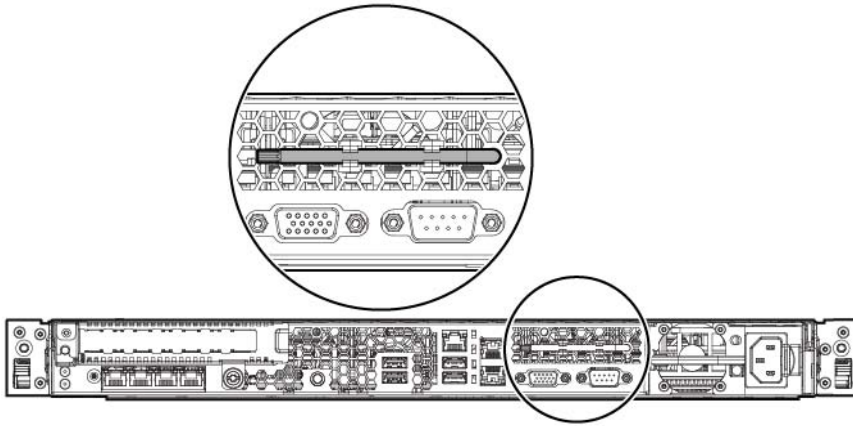


- Two-processor configuration
When processor 2 is installed, install fans in positions 2 and 5.



T-10/T-15 Torx screwdriver

The server ships with a T-10/T-15 Torx screwdriver. Use the screwdriver to loosen screws or thumbscrews, as needed, during procedures.



Operations

Power up the server

To power up the server, press the Power On/Standby button.

Power down the server

Before powering down the server for any upgrade or maintenance procedures, perform a backup of critical server data and programs.



IMPORTANT: When the server is in standby mode, auxiliary power is still being provided to the system.

To power down the server, use one of the following methods:

- Press and release the Power On/Standby button.
This method initiates a controlled shutdown of applications and the OS before the server enters standby mode.
- Press and hold the Power On/Standby button for more than 4 seconds to force the server to enter standby mode.
This method forces the server to enter standby mode without properly exiting applications and the OS. If an application stops responding, you can use this method to force a shutdown.
- Use a virtual power button selection through iLO.
This method initiates a controlled remote shutdown of applications and the OS before the server enters standby mode.

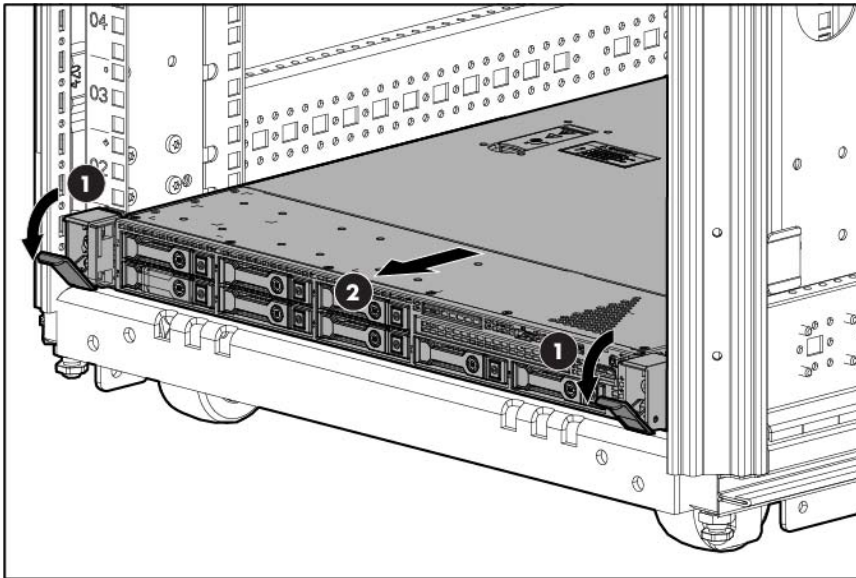
Before proceeding, verify the server is in standby mode by observing that the system power LED is amber.

Extend the server from the rack

1. Pull down the quick release levers on each side of the server.
2. Extend the server from the rack.



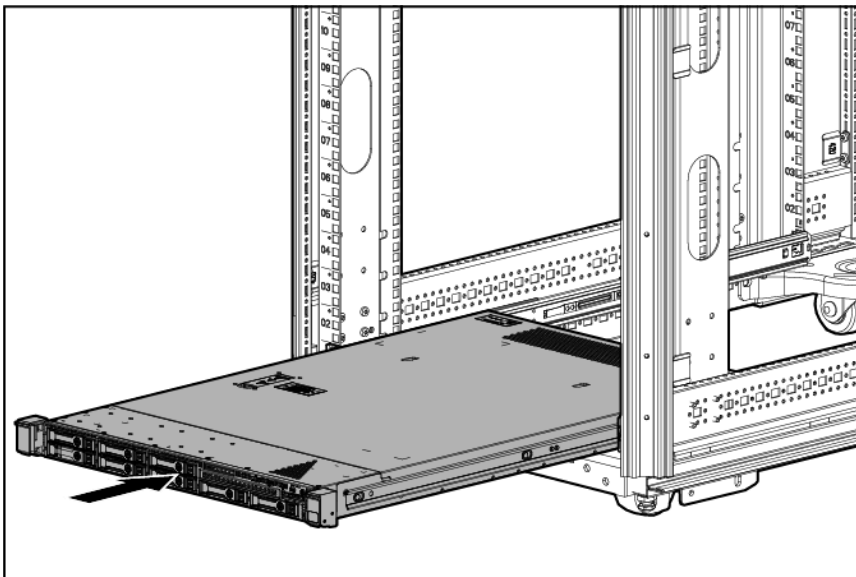
WARNING: To reduce the risk of personal injury or equipment damage, be sure that the rack is adequately stabilized before extending a component from the rack.



3. After performing the installation or maintenance procedure, slide the server back into the rack, and then press the server firmly into the rack to secure it in place.



WARNING: To reduce the risk of personal injury, be careful when pressing the server rail-release latches and sliding the server into the rack. The sliding rails could pinch your fingers.



Remove the server from the rack

To remove the server from an HP, Compaq branded, Telco, or third-party rack:

1. If installed, remove the rack bezel (on page 59).
2. Power down the server (on page 17).
3. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.

4. Extend the server from the rack (on page 17).
5. Release the locking latches.
6. Disconnect the cabling, and then remove the server from the rack. For more information, see the documentation that ships with the rack mounting option.
7. Place the server on a sturdy, level surface.

Remove the access panel



WARNING: To reduce the risk of personal injury from hot surfaces, allow the drives and the internal system components to cool before touching them.



CAUTION: Do not operate the server for long periods with the access panel open or removed. Operating the server in this manner results in improper airflow and improper cooling that can lead to thermal damage.

To remove the component:

1. If installed, remove the rack bezel (on page 59).
2. Power down the server (on page 17).
3. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
4. Extend the server from the rack (on page 17).
5. Open the locking latch, slide the access panel to the rear of the chassis, and remove the access panel. If the locking latch is locked use a T-15 Torx screwdriver to unlock the latch.

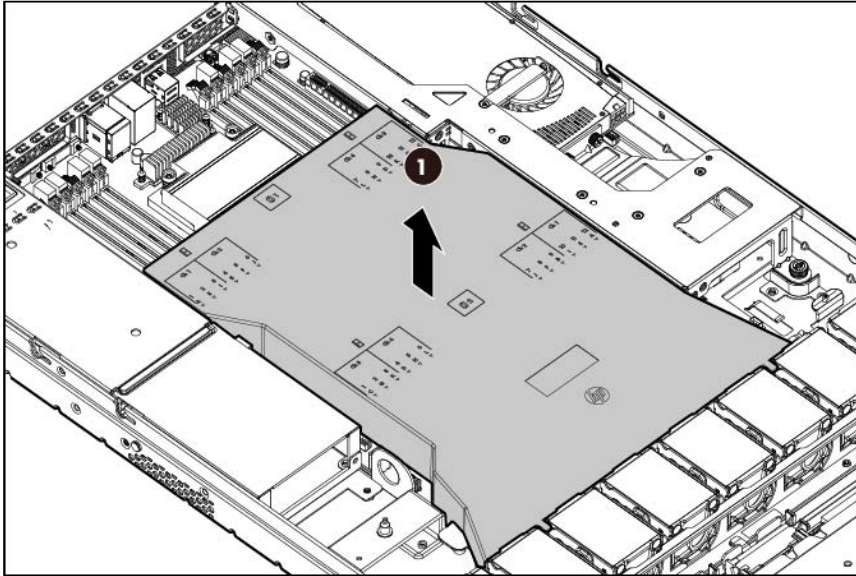
Install the access panel

1. Place the access panel on top of the server with the hood latch open. Allow the panel to extend past the rear of the server approximately 1.25 cm (0.5 in).
2. Push down on the hood latch. The access panel slides to a closed position.
3. Use the T-15 Torx screwdriver provided with the server to tighten the security screw on the hood latch.

Remove the processor air baffle

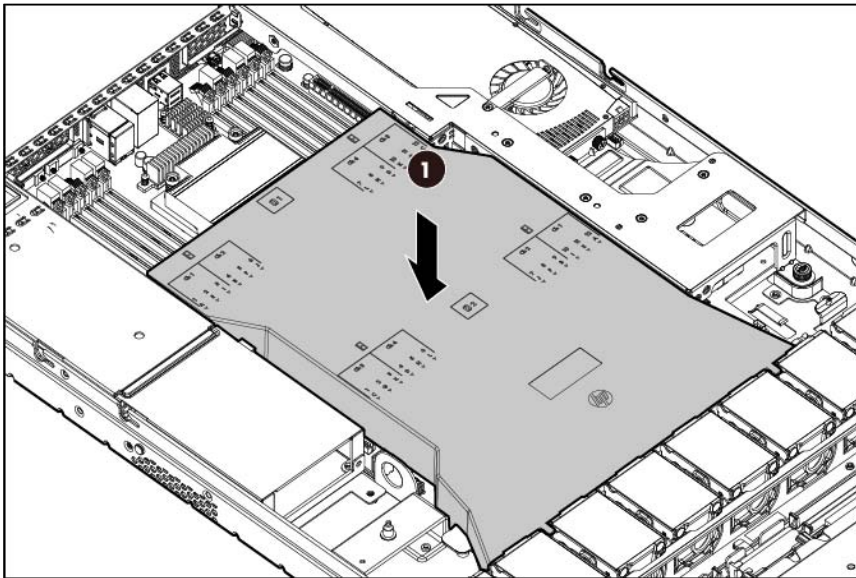
1. If installed, remove the rack bezel (on page 59).
2. Power down the server (on page 17).
3. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
4. Extend the server from the rack (on page 17).
5. Remove the access panel (on page 19).

6. Remove the processor air baffle.



Install the processor air baffle

1. Place the air baffle on top of the server.
2. Push down the air baffle.
The air baffle slides down to a closed position.



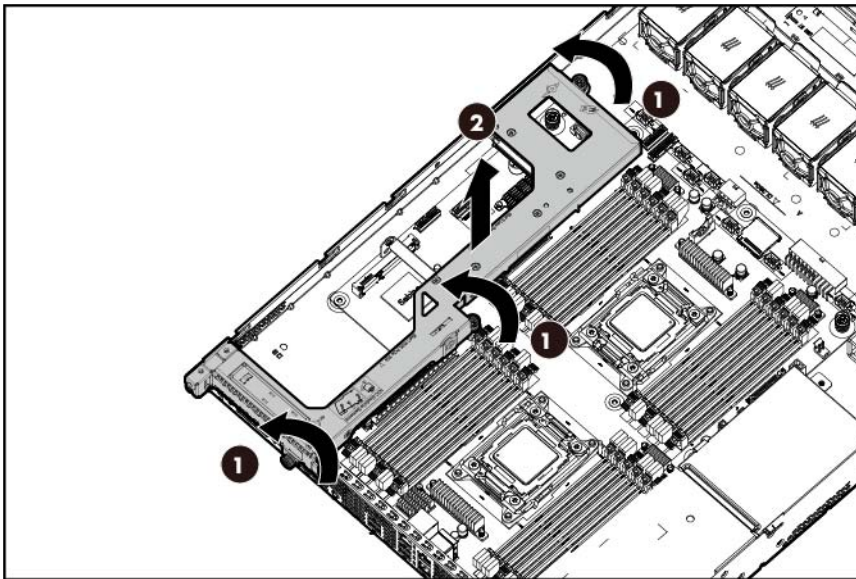
Remove the PCI riser cage



CAUTION: To prevent damage to the server or expansion boards, power down the server and remove all AC power cords before removing or installing the PCI riser board assembly.

1. If installed, remove the rack bezel (on page 59).

2. Power down the server (on page 17).
3. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
4. Extend the server from the rack (on page 17).
5. Remove the access panel (on page 19).
6. Remove the processor air baffle (on page 19).
7. Disconnect external cables connected to any existing expansion boards.
8. Remove the PCI riser cage:
 - a. Unfasten the three screws in the PCI riser cage.
 - b. To unseat the PCI riser boards, lift the assembly, and then remove the cage.



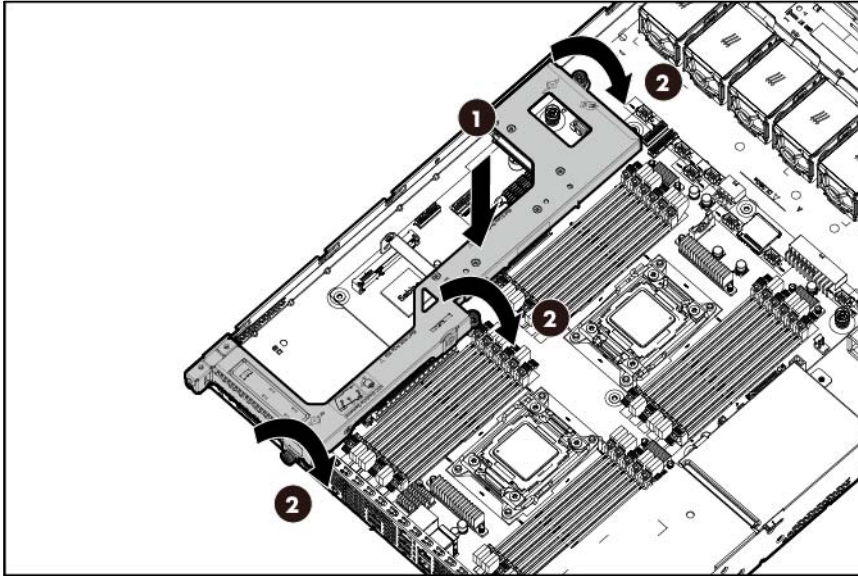
Install the PCI riser cage



CAUTION: To prevent damage to the server or expansion boards, power down the server and remove all AC power cords before removing or installing the PCI riser cage.

1. Align the PCI riser boards with the corresponding connectors on the system board, and then insert the cage.

2. Insert and then tighten the three screws of the PCI cage.



3. Install the processor air baffle.
4. Install the access panel (on page 19).
5. Slide the server into the rack.
6. Connect each power cord to the server.
7. Connect each power cord to the power source.
8. Power up the server (on page 17).

Setup

Optional installation services

Delivered by experienced, certified engineers, HP Care Pack services help you keep your servers up and running with support packages tailored specifically for HP ProLiant systems. HP Care Packs let you integrate both hardware and software support into a single package. A number of service level options are available to meet your needs.

HP Care Pack Services offer upgraded service levels to expand your standard product warranty with easy-to-buy, easy-to-use support packages that help you make the most of your server investments. Some of the Care Pack services are:

- Hardware support
 - 6-Hour Call-to-Repair
 - 4-Hour 24x7 Same Day
 - 4-Hour Same Business Day
- Software support
 - Microsoft®
 - Linux
 - HP ProLiant Essentials (HP SIM and RDP)
 - VMWare
- Integrated hardware and software support
 - Critical Service
 - Proactive 24
 - Support Plus
 - Support Plus 24
- Startup and implementation services for both hardware and software

For more information on HP Care Pack Services, see the HP website (<http://www.hp.com/services/carepack>).

Rack planning resources

The rack resource kit ships with all HP branded or Compaq branded 9000, 10000, and H9 series racks. For more information on the content of each resource, see the rack resource kit documentation.

Optimum environment

When installing the server in a rack, select a location that meets the environmental standards described in this section.

Space and airflow requirements

To allow for servicing and adequate airflow, observe the following space and airflow requirements when deciding where to install a rack:

- Leave a minimum clearance of 63.5 cm (25 in) in front of the rack.
- Leave a minimum clearance of 76.2 cm (30 in) behind the rack.
- Leave a minimum clearance of 121.9 cm (48 in) from the back of the rack to the back of another rack or row of racks.

HP servers draw in cool air through the front and expel warm air through the rear. Therefore, the front and rear rack doors must be adequately ventilated to allow ambient room air to enter the cabinet, and the rear door must be adequately ventilated to allow the warm air to escape from the cabinet.



CAUTION: To prevent improper cooling and damage to the equipment, do not block the ventilation openings.

When vertical space in the rack is not filled by a server or rack component, the gaps between the components cause changes in airflow through the rack and across the servers. Cover all gaps with blanking panels to maintain proper airflow.



CAUTION: Always use blanking panels to fill empty vertical spaces in the rack. This arrangement ensures proper airflow. Using a rack without blanking panels results in improper cooling that can lead to thermal damage.

The 9000 and 10000 Series Racks provide proper server cooling from flow-through perforations in the front and rear doors that provide 64 percent open area for ventilation.



CAUTION: When using a Compaq branded 7000 series rack, install the high airflow rack door insert (PN 327281-B21 for 42U rack, PN 157847-B21 for 22U rack) to provide proper front-to-back airflow and cooling.



CAUTION: If a third-party rack is used, observe the following additional requirements to ensure adequate airflow and to prevent damage to the equipment:

- Front and rear doors—If the 42U rack includes closing front and rear doors, you must allow 5,350 sq cm (830 sq in) of holes evenly distributed from top to bottom to permit adequate airflow (equivalent to the required 64 percent open area for ventilation).
- Side—The clearance between the installed rack component and the side panels of the rack must be a minimum of 7 cm (2.75 in).

Temperature requirements

To ensure continued safe and reliable equipment operation, install or position the system in a well-ventilated, climate-controlled environment.

The maximum recommended ambient operating temperature (TMRA) for most server products is 35°C (95°F). The temperature in the room where the rack is located must not exceed 35°C (95°F).



CAUTION: To reduce the risk of damage to the equipment when installing third-party options:

- Do not permit optional equipment to impede airflow around the server or to increase the internal rack temperature beyond the maximum allowable limits.
- Do not exceed the manufacturer's TMRA.

Power requirements

Installation of this equipment must comply with local and regional electrical regulations governing the installation of information technology equipment by licensed electricians. This equipment is designed to operate in installations covered by NFPA 70, 1999 Edition (National Electric Code) and NFPA-75, 1992 (code for Protection of Electronic Computer/Data Processing Equipment). For electrical power ratings on options, refer to the product rating label or the user documentation supplied with that option.



WARNING: To reduce the risk of personal injury, fire, or damage to the equipment, do not overload the AC supply branch circuit that provides power to the rack. Consult the electrical authority having jurisdiction over wiring and installation requirements of your facility.



CAUTION: Protect the server from power fluctuations and temporary interruptions with a regulating uninterruptible power supply (UPS). This device protects the hardware from damage caused by power surges and voltage spikes and keeps the system in operation during a power failure.

When installing more than one server, you might have to use additional power distribution devices to safely provide power to all devices. Observe the following guidelines:

- Balance the server power load between available AC supply branch circuits.
- Do not allow the overall system AC current load to exceed 80% of the branch circuit AC current rating.
- Do not use common power outlet strips for this equipment.
- Provide a separate electrical circuit for the server.

Electrical grounding requirements

The server must be grounded properly for proper operation and safety. In the United States, you must install the equipment in accordance with NFPA 70, 1999 Edition (National Electric Code), Article 250, as well as any local and regional building codes. In Canada, you must install the equipment in accordance with Canadian Standards Association, CSA C22.1, Canadian Electrical Code. In all other countries, you must install the equipment in accordance with any regional or national electrical wiring codes, such as the International Electrotechnical Commission (IEC) Code 364, parts 1 through 7. Furthermore, you must be sure that all power distribution devices used in the installation, such as branch wiring and receptacles, are listed or certified grounding-type devices.

Because of the high ground-leakage currents associated with multiple servers connected to the same power source, HP recommends the use of a PDU that is either permanently wired to the building's branch circuit or includes a nondetachable cord that is wired to an industrial-style plug. NEMA locking-style plugs or those complying with IEC 60309 are considered suitable for this purpose. Using common power outlet strips for the server is not recommended.

Rack warnings



WARNING: To reduce the risk of personal injury or damage to the equipment, be sure that:

- The leveling jacks are extended to the floor.
 - The full weight of the rack rests on the leveling jacks.
 - The stabilizing feet are attached to the rack if it is a single-rack installation.
 - The racks are coupled together in multiple-rack installations.
 - Only one component is extended at a time. A rack may become unstable if more than one component is extended for any reason.
-



WARNING: To reduce the risk of personal injury or equipment damage when unloading a rack:

- At least two people are needed to safely unload the rack from the pallet. An empty 42U rack can weigh as much as 115 kg (253 lb), can stand more than 2.1 m (7 ft) tall, and might become unstable when being moved on its casters.
 - Never stand in front of the rack when it is rolling down the ramp from the pallet. Always handle the rack from both sides.
-

Contents of the server shipping carton

Unpack the server shipping carton and locate the materials and documentation necessary for installing the server. All the rack mounting hardware necessary for installing the server into the rack is included with the rack or the server.

The contents of the server shipping carton include:

- Server
- Power cord
- Printed setup documentation, Documentation CD, and software products
- Rack mounting hardware kit and documentation

In addition to these supplied items, you might need:

- T-10/T-15 Torx screwdriver
- Hardware options
- Operating system or application software

Installing hardware options

Install any hardware options before initializing the server. For options installation information, refer to the option documentation. For server-specific information, refer to "Hardware options installation (on page 29)."

Installing the server into the rack

To install the server do the following:

To install the server into a rack with square, round, or threaded holes, refer to the instructions that ship with the rack hardware kit.

If you are installing the server into a telco rack, order the appropriate option kit at the RackSolutions.com website (<http://www.racksolutions.com/hp>). Follow the server-specific instructions on the website to install the rack brackets.

Use the following information when connecting peripheral cables and power cords to the server.



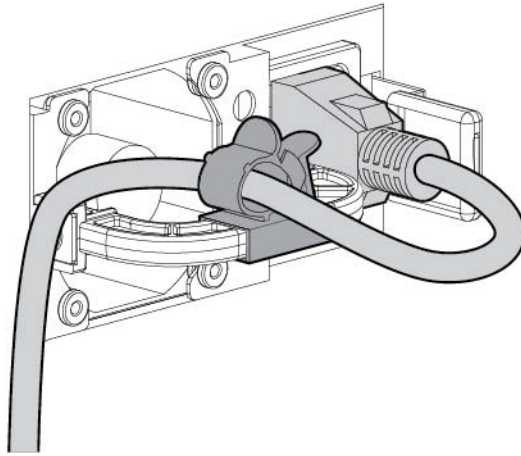
WARNING: This server is very heavy. To reduce the risk of personal injury or damage to the equipment:

- Observe local occupational health and safety requirements and guidelines for manual material handling.
- Get help to lift and stabilize the product during installation or removal, especially when the product is not fastened to the rails. When the server weighs more than 22.5 kg (50 lb), at least two people must lift the server into the rack together. A third person may be required to help align the server if the server is installed higher than chest level.
- Use caution when installing the server in or removing the server from the rack; it is unstable when not fastened to the rails.



CAUTION: Always plan the rack installation so that the heaviest item is on the bottom of the rack. Install the heaviest item first, and continue to populate the rack from the bottom to the top.

1. Install the server and cable management arm into the rack. See the installation instructions that ship with the Quick Deploy Rail System.
2. Connect peripheral devices to the server.
3. Connect the power cord to the server.
4. Using the strain relief clip from the server hardware kit, secure the power cord.



5. Connect the power cord to the power source.
6. Power up the server. ("[Power up the server](#)" on page 17)

Powering up and configuring the server

To power up the server, press the Power On/Standby button.

While the server boots, RBSU and the ORCA utility are automatically configured to prepare the server for operating system installation.

To configure these utilities manually:

- Press the **F8** key when prompted during the array controller initialization to configure the array controller using ORCA.
- Press the **F9** key when prompted during the boot process to change the server settings using RBSU. The system is set up by default for the English language.

For more information on the automatic configuration, refer to the *HP ROM-Based Setup Utility User Guide* located on the Documentation CD.

Installing the operating system

This ProLiant server does not ship with provisioning media. Everything needed to manage and install the system software and firmware is preloaded on the server.

To operate properly, the server must have a supported operating system. For the latest information on operating system support, see the HP website (<http://www.hp.com/go/supportos>).

To install an operating system on the server, use one of the following methods:

- **Intelligent Provisioning**—The iLO Management Engine is a new feature on ProLiant servers that contains Intelligent Provisioning for embedded deployment, updating, and provisioning capabilities. Intelligent Provisioning can configure the server and install an operating system, eliminating the need for SmartStart CDs and Smart Update Firmware DVDs.

To install an operating system on the server with Intelligent Provisioning (local or remote):

- a. Connect the Ethernet cable, and then power on the server.
 - b. During server POST, press the **F10** key.
 - c. Complete the initial Preferences and Registration portion of Intelligent Provisioning (on page 73).
 - d. At the 1 Start screen, click the **Configure and Install** button.
 - e. To finish the installation, follow the on-screen prompts. An Internet connection is required to update the firmware and systems software.
- **Remote deployment installation**—To remotely deploy an operating system, use Insight Control server deployment for an automated solution.

For additional system software and firmware updates, download the HP Service Pack for ProLiant from the HP website (<http://www.hp.com/go/spp/download>). Software and firmware must be updated before using the server for the first time, unless any installed software or components require an older version. For more information, see Keeping the system current (on page 81).

The Smart Update Firmware DVD ISO is also available at the download tab on the HP website (<http://www.hp.com/go/foundation>).

For more information on using these installation methods, see the HP website (<http://www.hp.com/go/ilo>).

Registering the server

To register the server, refer to the HP Registration website (<http://register.hp.com>).

Hardware options installation

Introduction

If more than one option is being installed, read the installation instructions for all the hardware options and identify similar steps to streamline the installation process.



WARNING: To reduce the risk of personal injury from hot surfaces, allow the drives and the internal system components to cool before touching them.



CAUTION: To prevent damage to electrical components, properly ground the server before beginning any installation procedure. Improper grounding can cause electrostatic discharge.

Processor and fan module option

When one processor is installed, install fan blanks in slots 2 and 5. When two processors are installed, install fans in these slots.

The server supports single processor and dual-processor operation.



CAUTION: To avoid damage to the processor and system board, only authorized personnel should attempt to replace or install the processor in this server.



CAUTION: To prevent possible server malfunction and damage to the equipment, multiprocessor configurations must contain processors with the same part number.



IMPORTANT: If installing a processor with a faster speed, update the system ROM before installing the processor.

NOTE: To prevent the processor bent pins from bending, do not reset, swap, or exchange the processor.

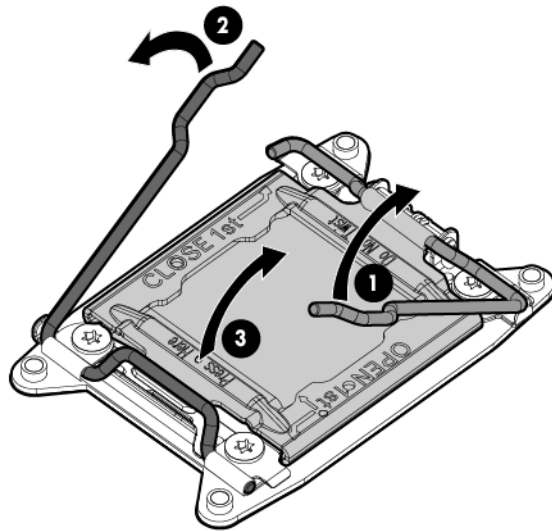
To install a processor:

1. If installed, remove the rack bezel (on page 59).
2. Power down the server (on page 17).
3. Remove the server from the rack (on page 18).
4. Remove the access panel (on page 19).
5. Remove the processor air baffle. ("[Remove the processor air baffle](#)" on page 19)

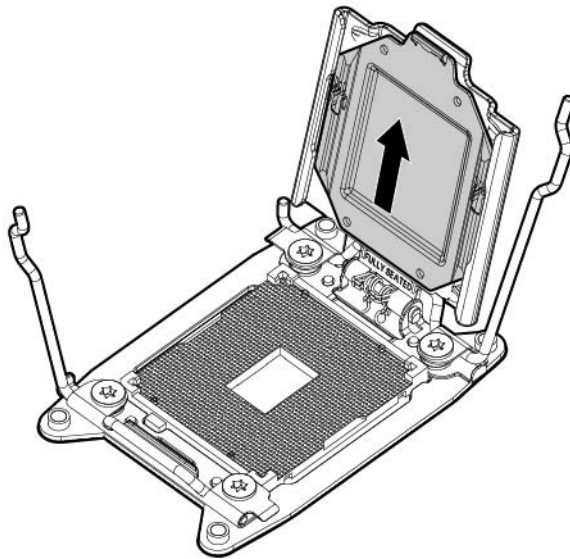


CAUTION: The pins on the processor socket are very fragile. Any damage to them may require replacing the system board.

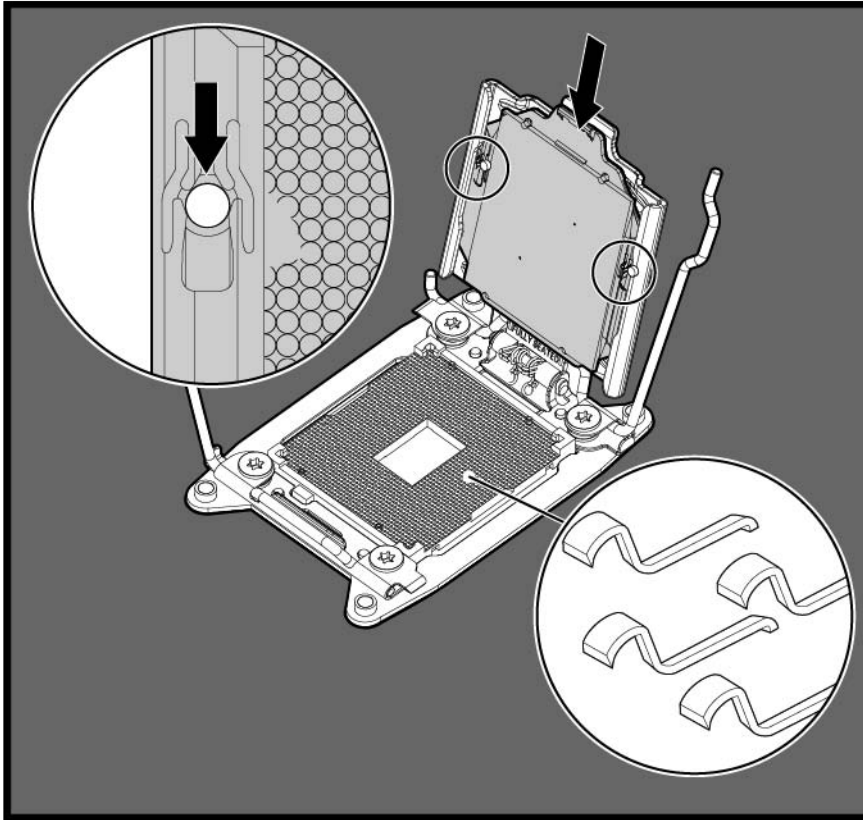
6. Open each of the processor locking levers in the order indicated, and then open the processor retaining bracket.



7. Remove the clear processor socket cover. Retain the processor socket cover for future use.



8. Install the processor. Verify that the processor is fully seated in the processor retaining bracket by visually inspecting the processor installation guides on either side of the processor. **THE PINS ON THE SYSTEM BOARD ARE VERY FRAGILE AND EASILY DAMAGED.**



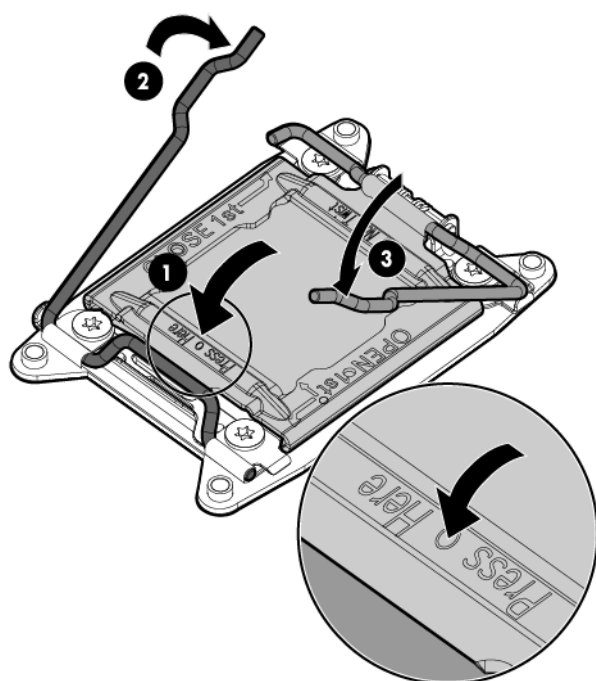
CAUTION: THE PINS ON THE SYSTEM BOARD ARE VERY FRAGILE AND EASILY DAMAGED. To avoid damage to the system board, do not touch the processor or the processor socket contacts.

9. Close the processor retaining bracket. When the processor is installed properly inside the processor retaining bracket, the processor retaining bracket clears the flange on the front of the socket.

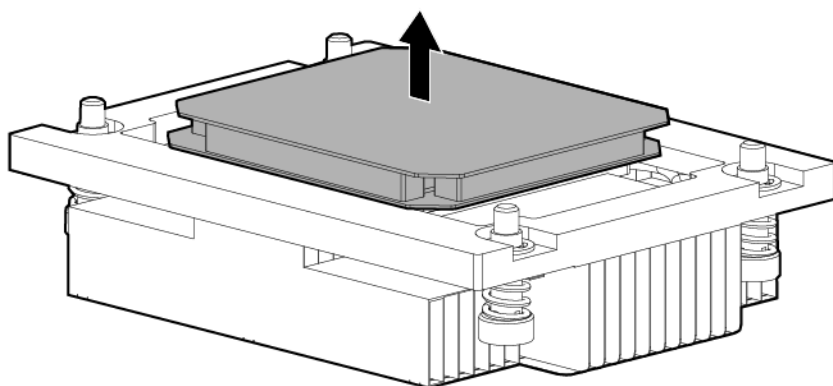


CAUTION: Do not press down on the processor. Pressing down on the processor may cause damage to the processor socket and the system board. Press only in the area indicated on the processor retaining bracket.

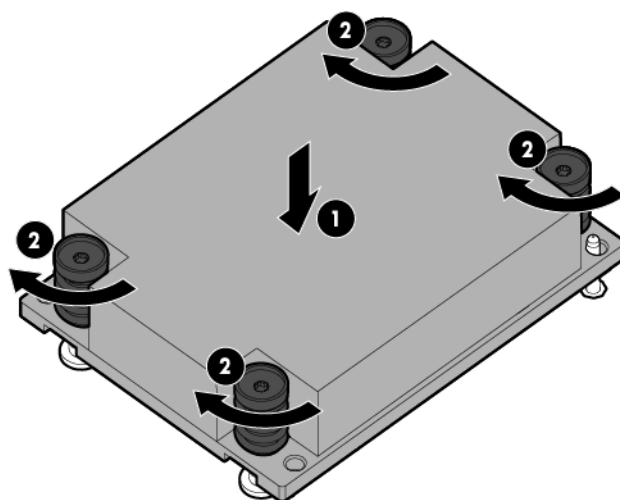
10. Press and hold the processor retaining bracket in place, and then close each processor locking lever. Press only in the area indicated on the processor retaining bracket.



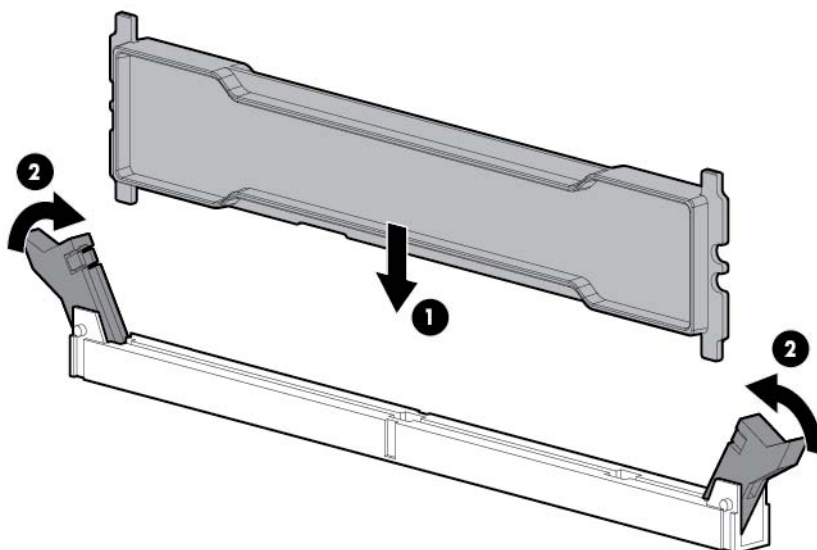
11. Remove the thermal interface protective cover from the heatsink.



12. Remove the adhesive tape from the slot, and then install the heatsink.

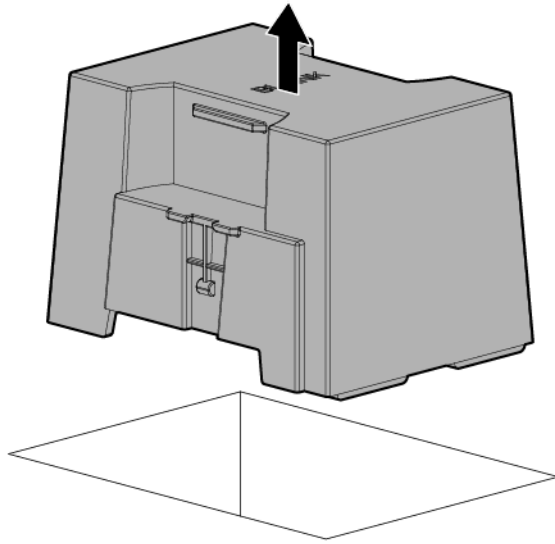


13. Install DIMM blanks in all empty DIMM slots next to the installed processor.

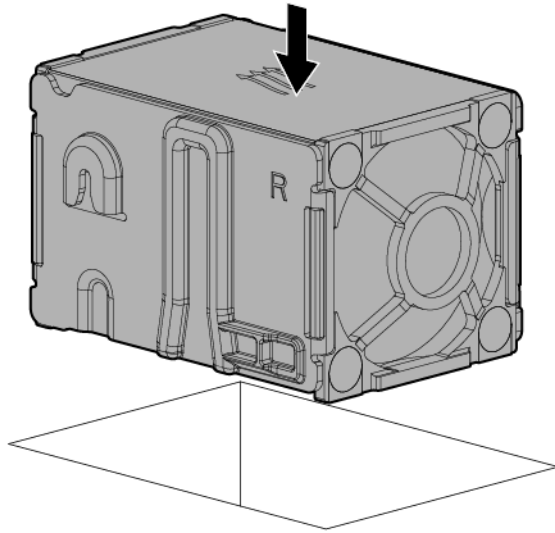


14. Locate fan slots 2 and 5.
15. Remove the fan blank from slots 2 and 5.

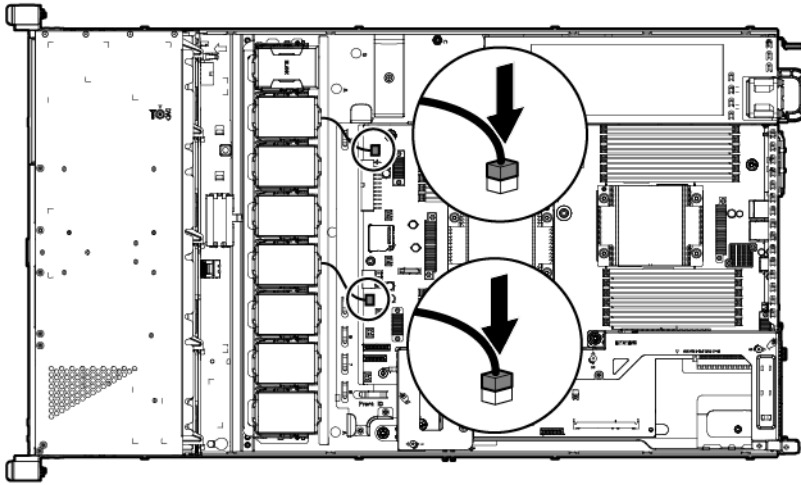
NOTE: Dual-processor configurations require seven fans.



16. Install the fans in slots 2 and 5.



17. Connect the fans to the system board connector.



18. Install the processor air baffle (on page 20).
19. Install the access panel (on page 19).
20. Slide the server into the rack.
21. Connect each power cord to the server.
22. Connect each power cord to the power source.
23. Power up the server (on page 17).
24. If removed, install the rack bezel (on page 60).

Memory options



IMPORTANT: This server does not support mixing RDIMMs or UDIMMs. Attempting to mix any combination of these DIMMs can cause the server to halt during BIOS initialization.

The memory subsystem in this server can support RDIMMs or UDIMMs. The two types are referred to as DIMMs when the information applies to the two types. When specified as RDIMM or UDIMM, the information applies to that type only. All memory installed in the server must be the same type.

The server supports the following DIMM speeds:

- Single-rank PC3-12800 (DDR-1600) DIMMs operating at 1600, 1333, and 1066 MHz
- Single-rank and dual-rank PC3-10600 (DDR-1333) DIMMs operating at 1333 and 1066 MHz

For more information on the effect of DIMM slot population, see "General DIMM slot population guidelines (on page 40)."

HP SmartMemory

HP SmartMemory, introduced for Gen8 servers, authenticates and unlocks certain features available only on HP Qualified memory and verifies whether installed memory has passed HP qualification and test processes. Qualified memory is performance-tuned for HP ProLiant and BladeSystem servers and provides future enhanced support through HP Active Health and manageability software.

Certain performance features are unique with HP SmartMemory. HP SmartMemory 1.35V DDR3-1333 Registered memory is engineered to achieve the same performance level as 1.5V memory. For example, while the industry supports DDR3-1333 RDIMM at 1.5V, this Gen8 server supports DDR3-1333 RDIMM up to 3 DIMMs per channel at 1066 MT/s running at 1.35V. This equates to up to 20% less power at the DIMM level with no performance penalty. In addition, the industry supports UDIMM at 2 DIMMs per channel at 1066 MT/s. HP SmartMemory supports 2 DIMMs per channel at 1333 MT/s, or 25% greater bandwidth.

Memory subsystem architecture

The memory subsystem in this server is divided into channels. Each processor supports four channels, and each channel supports three DIMM slots, as shown in the following table.

- Processor 1

Channel	Population order	Slot number
1	A	1
	E	2
	I	3
2	B	4
	F	5
	J	6
3	C	12
	G	11
	K	10
4	D	9
	H	8
	L	7

- Processor 2

Channel	Population order	Slot number
3	C	1
	G	2
	K	3
4	D	4
	H	5
	L	6
1	A	12
	E	11
	I	10
2	B	9
	F	8
	J	7

For the location of the slot numbers, see "DIMM slots (on page 12)."

This multi-channel architecture provides enhanced performance in Advanced ECC mode. This architecture also enables Lockstep and Online Spare Memory modes. This server supports RDIMMs and UDIMMs.

DIMM slots in this server are identified by number and by letter. Letters identify the population order. Slot numbers indicate the DIMM slot ID for spare replacement.

Single- and dual-rank DIMMs

DIMM configuration requirements are based on these classifications:

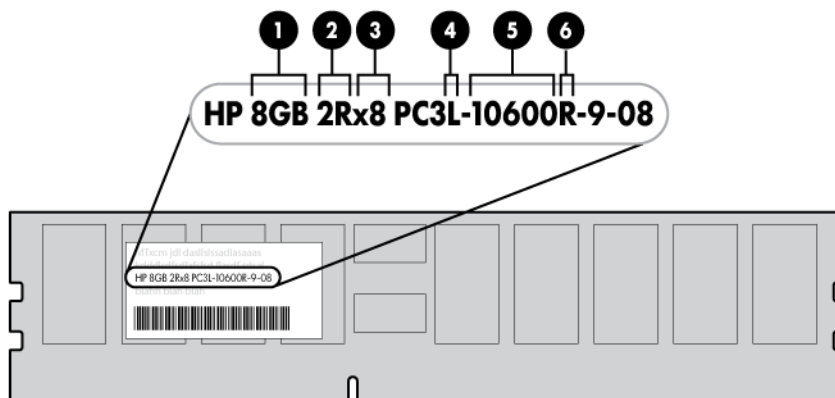
- Single-rank DIMM—One set of memory chips that is accessed while writing to or reading from the memory.
- Dual-rank DIMM—Two single-rank DIMMs on the same module, with only one rank accessible at a time.

The server memory control subsystem selects the proper rank within the DIMM when writing to or reading from the DIMM.

Dual-rank DIMMs provide the greatest capacity with the existing memory technology. For example, if current DRAM technology supports 2-GB single-rank DIMMs, a dual-rank DIMM would be 4-GB.

DIMM identification

To determine DIMM characteristics, use the label attached to the DIMM and the following illustration and table.



Item	Description	Definition
1	Size	—
2	Rank	1R = Single-rank 2R = Dual-rank 4R = Quad-rank
3	Data width	x4 = 4-bit x8 = 8-bit
4	Voltage rating	L = Low voltage (1.35v) U = Ultra low voltage (1.25v) Blank or omitted = Standard
5	Memory speed	12800 = 1600-MT/s 10600 = 1333-MT/s 8500 = 1066-MT/s
6	DIMM type	R = RDIMM (registered) E = UDIMM (unbuffered with ECC) L = LRDIMM (load reduced)

For the latest supported memory information, see the QuickSpecs on the HP website (<http://h18000.www1.hp.com/products/quickspecs/ProductBulletin.html>). At the website, choose the geographic region, and then locate the product by name or product category.

Memory configurations

To optimize server availability, the server supports the following AMP modes:

- **Advanced ECC**—Provides up to 4-bit error correction and enhanced performance over Lockstep mode. This mode is the default option for this server.
- **Lockstep**—Provides enhanced protection over Advanced ECC mode while continuing to make all installed memory available to the operating system. The server can continue to function if a single- or multi-bit memory failure within a single DRAM device occurs.
- **Online spare memory**—Provides protection against failing or degraded DIMMs. Certain memory is reserved as spare, and automatic failover to spare memory occurs when the system detects a DIMM that is degrading. This feature enables DIMMs that have a higher probability of receiving an uncorrectable memory error (which results in system downtime) to be removed from operation.

Advanced Memory Protection options are configured in RBSU. If the requested AMP mode is not supported by the installed DIMM configuration, the server boots in Advanced ECC mode. For more information, see "HP ROM-Based Setup Utility (on page 76)."

The server also can operate in Independent Channel Mode or Combined Channel Mode (Lockstep). Lockstep provides enhanced protection over Advanced ECC mode while continuing to make all installed memory available to the operating system. The server can continue to function if a single-bit or multi-bit memory failure within a single DRAM device occurs.

For the latest memory configuration information, see the QuickSpecs on the HP website (<http://www.hp.com>).

Intel Gen8 supported memory bandwidth

The following tables show the supported memory for each DIMM type.

Speed, voltage, and capacity

DIMM type	DIMM rank	DIMM capacity	Native speed (MT/s)	Voltage
RDIMM	Single-rank	4GB	1333	LV
RDIMM	Single-rank	4GB	1600	STD
RDIMM	Dual-rank	8GB	1333	LV
RDIMM	Single-rank	8GB	1600	STD
RDIMM	Dual-rank	16GB	1333	LV
UDIMM	Single-rank	2GB	1333	LV
UDIMM	Dual-rank	4Gb	1333	LV
UDIMM	Dual-rank	8Gb	1333	LV

Slot population

DIMM type	DIMM rank	16 slots (for max speed)	24 slots (for max capacity)
RDIMM	Single-rank	16	24

DIMM type	DIMM rank	16 slots (for max speed)	24 slots (for max capacity)
RDIMM	Single-rank	16	24
RDIMM	Dual-rank	16	24
RDIMM	Single-rank	16	24
RDIMM	Dual-rank	16	24
UDIMM	Single-rank	16	16
UDIMM	Dual-rank	16	16
UDIMM	Dual-rank	16	16

Maximum speed and capacity (GB)*

DIMM type	DIMM rank	16 slots (speed)	24 slots (capacity)
RDIMM	Single-rank	64	96
RDIMM	Single-rank	64	96
RDIMM	Dual-rank	128	192
RDIMM	Single-rank	128	192
RDIMM	Dual-rank	256	384
UDIMM	Single-rank	32	32
UDIMM	Dual-rank	64	64
UDIMM	Dual-rank	128	128

* Maximum capacity varies based on individual server platform qualification schedule

Populated DIMM speed (MT/s)

DIMM type	DIMM rank	1 DIMM per channel	2 DIMMs per channel	3 DIMMs per channel
RDIMM	Single-rank	1333	1333	1066*
RDIMM	Single-rank	1600	1600	1066
RDIMM	Dual-rank	1333	1333	1066*
RDIMM	Single-rank	1600	1600	1066
RDIMM	Dual-rank	1333	1333	1066*
UDIMM	Single-rank	1333	1333†	—
UDIMM	Dual-rank	1333	1333†	—
UDIMM	Dual-rank	1333	1333†	—

* RDIMM supports 1.35V 3DPC at 1066. Third-party memory supports 1.5V 3DPC at 1066.

† UDIMM is supported at 2DPC at 1333 using HP SmartMemory only. Third-party memory supports up to 2DPC at 1066.

RDIMM maximum memory configurations

The following table lists the maximum memory configurations possible with 8- or 16-GB RDIMMs.

Rank	Single-processor	Dual-processor
Single-rank	96 GB	192 GB
Dual-rank	192 GB	384 GB

UDIMM maximum memory configurations

The server supports a maximum of 64 GB with one processor and 128 GB with two processors using 8-GB dual-rank UDIMMs.

Advanced ECC memory configuration

Advanced ECC memory is the default memory protection mode for this server. Standard ECC can correct single-bit memory errors and detect multi-bit memory errors. When multi-bit errors are detected using Standard ECC, the error is signaled to the server and causes the server to halt.

Advanced ECC protects the server against some multi-bit memory errors. Advanced ECC can correct both single-bit memory errors and 4-bit memory errors if all failed bits are on the same DRAM device on the DIMM.

Advanced ECC provides additional protection over Standard ECC because it is possible to correct certain memory errors that would otherwise be uncorrected and result in a server failure. Using HP Advanced Memory Error Detection technology, the server provides notification when a DIMM is degrading and has a higher probability of uncorrectable memory error.

Lockstep memory configuration

Lockstep mode provides protection against multi-bit memory errors that occur on the same DRAM device. Lockstep mode can correct any single DRAM device failure on x4 and x8 DIMM types. The DIMMs in each channel must have identical HP part numbers.

Lockstep mode uses channel 1 and channel 2. Channel 3 is not populated. Because channel 3 cannot be populated when using Lockstep mode, the maximum memory capacity is lower than Advanced ECC mode. Memory performance with Advanced ECC is also slightly higher.

Online Spare memory configuration

Online spare memory provides protection against degraded DIMMs by reducing the likelihood of uncorrected memory errors. This protection is available without any operating system support.

Online spare memory protection dedicates one rank of each memory channel for use as spare memory. The remaining ranks are available for OS and application use. If correctable memory errors occur at a rate higher than a specific threshold on any of the non-spare ranks, the server automatically copies the memory contents of the degraded rank to the online spare rank. The server then deactivates the failing rank and automatically switches over to the online spare rank.

General DIMM slot population guidelines

Observe the following guidelines for all AMP modes:

- Install DIMMs only if the corresponding processor is installed.
- When two processors are installed, balance the DIMMs across the two processors.
- White DIMM slots denote the first slot of a channel (Ch 1-A, Ch 2-B, Ch 3-C, Ch 4-D).
- Do not mix UDIMMs or RDIMMs.
- Do not install more than two UDIMMs per channel. Do not install UDIMMs in slots Ch 1-I, Ch 2-J, Ch 3-K, or Ch 4-L.
- When two processors are installed, install the DIMMs in sequential alphabetical order balanced between the two processors: P1-A, P2-A, P1-B, P2-B, P1-C, P2-C, and so on.

For detailed memory configuration rules and guidelines, use the Online DDR3 Memory Configuration Tool on the HP website (<http://www.hp.com/go/ddr3memory-configurator>).

DIMM speeds are supported as indicated in the following table.

Populated slots (per channel)	Rank	Speeds supported (MT/s)
1	Single- or dual-rank	1333, 1600
2	Single- or dual-rank	1333
3	Single- or dual-rank	1066

Advanced ECC population guidelines

For Advanced ECC mode configurations, observe the following guidelines:

- Observe the general DIMM slot population guidelines (on page 40).
- DIMMs may be installed individually.

Single-processor Advanced ECC population order

For Advanced ECC mode configurations with a single processor, populate the DIMM slots in the following order:

- RDIMM: Sequentially in alphabetical order (A through L)
- UDIMM: A through H, sequentially in alphabetical order. Do not populate DIMM slots I through L.

Multi-processor Advanced ECC population order

For Advanced ECC mode configurations with multiple processors, populate the DIMM slots for each processor in the following order:

- RDIMM: Sequentially in alphabetical order (A through L)
- UDIMM: A through H, sequentially in alphabetical order. Do not populate DIMM slots I through L.

Lockstep Memory population guidelines

For Lockstep memory mode configurations, observe the following guidelines:

- Observe the general DIMM slot population guidelines (on page 40).
- Always install DIMMs in channels 1 and 2 for each installed processor.
- Do not install DIMMs in channel 3 for any processor.
- DIMM configuration on channel 1 and channel 2 of a processor must be identical.
- In multi-processor configurations, each processor must have a valid Lockstep Memory configuration.
- In multi-processor configurations, each processor may have a different valid Lockstep Memory configuration.

Population order

For memory configurations with a single processor or multiple processors, populate the DIMM slots in the following order:

- RDIMM: Sequentially in alphabetical order (A through L)

- UDIMM: A through H, sequentially in alphabetical order. Do not populate DIMM slots I through L.
- After installing the DIMMs, use RBSU to configure Advanced ECC, online spare, or lockstep memory support.

Multi-processor Lockstep population order

For Lockstep memory mode configurations with multiple processors, populate the DIMM slots for each processor in the following order:

- RDIMM
 - First: A, B, C, and D
 - Next: E, F, G, and H
 - Last: I, J, K, and L
- UDIMM
 - First: A, B, C, and D
 - Last: E, F, G, and H
 - Do not populate slots I, J, K, or L.

After installing the DIMMs, use RBSU to configure the system for Lockstep memory support.

Online Spare population guidelines

For Online Spare mode configurations, observe the following guidelines:

- Observe the general DIMM slot population guidelines (on page 40).
- DIMM configuration on each channel of a processor must be identical.
- Each processor must have a valid Online Spare configuration.
- In multi-processor configurations, each processor can have a different valid Online Spare configuration.

Single-processor Online Spare population order

For Online Spare memory mode configurations with a single processor, observe the following guidelines:

- Observe the general DIMM slot population guidelines.
- Each channel must have a valid online spare configuration.
- Each channel can have a different valid online spare configuration.
- Each populated channel must have a spare rank.
- A single dual-rank DIMM is not a valid configuration.

After installing the DIMMs, use RBSU to configure the system for Online Spare memory support.

Multi-processor Online Spare population order

For Online Spare mode configurations with multiple processors, observe the following guidelines:

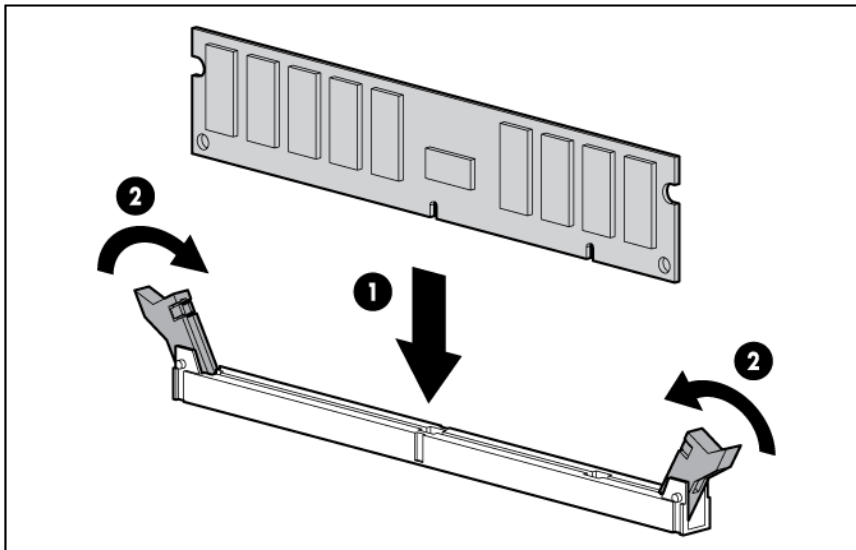
- Observe the general DIMM slot population guidelines.
- Each channel must have a valid online spare configuration.

- Each channel can have a different valid online spare configuration.
- Each populated channel must have a spare rank.
- A single dual-rank DIMM is not a valid configuration

After installing the DIMMs, use RBSU to configure the system for Online Spare memory support.

Installing a DIMM

1. If installed, remove the rack bezel (on page 59).
2. Power down the server (on page 17).
3. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
4. Extend the server from the rack (on page 17).
5. Remove the access panel (on page 19).
6. Remove the processor air baffle (on page 19).
7. Open the DIMM slot latches.
8. Install the DIMM.



9. Install the processor air baffle (on page 20).
10. Install the access panel (on page 19).
11. Slide the server into the rack.
12. Connect each power cord to the server.
13. Connect each power cord to the power source.
14. Power up the server (on page 17).
15. If removed, install the rack bezel (on page 60).

If you are installing DIMMs in online spare or lock-step configuration, configure this mode in RBSU ("[HP ROM-Based Setup Utility](#)" on page 76).

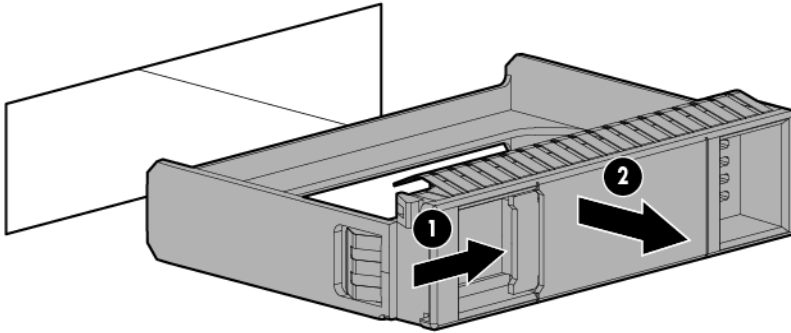
Hot-plug drive guidelines

When adding drives to the server, observe the following general guidelines:

- The system automatically sets all device numbers.
- If only one drive is used, install it in the bay with the lowest device number.
- Drives should be the same capacity to provide the greatest storage space efficiency when drives are grouped together into the same drive array.

Removing the drive blank

Remove the component as indicated.

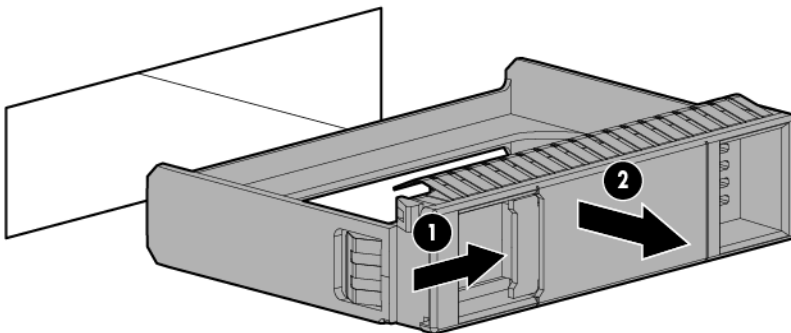


Installing a hot-plug drive

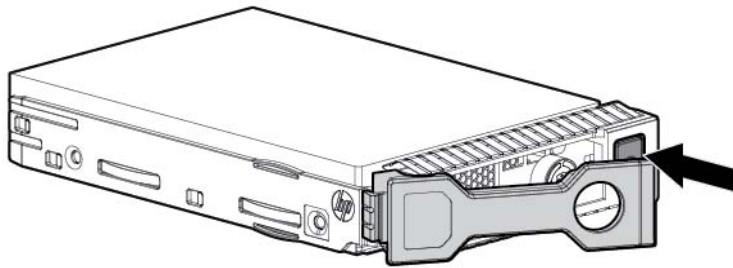
The server can support four drives in a LFF configuration and up to eight drives in a SFF configuration.

To install the component:

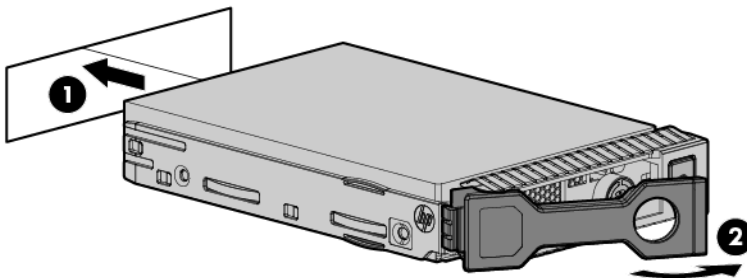
1. Remove the drive blank.



2. Prepare the drive.



3. Install the drive.



4. Determine the status of the drive from the drive LED definitions (on page 14).

DVD-ROM and DVD-RW drive option

This server supports the installation of a SATA DVD-ROM optical drive or a SATA DVD-RW optical drive.

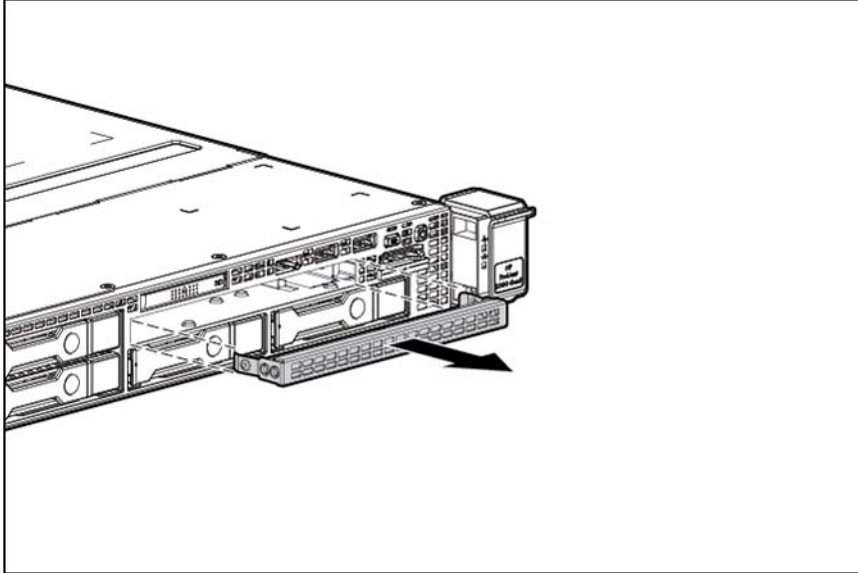
To install the component:

1. If installed, remove the rack bezel (on page 59).
2. Power down the server (on page 17).
3. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
4. Extend the server from the rack (on page 17).
5. Remove the access panel (on page 19).
6. Remove the processor air baffle (on page 19).
7. Remove the PCI riser cage (on page 20).

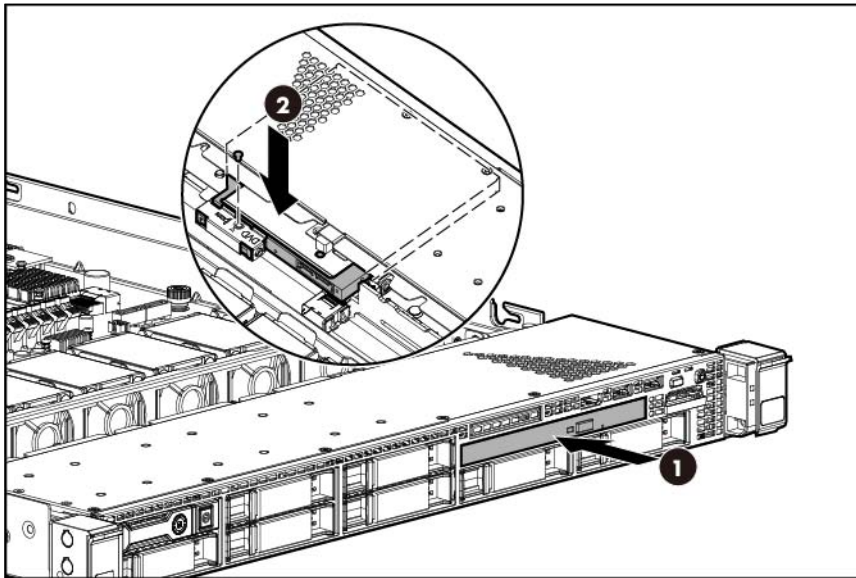


WARNING: To reduce the risk of personal injury from hot surfaces, allow the drives and the internal system components to cool before touching them.

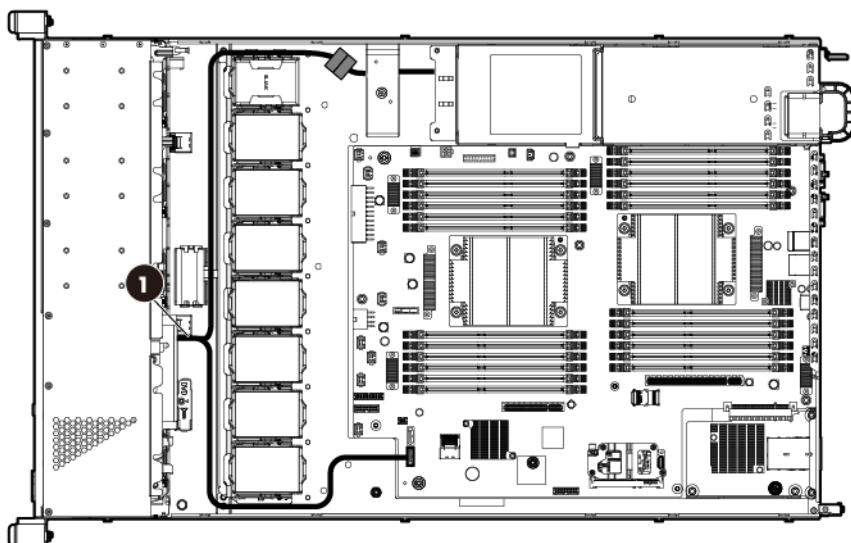
8. Remove the bezel blank from the DVD-ROM bay.



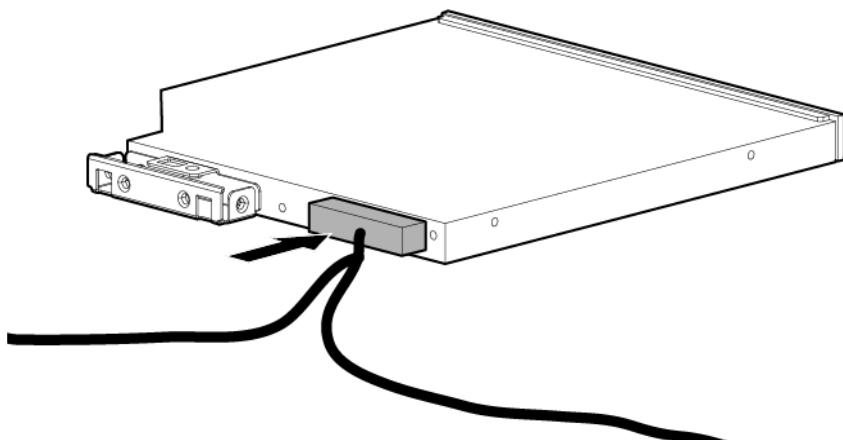
9. If you have a SFF configuration, install the DVD drive using the screws from this kit and the T-10/T-15 Torx screwdriver provided with the server.



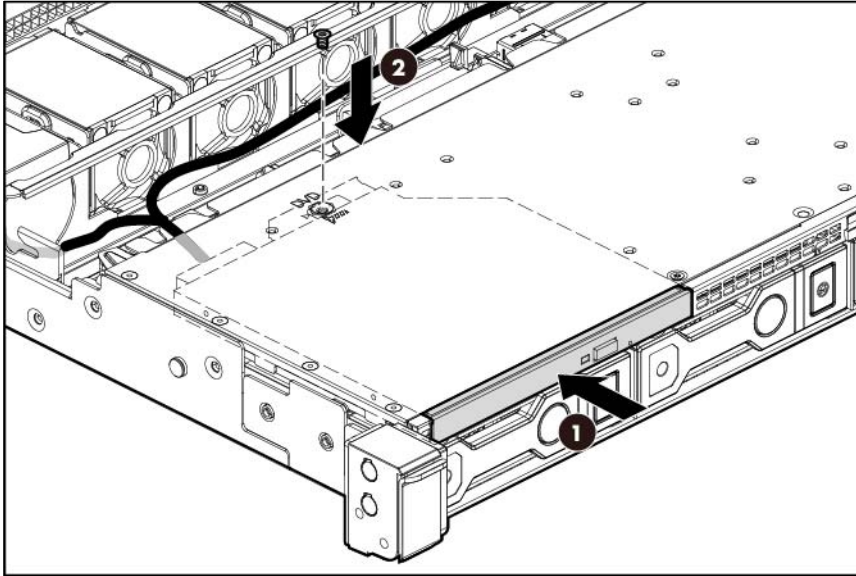
10. Connect the cable from the rear of the drive to the SATA DVD-ROM drive connector on the system board.



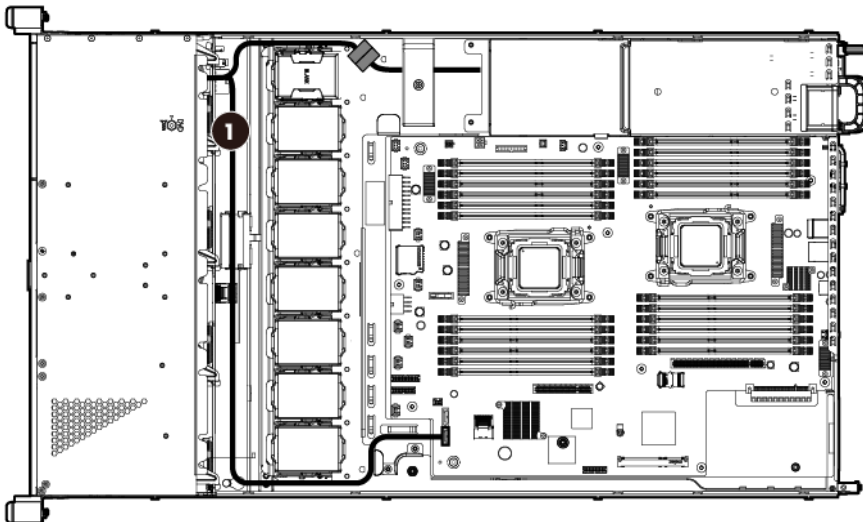
11. If you have a LFF configuration, route the cable through the drive bay, and then connect the cable to the rear of the optical drive.



12. Install the drive into the drive bay.



13. Connect the cable from the rear of the drive to the SATA DVD-ROM drive connector on the system board.





14. Install the PCI riser cage. ("[Install the PCI riser cage](#)" on page 21)
15. Install the processor air baffle.
16. Install the access panel (on page 19).
17. Slide the server into the rack.
18. Connect each power cord to the server.
19. Connect each power cord to the power source.
20. Power up the server (on page 17).
21. If removed, install the rack bezel (on page 60).


Controller options

The server ships with an embedded SATA controller. For more information about the controller and its features, see the *HP Smart Array Controllers for HP ProLiant Servers User Guide* on the HP website (<http://bizsupport2.austin.hp.com/bc/docs/support/SupportManual/c01608507/c01608507.pdf>). To configure arrays, see the *Configuring Arrays on HP Smart Array Controllers Reference Guide* on the HP website (<http://bizsupport1.austin.hp.com/bc/docs/support/SupportManual/c00729544/c00729544.pdf>).

The server supports Smart Array controllers P420/1 GB FBWC, P420/2 GB FBWC, and P222/512 MB FBWC. FBWC upgrade options are also available. FBWC consists of a cache module and a capacitor pack. The DDR cache module buffers and stores data being written by the controller. When the system is powered on, the capacitor pack charges fully in about 5 minutes. In the event of a system power failure, a fully charged capacitor pack provides power for up to 80 seconds. During that interval, the controller transfers the cached data from DDR memory to flash memory, where the data remains indefinitely or until a controller retrieves the data.


-
-  **CAUTION:** The cache module connector does not use the industry standard DDR3 mini DIMM pinout. Do not use this controller with cache modules designed for other controller models, because the controller can malfunction and you can lose data. Also, do not transfer this cache module to an unsupported controller model, because you can lose data.
-
-  **CAUTION:** After the server is powered down, wait 15 seconds and then check the amber LED before unplugging the cable from the cache module. If the amber LED blinks after 15 seconds, do not remove the cable from the cache module. The cache module is backing up data, and data is lost if the cable is detached.
-

FBWC option

-
-  **CAUTION:** The cache module connector does not use the industry standard DDR3 mini DIMM pinout. Do not use this controller with cache modules designed for other controller models, because the controller can malfunction and you can lose data. Also, do not transfer this cache module to an unsupported controller model, because you can lose data.
-

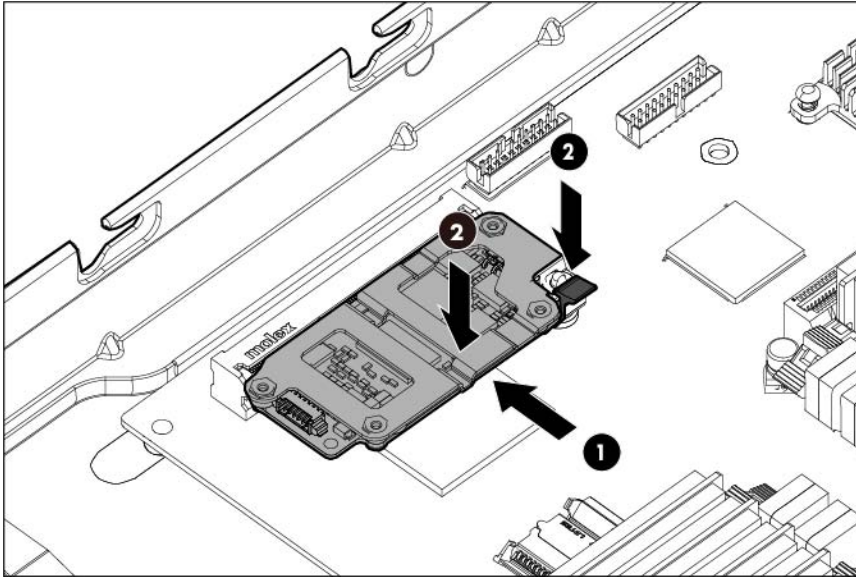
To install the component:

1. Back up all data.
2. Close all applications.

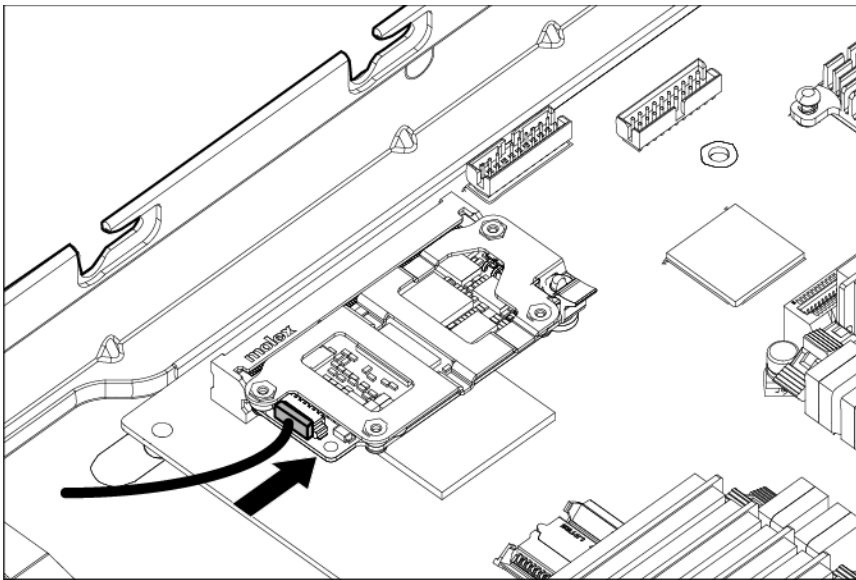
-
-  **CAUTION:** In systems that use external data storage, be sure that the server is the first unit to be powered down and the last to be powered back up. Taking this precaution ensures that the system does not erroneously mark the drives as failed when the server is powered up.
-

3. If installed, remove the rack bezel (on page 59).
4. Power down the server (on page 17).
5. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
6. Extend the server from the rack (on page 17).
7. Remove the access panel (on page 19).

8. Remove the processor air baffle (on page 19).
9. Remove the PCI riser cage. ("Remove the PCI riser cage" on page 20)
10. Install the cache module.



11. Connect the capacitor pack cable to the connector on the top of the cache module.



12. Install the PCI riser cage (on page 21).
13. Install the processor air baffle (on page 20).
14. Install the access panel (on page 19).
15. Slide the server into the rack.
16. Connect each power cord to the server.
17. Connect each power cord to the power source.
18. Power up the server (on page 17).
19. If removed, install the rack bezel (on page 60).

FBWC capacitor pack

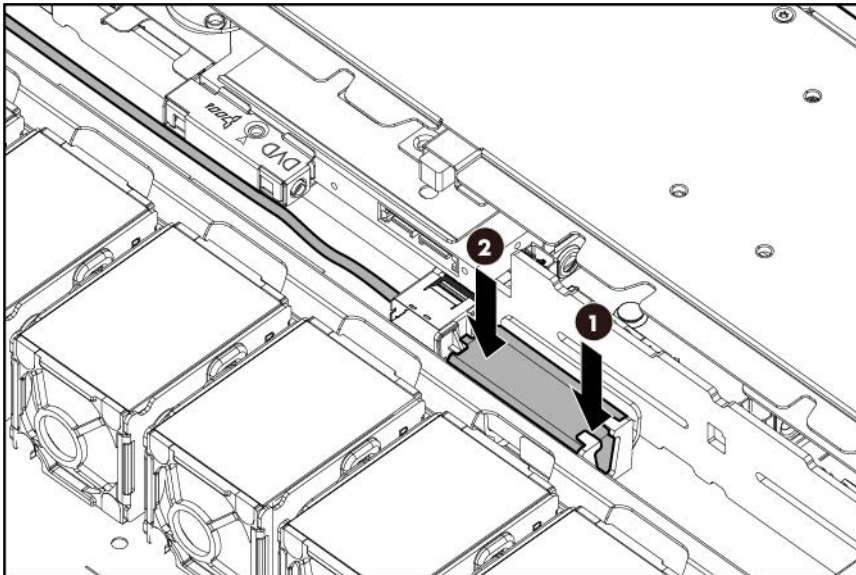
To install the component:

- △ **CAUTION:** The cache module connector does not use the industry standard DDR3 mini DIMM pinout. Do not use this controller with cache modules designed for other controller models, because the controller can malfunction and you can lose data. Also, do not transfer this cache module to an unsupported controller model, because you can lose data.

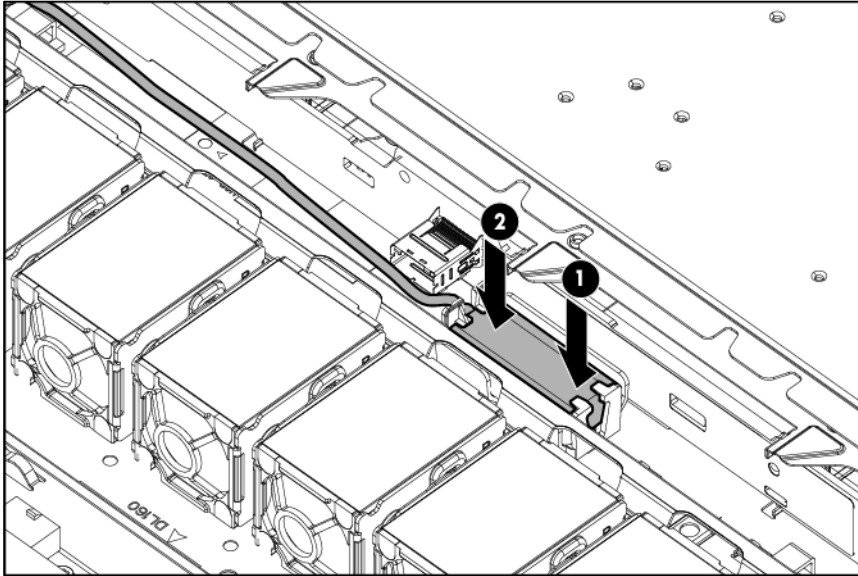
1. Back up all data.
2. Close all applications.
3. If installed, remove the rack bezel (on page 59).
4. Power down the server (on page 17).

- △ **CAUTION:** In systems that use external data storage, be sure that the server is the first unit to be powered down and the last to be powered back up. Taking this precaution ensures that the system does not erroneously mark the drives as failed when the server is powered up.

5. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
6. Extend the server from the rack (on page 17).
7. Remove the access panel (on page 19).
8. Remove the processor air baffle (on page 19).
9. Remove the PCI riser cage (on page 20).
10. Install the FBWC capacitor pack into the FBWC module.
11. Install the FBWC module into the server.
 - Eight-drive SFF

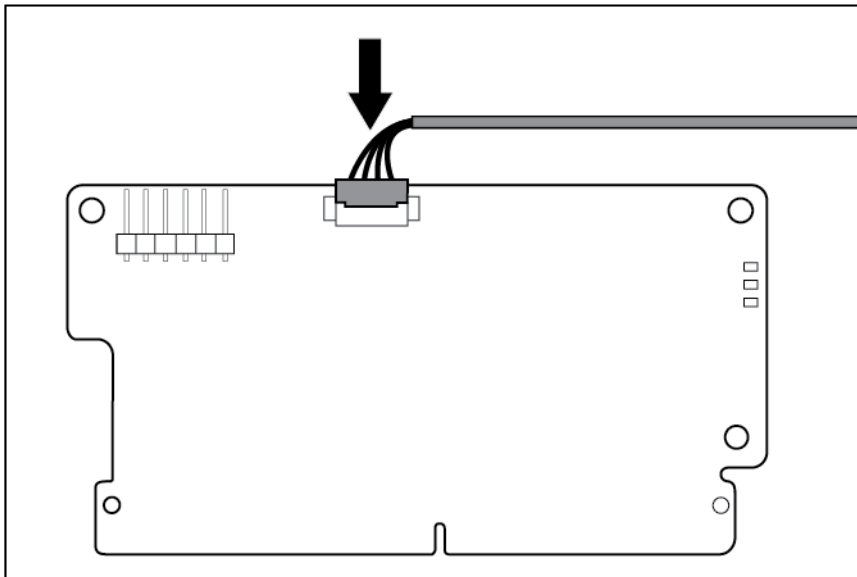


- Four-drive LFF

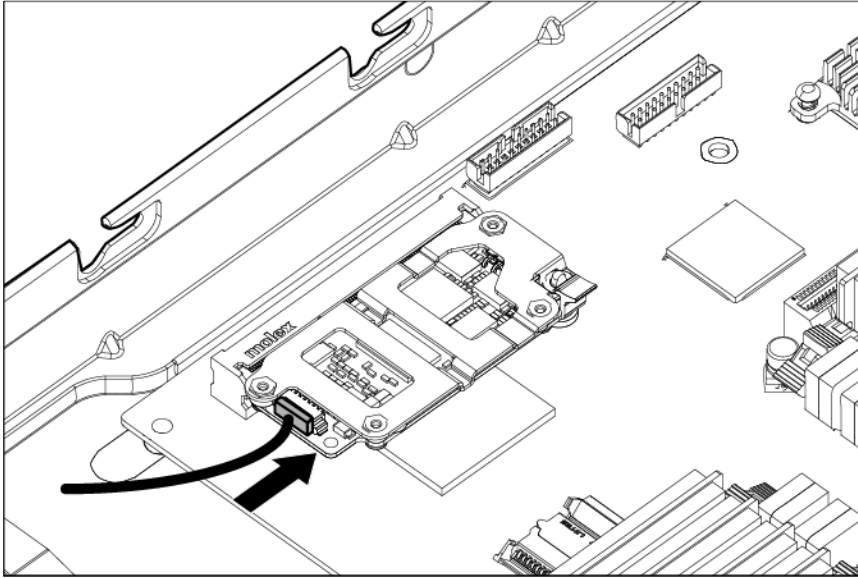


12. Connect the capacitor pack cable to the connector on top of the cache module in one of the following configurations:

- Expansion board



- FBWC cache module



13. Install the PCI riser cage (on page 21).
14. Install the processor air baffle. ("[Install the processor air baffle](#)" on page 20)
15. Install the access panel. ("[Install the access panel](#)" on page 19)
16. Slide the server into the rack.
17. Connect each power cord to the server.
18. Connect each power cord to the power source.
19. Power up the server. ("[Power up the server](#)" on page 17)
20. If removed, install the rack bezel (on page 60).

Installing the front video adapter cable

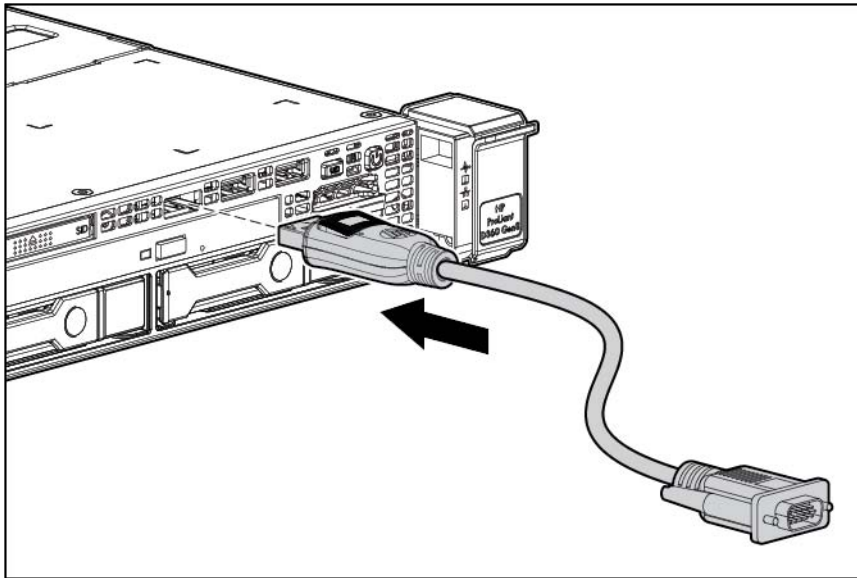
Depending on the model purchased, the server may look different than shown.

To install the component:

1. Connect the front video adapter to the front video connector.



CAUTION: Be sure to connect the video adapter to the video connector, and not to the USB connector.



2. Connect the front video adapter to the video device.

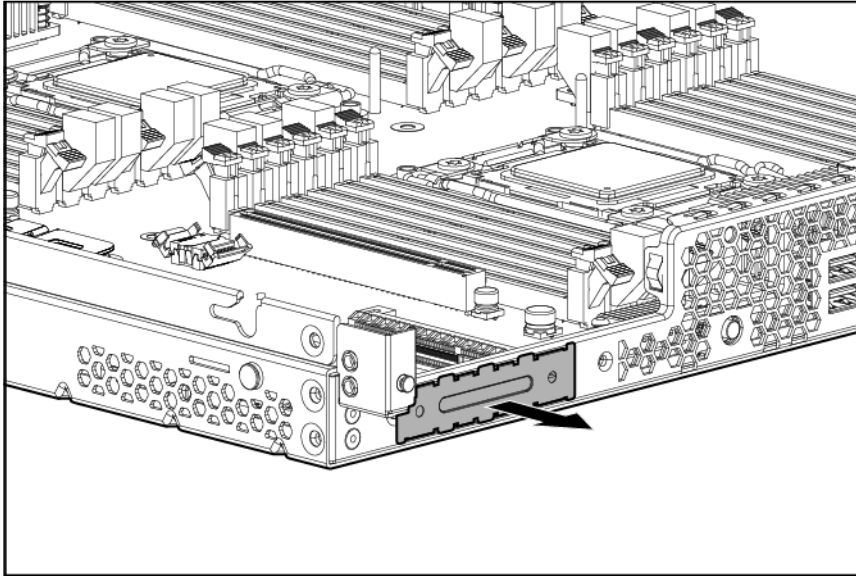
FlexibleLOM option



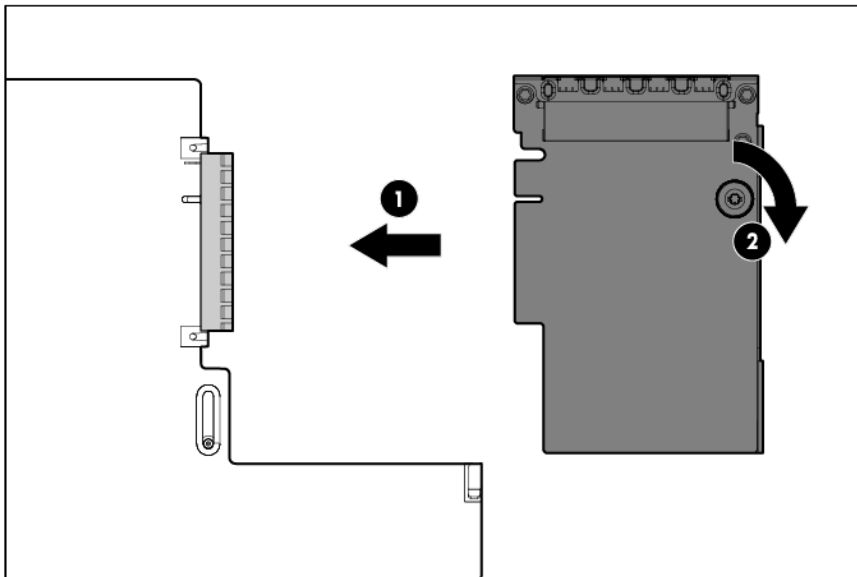
WARNING: To reduce the risk of personal injury, electric shock, or damage to the equipment, remove the power cord to remove power from the server. The front panel Power On/Standby button does not completely shut off system power. Portions of the power supply and some internal circuitry remain active until AC power is removed.

1. If installed, remove the rack bezel (on page 59).
2. Power down the server (on page 17).
3. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
4. Remove any attached network cables.
5. Extend the server from the rack (on page 17).
6. Remove the access panel (on page 19).
7. Remove the processor air baffle (on page 19).
8. Remove the PCI riser cage (on page 20).
9. Loosen the thumbscrew.

10. Remove the FlexibleLOM blank.



11. Install the component:
- a. Firmly seat the FlexibleLOM in the slot.
 - b. Tighten the thumbscrew.



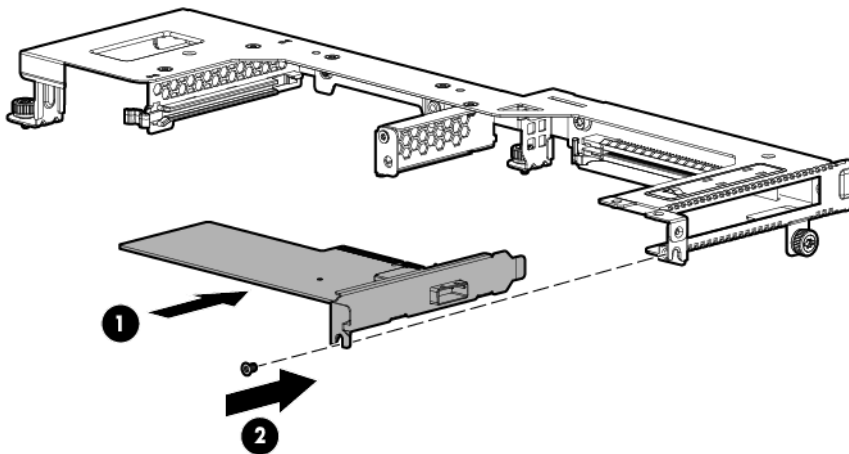
12. Install the PCI riser cage. ("[Install the PCI riser cage](#)" on page 21)
13. Install the processor air baffle ("[Install the processor air baffle](#)" on page 20).
14. Install the access panel (on page 19).
15. Slide the server into the rack.
16. Connect the LAN segment cables.
17. Connect each power cord to the server.
18. Connect each power cord to the power source.
19. Power up the server (on page 17).
20. If removed, install the rack bezel (on page 60).

Expansion board options

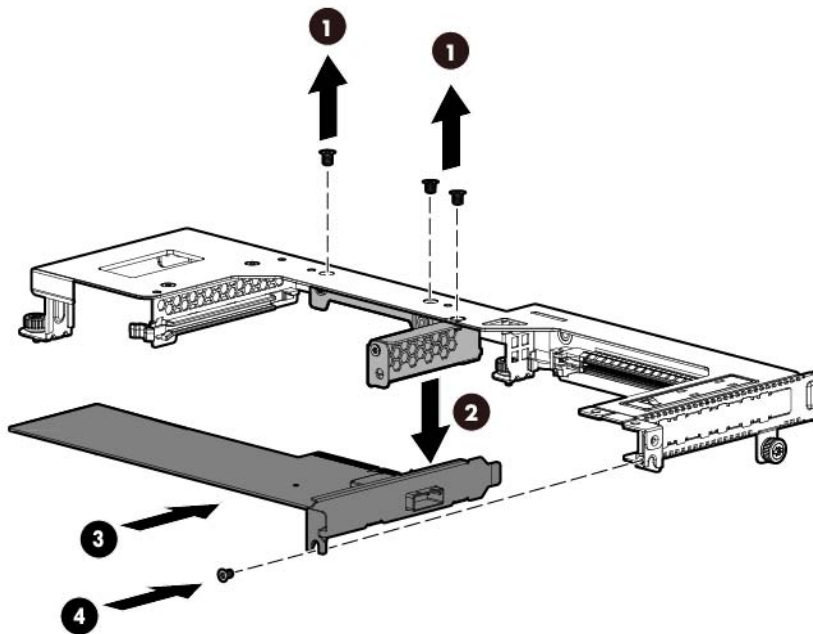
The server supports PCI Express expansion boards. The server ships with PCIe riser boards and expansion slots. PCIe expansion boards are supported with optional riser boards.

Installing an expansion board

1. If installed, remove the rack bezel (on page 59).
2. Power down the server (on page 17).
3. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
4. Extend the server from the rack (on page 17).
5. Remove the access panel (on page 19).
6. Remove the processor air baffle (on page 19).
7. Remove the PCI riser board assembly ("[Remove the PCI riser cage](#)" on page 20).
8. Remove the expansion slot cover from the PCI riser board assembly.
9. Install the expansion board.
 - o If installing a half length expansion board, install the expansion board into the slot until it seats firmly.



- If installing a full length full height expansion board, remove the low profile bracket, and then install the expansion board into the slot until it sits firmly.



10. Install the PCI riser board assembly. ("Install the PCI riser cage" on page 21)



IMPORTANT: The server does not power up if the PCI riser board assembly is not seated properly.

11. Connect all internal or external cabling to the expansion boards.
12. Install the processor air baffle. ("Install the processor air baffle" on page 20)
13. Install the access panel (on page 19).
14. Slide the server into the rack.
15. Connect each power cord to the server.
16. Connect each power cord to the power source.
17. Power up the server (on page 17).
18. If removed, install the rack bezel (on page 60).

Common slot power supply option

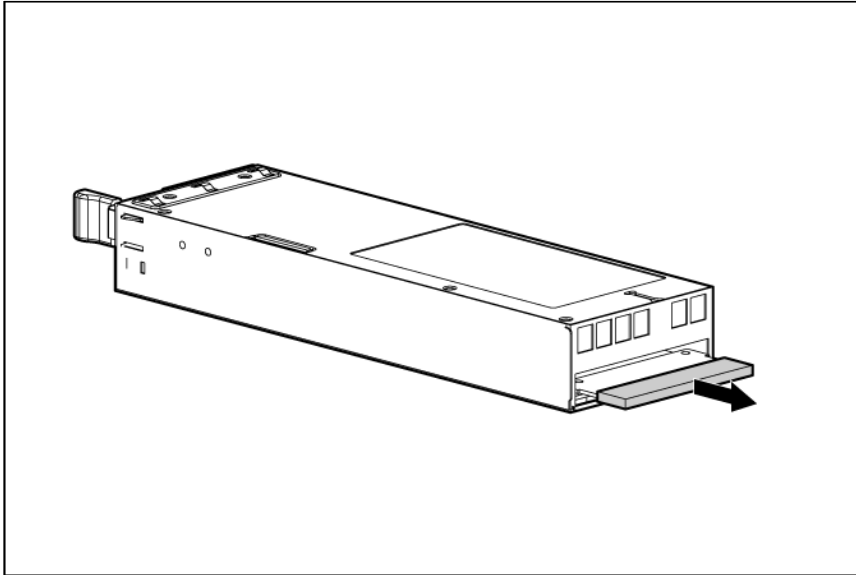


CAUTION: To prevent improper cooling and thermal damage, do not operate the server unless all bays are populated with either a component or a blank.

To install the component:

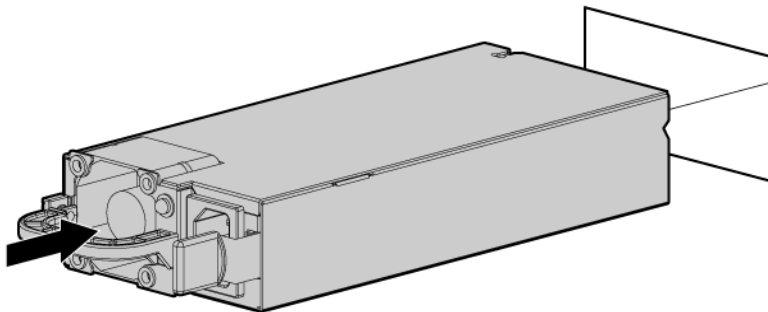
1. Unfasten the cable management solution to access the power supply bays.

2. Remove the protective cover from the connector pins on the power supply.

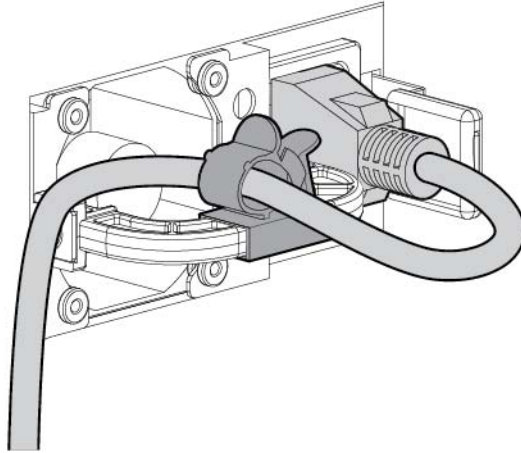


WARNING: To reduce the risk of electric shock or damage to the equipment, do not connect the power cord to the power supply until the power supply is installed.

3. Install the power supply into the bay until it clicks into place.



4. Connect the power cord to the power supply.



5. Route the power cord through the cable management solution to strain relief clip.
6. Connect the power cord to the power source.

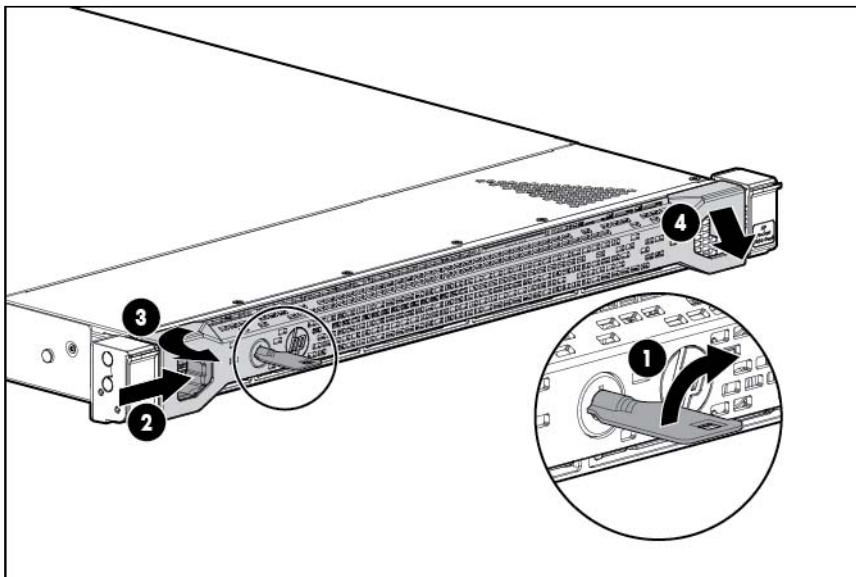
Be sure that the power supply LED is green.

Rack bezel option

The rack bezel helps prevent any unauthorized physical access to the server in the rack configuration. To access the drive cage, you must unlock and open the rack bezel.

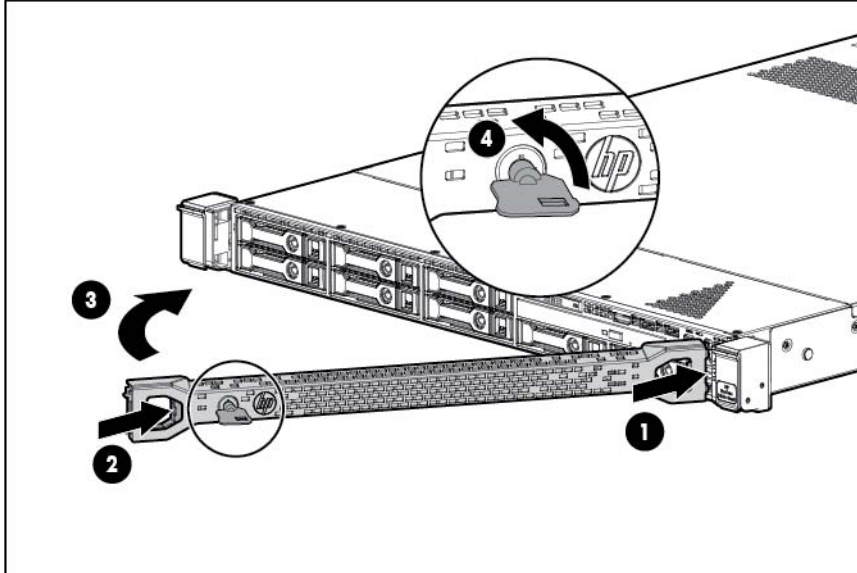
Remove the rack bezel

Unlock the rack bezel, press the latch on the rack bezel, and then remove the rack bezel.



Install the rack bezel

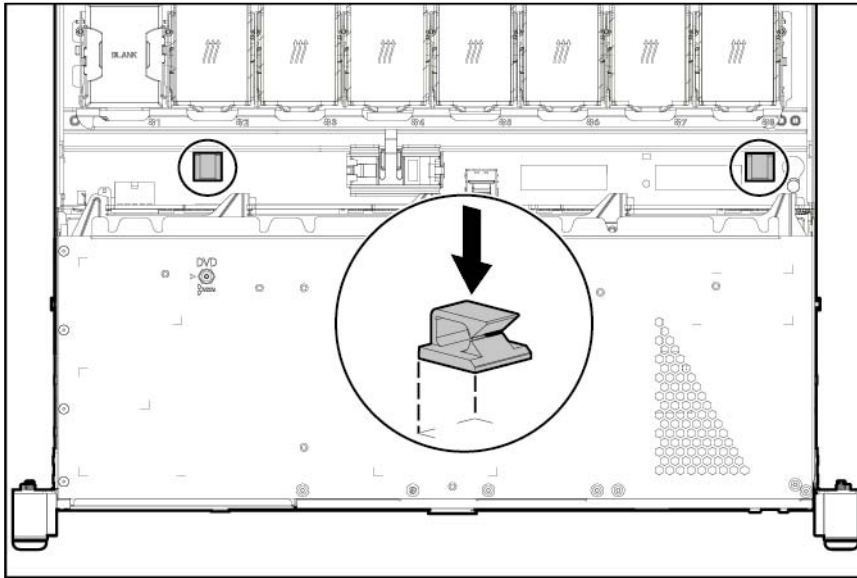
Install the rack bezel into the chassis, and then lock the rack bezel with the key.



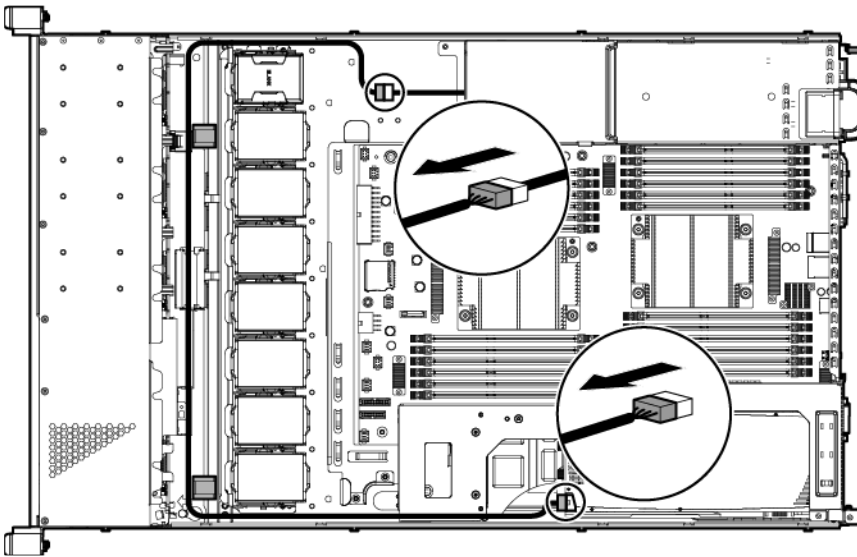
VGA power cable option

1. If installed, remove the rack bezel. ("[Remove the rack bezel](#)" on page 59)
2. Power down the server (on page 17).
3. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
4. Extend the server from the rack (on page 17).
5. Remove the access panel (on page 19).
6. Remove the processor air baffle (on page 19).

7. Remove the adhesive stickers from the VGA cable clips, and then attach the clips onto the fan cage.



8. Route the cable through the cable clips, and then connect the cable to the VGA card and power supply cable.



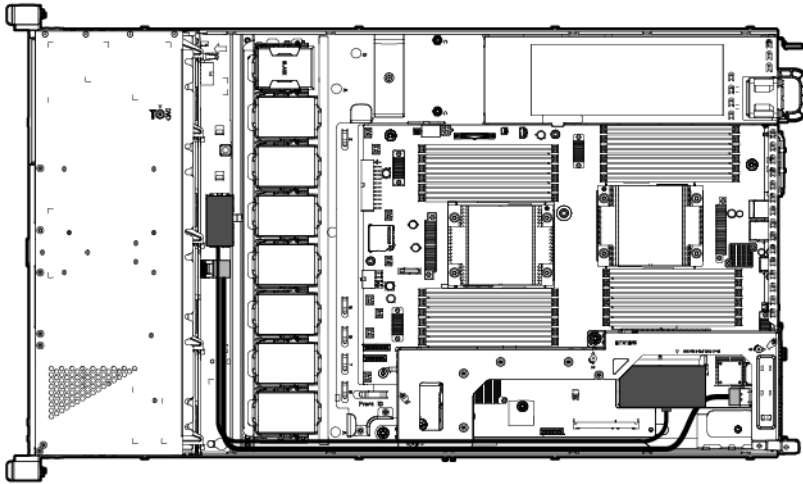
9. Install the processor air baffle. ("Install the processor air baffle" on page 20)
10. Install the access panel.
11. Slide the server into the rack.
12. Connect each power cord to the server.
13. Connect each power cord to the power source.
14. Power up the server (on page 17).
15. If removed, install the rack bezel (on page 60).

Mini-SAS cable option

The server supports the 700 mm mini-SAS cable option.

Installing the 700mm mini-SAS cable

1. If installed, remove the rack bezel (on page 59).
2. Power down the server (on page 17).
3. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
4. Extend the server from the rack (on page 17).
5. Remove the access panel (on page 19).
6. Remove the processor air baffle (on page 19).
7. Install a P222 Smart Array Controller.
8. Connect the mini-SAS cable from the Smart Array Controller to the drive backplane.



9. Install the processor air baffle (on page 20).
10. Install the access panel (on page 19).
11. Slide the server into the rack.
12. Connect each power cord to the server.
13. Connect each power cord to the power source.
14. Power up the server (on page 17).
15. If removed, install the rack bezel (on page 60).

HP Trusted Platform Module option

Use these instructions to install and enable a TPM on a supported server. This procedure includes three sections:

1. Installing the Trusted Platform Module board.
2. Retaining the recovery key/password (on page 65).
3. Enabling the Trusted Platform Module (on page 65).

Enabling the TPM requires accessing RBSU ("HP ROM-Based Setup Utility" on page 76). For more information about RBSU, see the HP website (<http://www.hp.com/go/ilomgmtengine/docs>).

TPM installation requires the use of drive encryption technology, such as the Microsoft Windows BitLocker Drive Encryption feature. For more information on BitLocker, see the Microsoft website (<http://www.microsoft.com>).



CAUTION: Always observe the guidelines in this document. Failure to follow these guidelines can cause hardware damage or halt data access.

When installing or replacing a TPM, observe the following guidelines:

- Do not remove an installed TPM. Once installed, the TPM becomes a permanent part of the system board.
- When installing or replacing hardware, HP service providers cannot enable the TPM or the encryption technology. For security reasons, only the customer can enable these features.
- When returning a system board for service replacement, do not remove the TPM from the system board. When requested, HP Service provides a TPM with the spare system board.
- Any attempt to remove an installed TPM from the system board breaks or disfigures the TPM security rivet. Upon locating a broken or disfigured rivet on an installed TPM, administrators should consider the system compromised and take appropriate measures to ensure the integrity of the system data.
- When using BitLocker, always retain the recovery key/password. The recovery key/password is required to enter Recovery Mode after BitLocker detects a possible compromise of system integrity.
- HP is not liable for blocked data access caused by improper TPM use. For operating instructions, see the encryption technology feature documentation provided by the operating system.

Installing the Trusted Platform Module board



WARNING: To reduce the risk of personal injury, electric shock, or damage to the equipment, remove the power cord to remove power from the server. The front panel Power On/Standby button does not completely shut off system power. Portions of the power supply and some internal circuitry remain active until AC power is removed.



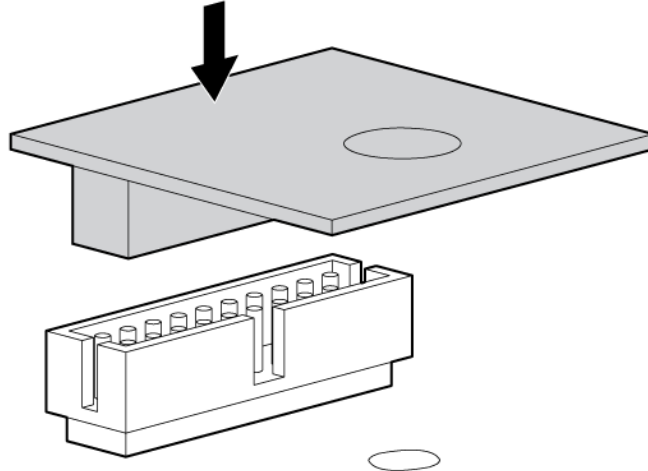
WARNING: To reduce the risk of personal injury from hot surfaces, allow the drives and the internal system components to cool before touching them.

1. If installed, remove the rack bezel (on page 59).
2. Power down the server (on page 17).
3. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
4. Extend the server from the rack (on page 17).
5. Remove the access panel (on page 19).
6. Remove the processor air baffle (on page 19).
7. Remove the PCI riser cage.

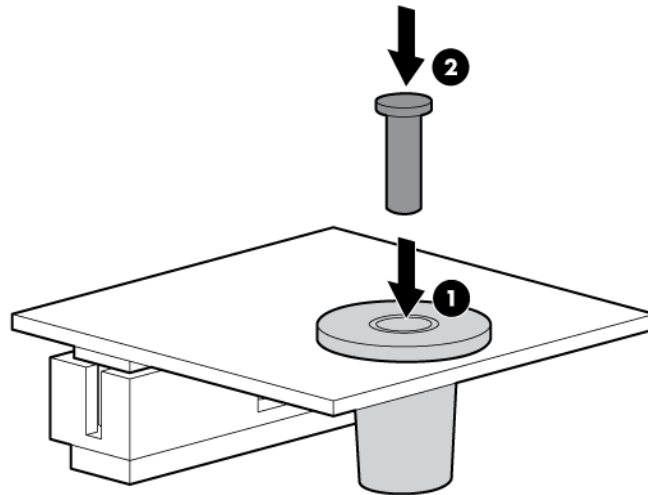


CAUTION: Any attempt to remove an installed TPM from the system board breaks or disfigures the TPM security rivet. Upon locating a broken or disfigured rivet on an installed TPM, administrators should consider the system compromised and take appropriate measures to ensure the integrity of the system data.

8. Install the TPM board. Press down on the connector to seat the board ("[System board components](#)" on page [11](#)).



9. Install the TPM security rivet by pressing the rivet firmly into the system board.



10. Install the PCI riser cage.
11. Install the processor air baffle (on page [20](#)).
12. Install the access panel (on page [19](#)).
13. Slide the server into the rack.
14. Connect each power cord to the server.
15. Connect each power cord to the power source.
16. Power up the server (on page [17](#)).
17. If removed, install the rack bezel (on page [60](#)).

Retaining the recovery key/password

The recovery key/password is generated during BitLocker™ setup, and can be saved and printed after BitLocker™ is enabled. When using BitLocker™, always retain the recovery key/password. The recovery key/password is required to enter Recovery Mode after BitLocker™ detects a possible compromise of system integrity.

To help ensure maximum security, observe the following guidelines when retaining the recovery key/password:

- Always store the recovery key/password in multiple locations.
- Always store copies of the recovery key/password away from the server.
- Do not save the recovery key/password on the encrypted hard drive.

Enabling the Trusted Platform Module

1. When prompted during the start-up sequence, access RBSU by pressing the **F9** key.
2. From the Main Menu, select **Server Security**.
3. From the Server Security Menu, select **Trusted Platform Module**.
4. From the Trusted Platform Module Menu, select **TPM Functionality**.
5. Select **Enable**, and then press the **Enter** key to modify the TPM Functionality setting.
6. Press the **Esc** key to exit the current menu, or press the **F10** key to exit RBSU.
7. Reboot the server.
8. Enable the TPM in the OS. For OS-specific instructions, see the OS documentation.



CAUTION: When a TPM is installed and enabled on the server, data access is locked if you fail to follow the proper procedures for updating the system or option firmware, replacing the system board, replacing a hard drive, or modifying OS application TPM settings.

For more information on firmware updates and hardware procedures, see the *HP Trusted Platform Module Best Practices White Paper* on the HP website (<http://www.hp.com/support>).

For more information on adjusting TPM usage in BitLocker™, see the Microsoft website (<http://technet.microsoft.com/en-us/library/cc732774.aspx>).

Cabling

Cabling overview

This section provides guidelines that help you make informed decisions about cabling the server and hardware options to optimize performance.

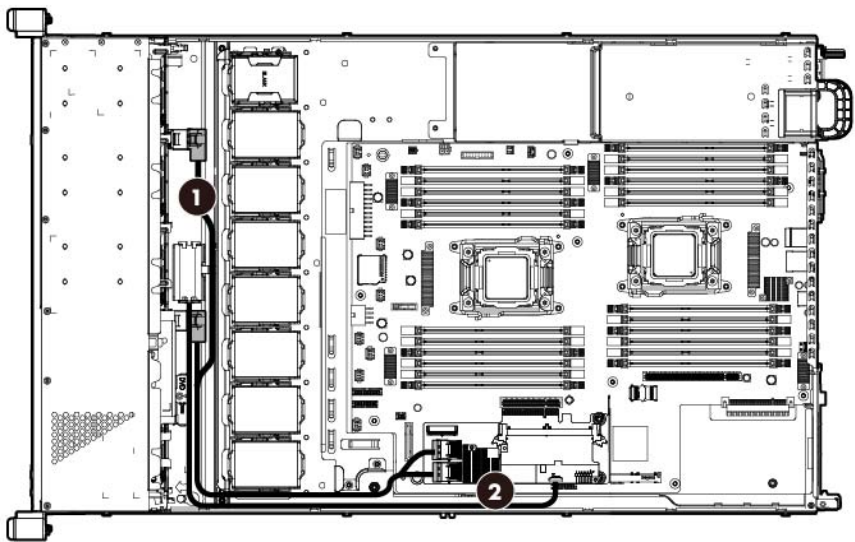
For information on cabling peripheral components, refer to the white paper on high-density deployment at the HP website (<http://www.hp.com/products/servers/platforms>).



CAUTION: When routing cables, always be sure that the cables are not in a position where they can be pinched or crimped.

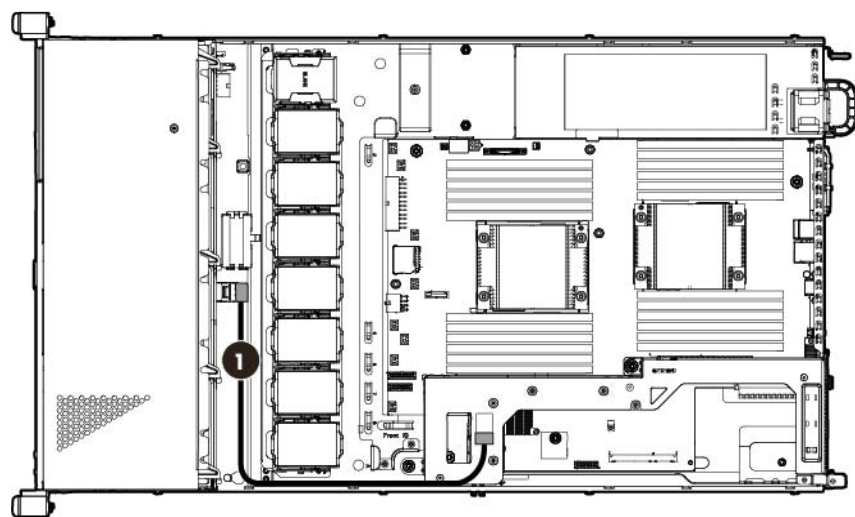
Data cabling

P420 Smart Array Controller cabling



Cable number	Description
1	SAS cable
2	FBWC capacitor pack cable

SATA cabling

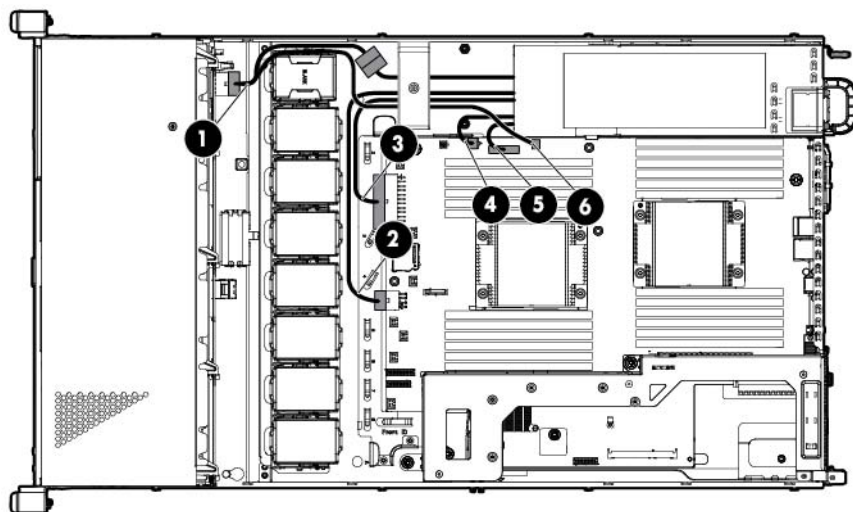


Cable number	Description
1	SATA Cable

Power cabling

Server power cabling

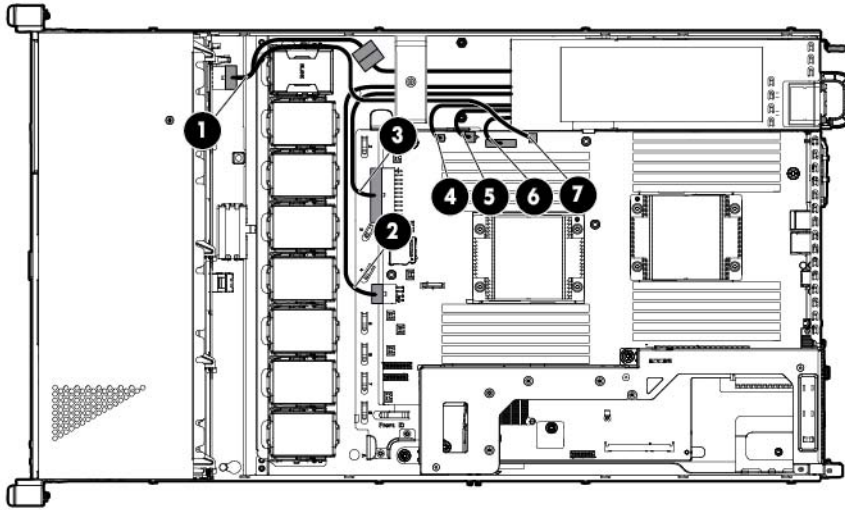
Basic configuration



Cable number	Description
1	Drive backplane cable
2	2x4 Power supply cable
3	2x12 Power supply cable
4	2x2 Power supply cable
5	RPS control cable

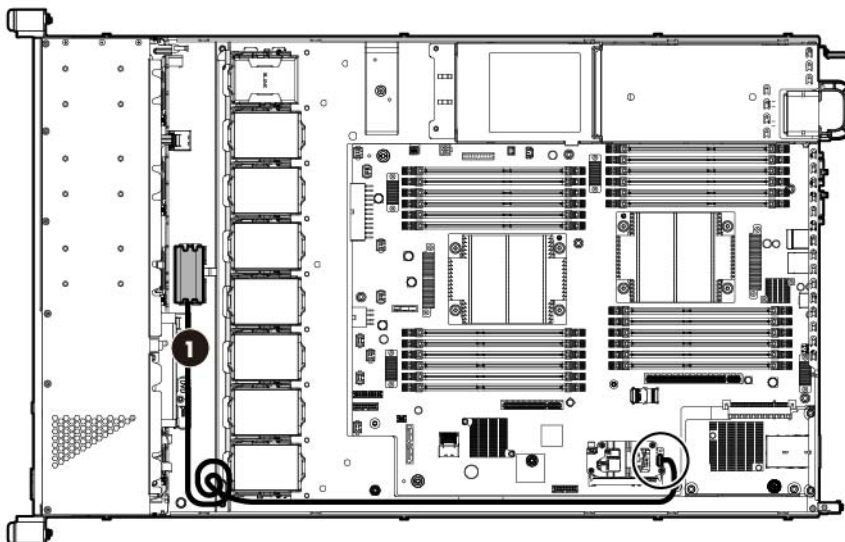
Cable number	Description
6	Discovery service cable

Maximum configuration



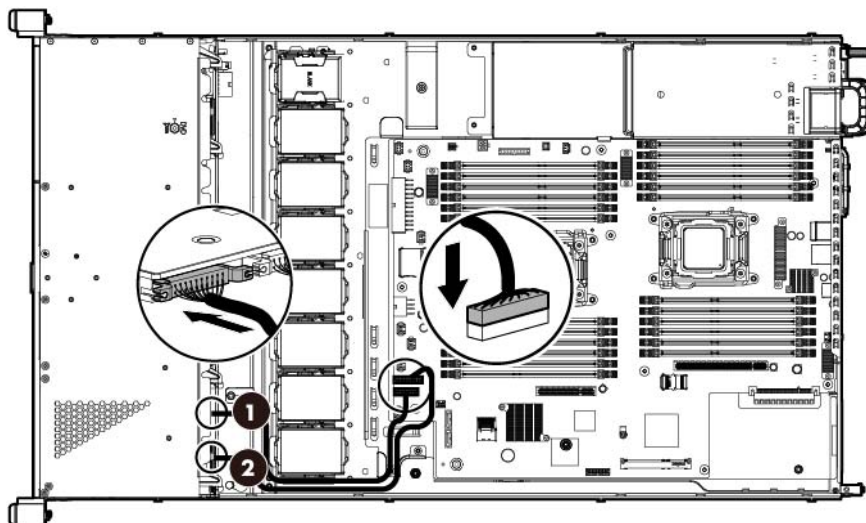
Cable number	Description
1	Drive backplane cable
2	2x4 Power supply cable
3	2x12 Power supply cable
4	FlexibleLOM standby power cable
5	2x2 Power supply cable
6	RPS control cable
7	Discovery service cable

FBWC capacitor pack cabling



Cable number	Description
1	FBWC capacitor pack cable

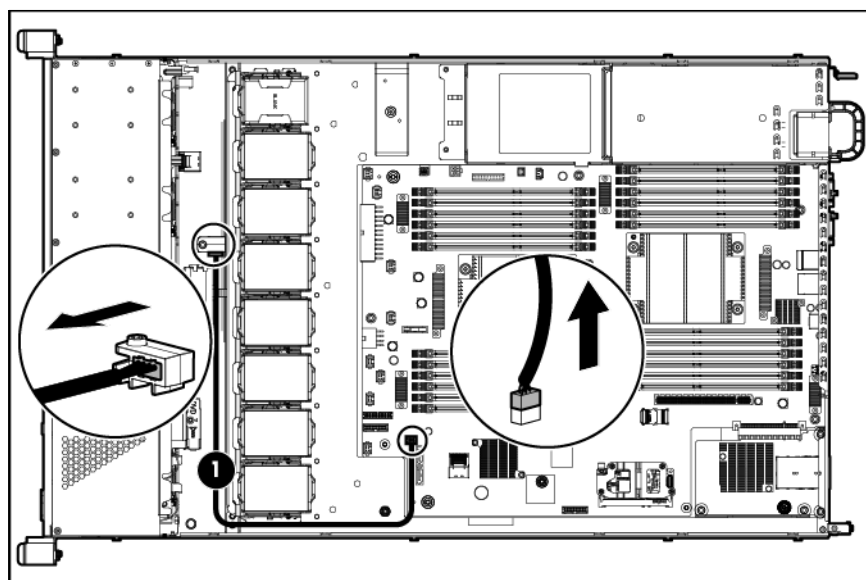
Front panel cabling



Cable number	Description
1	2x10 Front panel IO cables
2	2x12 Front panel IO cables

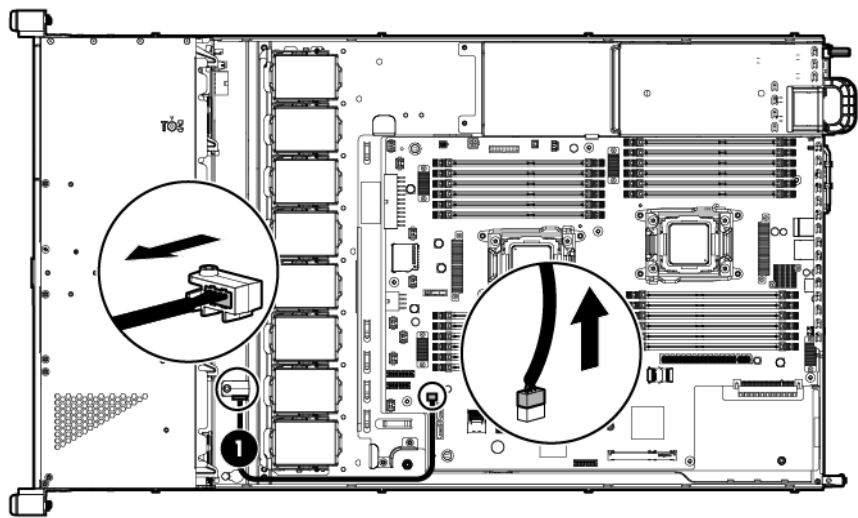
Internal USB cabling

SFF configuration



Cable number	Description
1	Internal USB cable

LFF configuration



Cable number	Description
1	Internal USB cable

Software and configuration utilities

Server mode

The software and configuration utilities presented in this section operate in online mode, offline mode, or in both modes.

Software or configuration utility	Server mode
HP iLO (on page 71)	Online and Offline
Active Health System (on page 72)	Online and Offline
Integrated Management Log (on page 73)	Online and Offline
Intelligent Provisioning (on page 73)	Offline
HP Insight Diagnostics (on page 74)	Online and Offline
Erase Utility (on page 74)	Offline
Scripting Toolkit (on page 75)	Online
HP Service Pack for ProLiant (on page 75)	Online and Offline
HP Smart Update Manager (on page 75)	Online and Offline
HP ROM-Based Setup Utility (on page 76)	Offline
Array Configuration Utility (on page 78)	Online and Offline
Option ROM Configuration for Arrays (on page 79)	Offline
ROMPaq utility (on page 79)	Offline

Server QuickSpecs

For more information about product features, specifications, options, configurations, and compatibility, see the QuickSpecs on the HP website (<http://h18000.www1.hp.com/products/quickspecs/ProductBulletin.html>). At the website, choose the geographic region, and then locate the product by name or product category.

HP iLO Management Engine

The HP iLO Management Engine is a set of embedded management features supporting the complete lifecycle of the server, from initial deployment through ongoing management.

HP iLO

The iLO subsystem is a standard component of selected HP ProLiant servers that simplifies initial server setup, server health monitoring, power and thermal optimization, and remote server administration. The iLO subsystem includes an intelligent microprocessor, secure memory, and a dedicated network interface. This design makes iLO independent of the host server and its operating system.

iLO enables and manages the Active Health System (on page 72) and also features Agentless Management. All key internal subsystems are monitored by iLO. SNMP alerts are sent directly by iLO regardless of the host operating system or even if no host operating system is installed.

Using iLO, you can do the following:

- Access a high-performance and secure Remote Console to the server from anywhere in the world.
- Use the shared iLO Remote Console to collaborate with up to six server administrators.
- Remotely mount high-performance Virtual Media devices to the server.
- Securely and remotely control the power state of the managed server.
- Have true Agentless Management with SNMP alerts from iLO regardless of the state of the host server.
- Access Active Health System troubleshooting features through the iLO interface.

For more information about iLO features (which may require an iLO Advanced Pack or iLO Advanced for BladeSystem license), see the iLO documentation on the Documentation CD or on the HP website (<http://www.hp.com/go/ilo/docs>).

Active Health System

HP Active Health System provides the following features:

- Combined diagnostics tools/scanners
- Always on, continuous monitoring for increased stability and shorter downtimes
- Rich configuration history
- Health and service alerts
- Easy export and upload to Service and Support

The HP Active Health System monitors and records changes in the server hardware and system configuration. The Active Health System assists in diagnosing problems and delivering rapid resolution when server failures occur.

The Active Health System collects the following types of data:

- Server model
- Serial number
- Processor model and speed
- Storage capacity and speed
- Memory capacity and speed
- Firmware/BIOS

HP Active Health System does not collect information about Active Health System users' operations, finances, customers, employees, partners, or data center, such as IP addresses, host names, user names, and passwords. HP Active Health System does not parse or change operating system data from third-party error event log activities, such as content created or passed through by the operating system.

The data that is collected is managed according to the HP Data Privacy policy. For more information see the HP website (<http://www.hp.com/go/privacy>).

The Active Health System log, in conjunction with the system monitoring provided by Agentless Management or SNMP Pass-thru, provides continuous monitoring of hardware and configuration changes, system status, and service alerts for various server components.

The Agentless Management Service is available in the SPP, which is a disk image (.iso) that you can download from the HP website (<http://www.hp.com/go/spp/download>). The Active Health System log can be downloaded manually from iLO or HP Intelligent Provisioning and sent to HP. For more information, see the *HP iLO User Guide* or *HP Intelligent Provisioning User Guide* on the HP website (<http://www.hp.com/go/ilo/docs>).

Integrated Management Log

The IML records hundreds of events and stores them in an easy-to-view form. The IML timestamps each event with 1-minute granularity.

You can view recorded events in the IML in several ways, including the following:

- From within HP SIM
- From within operating system-specific IML viewers
 - For Windows: IML Viewer
 - For Linux: IML Viewer Application
- From within the iLO user interface
- From within HP Insight Diagnostics (on page 74)

Intelligent Provisioning

Several packaging changes have taken place with HP ProLiant Gen8 servers: SmartStart CDs and the Smart Update Firmware DVD will no longer ship with these new servers. Instead, the deployment capability is embedded in the server as part of HP iLO Management Engine's Intelligent Provisioning.

Intelligent Provisioning is an essential single-server deployment tool embedded in HP ProLiant Gen8 servers that simplifies HP ProLiant server setup, providing a reliable and consistent way to deploy HP ProLiant server configurations.

- Intelligent Provisioning assists with the OS installation process by preparing the system for installing "off-the-shelf" versions of leading operating system software and automatically integrating optimized HP ProLiant server support software from SPP. SPP is the installation package for operating system-specific bundles of HP ProLiant optimized drivers, utilities, management agents, and system firmware.
- Intelligent Provisioning provides maintenance-related tasks through Perform Maintenance features.
- Intelligent Provisioning provides installation help for Microsoft Windows, Red Hat and SUSE Linux, and VMware. For specific OS support, see the *HP Intelligent Provisioning Release Notes*.

For more information on Intelligent Provisioning software, see the HP website (<http://www.hp.com/go/ilo>). For more information about Intelligent Provisioning drivers, firmware, and SPP, see the HP website (<http://www.hp.com/go/spp/download>).

HP Insight Diagnostics

HP Insight Diagnostics is a proactive server management tool, available in both offline and online versions, that provides diagnostics and troubleshooting capabilities to assist IT administrators who verify server installations, troubleshoot problems, and perform repair validation.

HP Insight Diagnostics Offline Edition performs various in-depth system and component testing while the OS is not running. To run this utility, boot the server using Intelligent Provisioning (on page 73).

HP Insight Diagnostics Online Edition is a web-based application that captures system configuration and other related data needed for effective server management. Available in Microsoft Windows and Linux versions, the utility helps to ensure proper system operation.

For more information or to download the utility, see the HP website (<http://www.hp.com/servers/diags>). HP Insight Diagnostics Online Edition is also available in the SPP. For more information, see the HP website (<http://www.hp.com/go/spp/download>).

HP Insight Diagnostics survey functionality

HP Insight Diagnostics (on page 74) provides survey functionality that gathers critical hardware and software information on ProLiant servers.

This functionality supports operating systems that are supported by the server. For operating systems supported by the server, see the HP website (<http://www.hp.com/go/supportos>).

If a significant change occurs between data-gathering intervals, the survey function marks the previous information and overwrites the survey data files to reflect the latest changes in the configuration.

Survey functionality is installed with every Intelligent Provisioning-assisted HP Insight Diagnostics installation, or it can be installed through the SPP ("HP Service Pack for ProLiant" on page 75).

Erase Utility



CAUTION: Perform a backup before running the System Erase Utility. The utility sets the system to its original factory state, deletes the current hardware configuration information, including array setup and disk partitioning, and erases all connected hard drives completely. Refer to the instructions for using this utility.

The Erase utility enables you to erase system CMOS, NVRAM, and hard drives. Run the Erase Utility if you must erase the system for the following reasons:

- You want to install a new operating system on a server with an existing operating system.
- You encounter an error when completing the steps of a factory-installed operating system installation.

To access the Erase Utility, click the Perform Maintenance icon from the Intelligent Provisioning home screen and then select **Erase**.

Run the Erase utility to:

- **Reset all settings** — erases all drives, NVRAM, and RBSU
- **Reset all disks** — erases all drives
- **Reset RBSU** — erases current RBSU settings

After selecting the appropriate option, click **Erase System**. Click **Exit** to reboot the server after the erase task is completed. Click **Cancel Erase** to exit the utility without erasing.

Scripting Toolkit

The Scripting Toolkit is a server deployment product that enables you to build an unattended automated installation for high-volume server deployments. The Scripting Toolkit is designed to support ProLiant BL, ML, DL, and SL servers. The toolkit includes a modular set of utilities and important documentation that describes how to apply these tools to build an automated server deployment process.

The Scripting Toolkit provides a flexible way to create standard server configuration scripts. These scripts are used to automate many of the manual steps in the server configuration process. This automated server configuration process cuts time from each deployment, making it possible to scale rapid, high-volume server deployments.

For more information, and to download the Scripting Toolkit, see the HP website (<http://www.hp.com/go/ProLiantSTK>).

HP Service Pack for ProLiant

SPP is a release set that contains a comprehensive collection of firmware and system software components, all tested together as a single solution stack for HP ProLiant servers, their options, BladeSystem enclosures, and limited HP external storage.

SPP has several key features for updating HP ProLiant servers. Using HP SUM as the deployment tool, SPP can be used in an online mode on a Windows or Linux hosted operating system, or in an offline mode where the server is booted to the ISO so that the server can be updated automatically with no user interaction or updated in interactive mode.

For more information or to download SPP, see the HP website (<http://www.hp.com/go/spp>).

HP Smart Update Manager

The HP SUM provides intelligent and flexible firmware and software deployment. This technology assists in reducing the complexity of provisioning and updating HP ProLiant Servers, options, and Blades within the data center. HP SUM is used to deploy firmware and software in SPP.

HP SUM enables system administrators to upgrade ROM images efficiently across a wide range of servers and options. This tool has the following features:

- Enables GUI and a command-line, scriptable interface
- Provides scriptable, command-line deployment
- Requires no agent for remote installations
- Enables dependency checking, which ensures appropriate install order and dependency checking between components
- Deploys software and firmware on Windows and Linux operating systems
- Performs local or remote (one-to-many) online deployment
- Deploys firmware and software together
- Supports offline and online deployment
- Deploys necessary component updates only
- Downloads the latest components from Web

- Enables direct update of BMC firmware (HP iLO)

For more information about HP SUM and to access the *HP Smart Update Manager User Guide*, see the HP website (<http://www.hp.com/go/hpsum/documentation>).

HP ROM-Based Setup Utility

RBSU is a configuration utility embedded in ProLiant servers that performs a wide range of configuration activities that can include the following:

- Configuring system devices and installed options
- Enabling and disabling system features
- Displaying system information
- Selecting the primary boot controller
- Configuring memory options
- Language selection

For more information on RBSU, see the *HP ROM-Based Setup Utility User Guide* on the Documentation CD or the HP website (<http://www.hp.com/support/rbsu>).

Using RBSU

To use RBSU, use the following keys:

- To access RBSU, press the **F9** key during power-up when prompted.
- To navigate the menu system, use the arrow keys.
- To make selections, press the **Enter** key.
- To access Help for a highlighted configuration option, press the **F1** key.



IMPORTANT: RBSU automatically saves settings when you press the **Enter** key. The utility does not prompt you for confirmation of settings before you exit the utility. To change a selected setting, you must select a different setting and press the **Enter** key.

Default configuration settings are applied to the server at one of the following times:

- Upon the first system power-up
- After defaults have been restored

Default configuration settings are sufficient for proper typical server operation, but configuration settings can be modified using RBSU. The system will prompt you for access to RBSU with each power-up.

Auto-configuration process

The auto-configuration process automatically runs when you boot the server for the first time. During the power-up sequence, the system ROM automatically configures the entire system without needing any intervention. During this process, the ORCA utility, in most cases, automatically configures the array to a default setting based on the number of drives connected to the server.

NOTE: If the boot drive is not empty or has been written to in the past, ORCA does not automatically configure the array. You must run ORCA to configure the array settings.

NOTE: The server may not support all the following examples.

Drives installed	Drives used	RAID level
1	1	RAID 0
2	2	RAID 1
3, 4, 5, or 6	3, 4, 5, or 6	RAID 5
More than 6	0	None

To change any ORCA default settings and override the auto-configuration process, press the **F8** key when prompted.

For more information on RBSU, see the *HP ROM-Based Setup Utility User Guide* on the Documentation CD or the HP website (<http://www.hp.com/support/rbsu>).

Boot options

Near the end of the boot process, the boot options screen is displayed. This screen is visible for several seconds before the system attempts to boot from a supported boot device. During this time, you can do the following:

- Access RBSU by pressing the **F9** key.
- Access Intelligent Provisioning Maintenance Menu by pressing the **F10** key.
- Access the boot menu by pressing the **F11** key.
- Force a PXE Network boot by pressing the **F12** key.

Configuring AMP modes

Not all ProLiant servers support all AMP modes. RBSU provides menu options only for the modes supported by the server. Advanced memory protection within RBSU enables the following advanced memory modes:

- **Advanced ECC Mode**—Provides memory protection beyond Standard ECC. All single-bit failures and some multi-bit failures can be corrected without resulting in system downtime.
- **Online Spare Mode**—Provides protection against failing or degraded DIMMs. Certain memory is set aside as spare, and automatic failover to spare memory occurs when the system detects a degraded DIMM. DIMMs that are likely to receive a fatal or uncorrectable memory error are removed from operation automatically, resulting in less system downtime.

For DIMM population requirements, see the server-specific user guide.

Re-entering the server serial number and product ID

After you replace the system board, you must re-enter the server serial number and the product ID.

1. During the server startup sequence, press the **F9** key to access RBSU.
2. Select the **Advanced Options** menu.
3. Select **Service Options**.
4. Select **Serial Number**. The following warnings appear:

WARNING! WARNING! WARNING! The serial number is loaded into the system during the manufacturing process and should NOT be modified. This option should only be used by qualified service personnel. This value should always match the serial number sticker located on the chassis.

Warning: The serial number should ONLY be modified by qualified service personnel. This value should always match the serial number located on the chassis.

5. Press the **Enter** key to clear the warning.
6. Enter the serial number and press the **Enter** key.
7. Select **Product ID**. The following warning appears:
Warning: The Product ID should ONLY be modified by qualified service personnel. This value should always match the Product ID on the chassis.
8. Enter the product ID and press the **Enter** key.
9. Press the **Esc** key to close the menu.
10. Press the **Esc** key to exit RBSU.
11. Press the **F10** key to confirm exiting RBSU. The server automatically reboots.

Utilities and features

Array Configuration Utility

ACU is a browser-based utility with the following features:

- Runs as a local application or remote service accessed through the HP System Management Homepage
- Supports online array capacity expansion, logical drive extension, assignment of online spares, and RAID or stripe size migration
- Suggests the optimum configuration for an unconfigured system
- For supported controllers, provides access to licensed features, including:
 - Moving and deleting individual logical volumes
 - Advanced Capacity Expansion (SATA to SAS and SAS to SATA)
 - Offline Split Mirror
 - RAID 6 and RAID 60
 - RAID 1 (ADM) and RAID 10 (ADM)
 - HP Drive Erase
 - Video-On-Demand Advanced Controller Settings
- Provides different operating modes, enabling faster configuration or greater control over the configuration options
- Remains available any time that the server is on
- Displays on-screen tips for individual steps of a configuration procedure
- Provides context-sensitive searchable help content
- Provides diagnostic and SmartSSD Wear Gauge functionality on the Diagnostics tab

ACU is now available as an embedded utility, starting with HP ProLiant Gen8 servers. To access ACU, use one of the following methods:

- If an optional controller is not installed, press **F10** during boot.
- If an optional controller is installed, when the system recognizes the controller during POST, press **F5**.

For optimum performance, the minimum display settings are 1024 × 768 resolution and 16-bit color. Servers running Microsoft® operating systems require one of the following supported browsers:

- Internet Explorer 6.0 or later
- Mozilla Firefox 2.0 or later

For Linux servers, see the README.TXT file for additional browser and support information.

For more information about the controller and its features, see the *HP Smart Array Controllers for HP ProLiant Servers User Guide* on the HP website

(<http://bizsupport2.austin.hp.com/bc/docs/support/SupportManual/c01608507/c01608507.pdf>). To configure arrays, see the *Configuring Arrays on HP Smart Array Controllers Reference Guide* on the HP website

(<http://bizsupport1.austin.hp.com/bc/docs/support/SupportManual/c00729544/c00729544.pdf>).

Option ROM Configuration for Arrays

Before installing an operating system, you can use the ORCA utility to create the first logical drive, assign RAID levels, and establish online spare configurations.

The utility also provides support for the following functions:

- Reconfiguring one or more logical drives
- Viewing the current logical drive configuration
- Deleting a logical drive configuration
- Setting the controller to be the boot controller
- Selecting the boot volume

If you do not use the utility, ORCA will default to the standard configuration.

For more information regarding the default configurations that ORCA uses, see the *HP ROM-Based Setup Utility User Guide* on the Documentation CD or the HP website (<http://www.hp.com/support/rbsu>).

For more information about the controller and its features, see the *HP Smart Array Controllers for HP ProLiant Servers User Guide* on the HP website

(<http://bizsupport2.austin.hp.com/bc/docs/support/SupportManual/c01608507/c01608507.pdf>). To configure arrays, see the *Configuring Arrays on HP Smart Array Controllers Reference Guide* on the HP website

(<http://bizsupport1.austin.hp.com/bc/docs/support/SupportManual/c00729544/c00729544.pdf>).

ROMPq utility

The ROMPq utility enables you to upgrade the system firmware (BIOS). To upgrade the firmware, insert a ROMPq USB Key into an available USB port and boot the system. In addition to ROMPq, Online Flash Components for Windows and Linux operating systems are available for updating the system firmware.

The ROMPq utility checks the system and provides a choice (if more than one exists) of available firmware revisions.

For more information, see the Download drivers and software page for the server. To access the server-specific page, enter the following web address into the browser:

<http://www.hp.com/support/<servername>>

For example:

<http://www.hp.com/support/dl360g6>

Automatic Server Recovery

ASR is a feature that causes the system to restart when a catastrophic operating system error occurs, such as a blue screen, ABEND (does not apply to HP ProLiant DL980 Servers), or panic. A system fail-safe timer, the ASR timer, starts when the System Management driver, also known as the Health Driver, is loaded. When the operating system is functioning properly, the system periodically resets the timer. However, when the operating system fails, the timer expires and restarts the server.

ASR increases server availability by restarting the server within a specified time after a system hang. At the same time, the HP SIM console notifies you by sending a message to a designated pager number that ASR has restarted the system. You can disable ASR from the System Management Homepage or through RBSU.

USB support

HP provides both standard USB 2.0 support and legacy USB 2.0 support. Standard support is provided by the OS through the appropriate USB device drivers. Before the OS loads, HP provides support for USB devices through legacy USB support, which is enabled by default in the system ROM.

Legacy USB support provides USB functionality in environments where USB support is not available normally. Specifically, HP provides legacy USB functionality for the following:

- POST
- RBSU
- Diagnostics
- DOS
- Operating environments which do not provide native USB support

Redundant ROM support

The server enables you to upgrade or configure the ROM safely with redundant ROM support. The server has a single ROM that acts as two separate ROM images. In the standard implementation, one side of the ROM contains the current ROM program version, while the other side of the ROM contains a backup version.

NOTE: The server ships with the same version programmed on each side of the ROM.

Safety and security benefits

When you flash the system ROM, ROMPaq writes over the backup ROM and saves the current ROM as a backup, enabling you to switch easily to the alternate ROM version if the new ROM becomes corrupted for any reason. This feature protects the existing ROM version, even if you experience a power failure while flashing the ROM.

Keeping the system current

Drivers



IMPORTANT: Always perform a backup before installing or updating device drivers.

The server includes new hardware that may not have driver support on all OS installation media.

If you are installing an Intelligent Provisioning-supported OS, use Intelligent Provisioning (on page 73) and its Configure and Install feature to install the OS and latest supported drivers.

If you do not use Intelligent Provisioning to install an OS, drivers for some of the new hardware are required. These drivers, as well as other option drivers, ROM images, and value-add software can be downloaded as part of an SPP.

If you are installing drivers from SPP, be sure that you are using the latest SPP version that your server supports. To verify that your server is using the latest supported version and for more information about SPP, see the HP website (<http://www.hp.com/go/spp/download>).

To directly locate the OS drivers for a particular server, enter the following web address into the browser:

<http://www.hp.com/support/<servername>>

In place of <servername>, enter the server name.

For example:

<http://www.hp.com/support/dl360g6>

Software and firmware

Software and firmware should be updated before using the server for the first time, unless any installed software or components require an older version. For system software and firmware updates, download the SPP ("HP Service Pack for ProLiant" on page 75) from the HP website (<http://www.hp.com/go/spp>).

Version control

The VCRM and VCA are web-enabled Insight Management Agents tools that HP SIM uses to schedule software update tasks to the entire enterprise.

- VCRM manages the repository for SPP. Administrators can view the SPP contents or configure VCRM to automatically update the repository with internet downloads of the latest software and firmware from HP.
- VCA compares installed software versions on the node with updates available in the VCRM managed repository. Administrators configure VCA to point to a repository managed by VCRM.

For more information about version control tools, see the *HP Systems Insight Manager User Guide*, the *HP Version Control Agent User Guide*, and the *HP Version Control Repository User Guide* on the HP website (<http://www.hp.com/go/hpsim>).

HP Operating Systems and Virtualization Software Support for ProLiant Servers

For information about specific versions of a supported operating system, see the HP website (<http://www.hp.com/go/ossupport>).

HP Technology Service Portfolio

HP Technology Services offers a targeted set of consultancy, deployment, and service solutions designed to meet the support needs of the most business and IT environments.

Foundation Care services deliver scalable hardware and software support packages for HP ProLiant server and industry-standard software. You can choose the type and level of service that is most suitable for your business needs.

HP Collaborative Support — With a single call, HP addresses initial hardware and software support needs and helps to quickly identify if a problem is related to hardware or software. If the problem is identified as hardware, HP will resolve as per service level commitments. If the reported incident is related to HP or supported 3rd party software product and cannot be resolved by applying known fixes, HP will contact the third-party vendor and create a problem incident on the your behalf.

HP Proactive Care — For customers running business critical environments where down time is not an option, then HP Proactive Care helps to deliver high levels of application availability. Key to these service options is the delivery of proactive service management offers to help you avoid the causes of down time. If a problems arises than HP offers advanced technical response from critical system support specialist for fast problem identification and resolution.

HP Support Center — All service options include HP Support Center delivering information, tools, and experts required to support HP business products.

HP Insight Remote Support — Provides 24x7 secure remote monitoring, diagnosis and problem resolution.

For more information, see the HP website (<http://www.hp.com/services/proliant>) or the HP website for the HP BladeSystem (<http://www.hp.com/services/bladesystem>).

Change control and proactive notification

HP offers Change Control and Proactive Notification to notify customers 30 to 60 days in advance of upcoming hardware and software changes on HP commercial products.

For more information, refer to the HP website (<http://www.hp.com/go/pcn>).

Troubleshooting

Troubleshooting resources

The *HP ProLiant Gen8 Troubleshooting Guide, Volume I: Troubleshooting* provides procedures for resolving common problems and comprehensive courses of action for fault isolation and identification, issue resolution, and software maintenance on ProLiant servers and server blades. To view the guide, select a language:

- English (http://www.hp.com/support/ProLiant_TSG_v1_en)
- French (http://www.hp.com/support/ProLiant_TSG_v1_fr)
- Spanish (http://www.hp.com/support/ProLiant_TSG_v1_sp)
- German (http://www.hp.com/support/ProLiant_TSG_v1_gr)
- Japanese (http://www.hp.com/support/ProLiant_TSG_v1_jp)
- Simplified Chinese (http://www.hp.com/support/ProLiant_TSG_v1_sc)

The *HP ProLiant Gen8 Troubleshooting Guide, Volume II: Error Messages* provides a list of error messages and information to assist with interpreting and resolving error messages on ProLiant servers and server blades. To view the guide, select a language:

- English (http://www.hp.com/support/ProLiant_EMG_v1_en)
- French (http://www.hp.com/support/ProLiant_EMG_v1_fr)
- Spanish (http://www.hp.com/support/ProLiant_EMG_v1_sp)
- German (http://www.hp.com/support/ProLiant_EMG_v1_gr)
- Japanese (http://www.hp.com/support/ProLiant_EMG_v1_jp)
- Simplified Chinese (http://www.hp.com/support/ProLiant_EMG_v1_sc)

System battery

If the server no longer automatically displays the correct date and time, you may need to replace the battery that provides power to the real-time clock. Under normal use, battery life is 5 to 10 years.

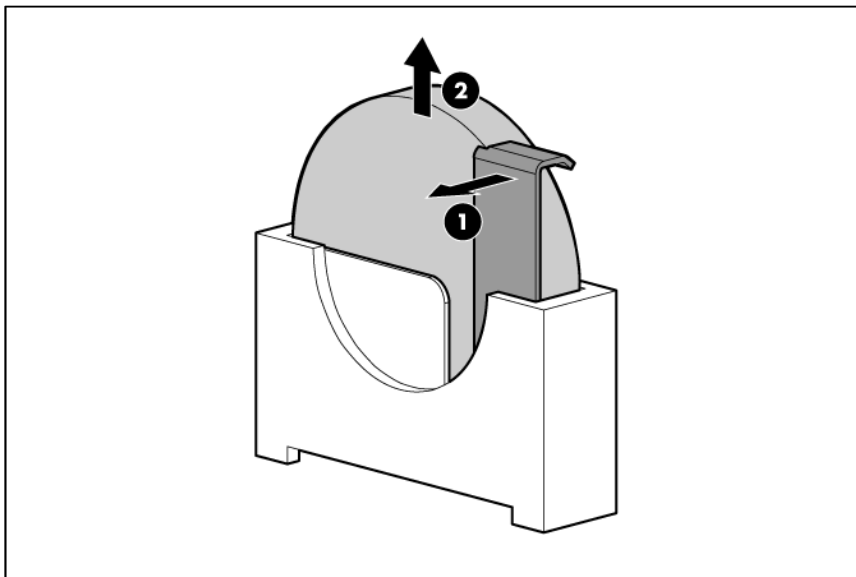


WARNING: The computer contains an internal lithium manganese dioxide, a vanadium pentoxide, or an alkaline battery pack. A risk of fire and burns exists if the battery pack is not properly handled. To reduce the risk of personal injury:

- Do not attempt to recharge the battery.
- Do not expose the battery to temperatures higher than 60°C (140°F).
- Do not disassemble, crush, puncture, short external contacts, or dispose of in fire or water.
- Replace only with the spare designated for this product.

To remove the component:

1. If installed, remove the rack bezel (on page 59).
2. Power down the server (on page 17).
3. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
4. Extend the server from the rack (on page 17).
5. Remove the access panel (on page 19).
6. Remove the processor air baffle (on page 19).
7. If installed, remove the FBWC capacitor pack.
8. Locate the battery on the system board ("[System board components](#)" on page 11).
9. Remove the battery.





IMPORTANT: Replacing the system board battery resets the system ROM to its default configuration. After replacing the battery, reconfigure the system through RBSU.

To replace the component, reverse the removal procedure.

For more information about battery replacement or proper disposal, contact an authorized reseller or an authorized service provider.

Regulatory compliance notices

Regulatory compliance identification numbers

For the purpose of regulatory compliance certifications and identification, this product has been assigned a unique regulatory model number. The regulatory model number can be found on the product nameplate label, along with all required approval markings and information. When requesting compliance information for this product, always refer to this regulatory model number. The regulatory model number is not the marketing name or model number of the product.

Federal Communications Commission notice

Part 15 of the Federal Communications Commission (FCC) Rules and Regulations has established Radio Frequency (RF) emission limits to provide an interference-free radio frequency spectrum. Many electronic devices, including computers, generate RF energy incidental to their intended function and are, therefore, covered by these rules. These rules place computers and related peripheral devices into two classes, A and B, depending upon their intended installation. Class A devices are those that may reasonably be expected to be installed in a business or commercial environment. Class B devices are those that may reasonably be expected to be installed in a residential environment (for example, personal computers). The FCC requires devices in both classes to bear a label indicating the interference potential of the device as well as additional operating instructions for the user.

FCC rating label

The FCC rating label on the device shows the classification (A or B) of the equipment. Class B devices have an FCC logo or ID on the label. Class A devices do not have an FCC logo or ID on the label. After you determine the class of the device, refer to the corresponding statement.

FCC Notice, Class A Equipment

This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to Part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a commercial environment. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. Operation of this equipment in a residential area is likely to cause harmful interference, in which case the user will be required to correct the interference at personal expense.

FCC Notice, Class B Equipment

This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to Part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to

radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit that is different from that to which the receiver is connected.
- Consult the dealer or an experienced radio or television technician for help.

Declaration of conformity for products marked with the FCC logo, United States only

This device complies with Part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) this device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

For questions regarding this product, contact us by mail or telephone:

- Hewlett-Packard Company
P. O. Box 692000, Mail Stop 530113
Houston, Texas 77269-2000
- 1-800-HP-INVENT (1-800-474-6836). (For continuous quality improvement, calls may be recorded or monitored.)

For questions regarding this FCC declaration, contact us by mail or telephone:

- Hewlett-Packard Company
P. O. Box 692000, Mail Stop 510101
Houston, Texas 77269-2000
- 1-281-514-3333

To identify this product, refer to the part, series, or model number found on the product.

Modifications

The FCC requires the user to be notified that any changes or modifications made to this device that are not expressly approved by Hewlett-Packard Company may void the user's authority to operate the equipment.

Cables

Connections to this device must be made with shielded cables with metallic RFI/EMI connector hoods in order to maintain compliance with FCC Rules and Regulations.

Canadian notice (Avis Canadien)

Class A equipment

This Class A digital apparatus meets all requirements of the Canadian Interference-Causing Equipment Regulations.

Cet appareil numérique de la classe A respecte toutes les exigences du Règlement sur le matériel brouilleur du Canada.

Class B equipment

This Class B digital apparatus meets all requirements of the Canadian Interference-Causing Equipment Regulations.

Cet appareil numérique de la classe B respecte toutes les exigences du Règlement sur le matériel brouilleur du Canada.

European Union regulatory notice

Products bearing the CE marking comply with the following EU Directives:

- Low Voltage Directive 2006/95/EC
- EMC Directive 2004/108/EC
- Ecodesign Directive 2009/125/EC, where applicable

CE compliance of this product is valid if powered with the correct CE-marked AC adapter provided by HP.

Compliance with these directives implies conformity to applicable harmonized European standards (European Norms) that are listed in the EU Declaration of Conformity issued by HP for this product or product family and available (in English only) either within the product documentation or at the following HP website (<http://www.hp.eu/certificates>) (type the product number in the search field).

The compliance is indicated by one of the following conformity markings placed on the product:

For non-telecommunications products and for EU harmonized telecommunications products, such as Bluetooth® within power class below 10mW.



For EU non-harmonized telecommunications products (If applicable, a 4-digit notified body number is inserted between CE and !).



Please refer to the regulatory label provided on the product.

The point of contact for regulatory matters is Hewlett-Packard GmbH, Dept./MS: HQ-TRE, Herrenberger Strasse 140, 71034 Boeblingen, GERMANY.

Disposal of waste equipment by users in private households in the European Union



This symbol on the product or on its packaging indicates that this product must not be disposed of with your other household waste. Instead, it is your responsibility to dispose of your waste equipment by handing it over to a designated collection point for the recycling of waste electrical and electronic equipment. The separate collection and recycling of your waste equipment at the time of disposal will help to conserve natural resources and ensure that it is recycled in a manner that protects human health and the environment. For more information about where you can drop off your waste equipment for recycling, please contact your local city office, your household waste disposal service or the shop where you purchased the product.

Japanese notice

ご使用になっている装置に VCCI マークが付いていましたら、次の説明文をお読み下さい。

この装置は、クラス B 情報技術装置です。この装置は、家庭環境で使用することを目的としています。この装置がラジオやテレビジョン受信機に近接して使用されると、受信障害を引き起こすことがあります。取扱説明書に従って正しい取り扱いをして下さい。

VCCI-B

VCCI マークが付いていない場合には、次の点にご注意下さい。

この装置は、クラス A 情報技術装置です。この装置を家庭環境で使用すると電波妨害を引き起こすことがあります。この場合には使用者は適切な対策を講ずるよう要求されることがあります。

VCCI-A

BSMI notice

警告使用者:

這是甲類的資訊產品，在居住的環境中使用時，可能會造成射頻干擾，在這種情況下，使用者會被要求採取某些適當的對策。

Korean notice

Class A equipment

A급 기기 (업무용 방송통신기기)	이 기기는 업무용(A급)으로 전자파적합등록을 한 기기이오니 판매자 또는 사용자는 이 점을 주의하시기 바라며, 가정 외의 지역에서 사용하는 것을 목적으로 합니다.
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Class B equipment

B급 기기 (가정용 방송통신기기)	이 기기는 가정용(B급)으로 전자파적합등록을 한 기기로서 주로 가정에서 사용하는 것을 목적으로 하며, 모든 지역에서 사용할 수 있습니다.
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Chinese notice

Class A equipment

声明

此为 A 级产品，在生活环境中，该产品可能会造成无线电干扰。在这种情况下，可能需要用户对其干扰采取可行的措施。

Vietnam compliance marking notice

This marking is for applicable products only.



Ukraine notice

Україна Додаток до документації користувача

Обладнання відповідає вимогам Технічного регламенту щодо обмеження використання деяких небезпечних речовин в електричному та електронному обладнанні, затвердженого постановою Кабінету Міністрів України від 3 грудня 2008 № 1057

Збережіть цей документ разом із документацією користувача для цього виробу

Laser compliance

This product may be provided with an optical storage device (that is, CD or DVD drive) and/or fiber optic transceiver. Each of these devices contains a laser that is classified as a Class 1 Laser Product in accordance with US FDA regulations and the IEC 60825-1. The product does not emit hazardous laser radiation.

Each laser product complies with 21 CFR 1040.10 and 1040.11 except for deviations pursuant to Laser Notice No. 50, dated June 24, 2007; and with IEC 60825-1:2007.



WARNING: Use of controls or adjustments or performance of procedures other than those specified herein or in the laser product's installation guide may result in hazardous radiation exposure. To reduce the risk of exposure to hazardous radiation:

- Do not try to open the module enclosure. There are no user-serviceable components inside.
- Do not operate controls, make adjustments, or perform procedures to the laser device other than those specified herein.
- Allow only HP Authorized Service technicians to repair the unit.

The Center for Devices and Radiological Health (CDRH) of the U.S. Food and Drug Administration implemented regulations for laser products on August 2, 1976. These regulations apply to laser products manufactured from August 1, 1976. Compliance is mandatory for products marketed in the United States.

Battery replacement notice



WARNING: The computer contains an internal lithium manganese dioxide, a vanadium pentoxide, or an alkaline battery pack. A risk of fire and burns exists if the battery pack is not properly handled. To reduce the risk of personal injury:

- Do not attempt to recharge the battery.
- Do not expose the battery to temperatures higher than 60°C (140°F).
- Do not disassemble, crush, puncture, short external contacts, or dispose of in fire or water.

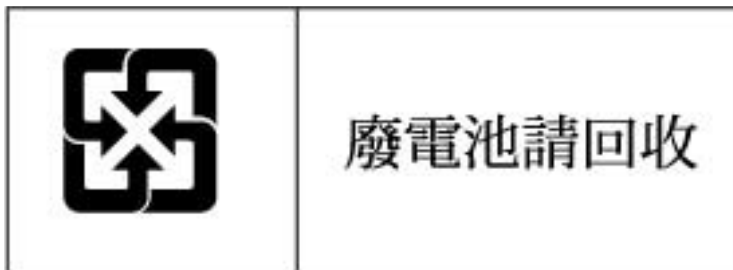


Batteries, battery packs, and accumulators should not be disposed of together with the general household waste. To forward them to recycling or proper disposal, use the public collection system or return them to HP, an authorized HP Partner, or their agents.

For more information about battery replacement or proper disposal, contact an authorized reseller or an authorized service provider.

Taiwan battery recycling notice

The Taiwan EPA requires dry battery manufacturing or importing firms in accordance with Article 15 of the Waste Disposal Act to indicate the recovery marks on the batteries used in sales, giveaway or promotion. Contact a qualified Taiwanese recycler for proper battery disposal.



Power cord statement for Japan

製品には、同梱された電源コードをお使い下さい。
同梱された電源コードは、他の製品では使用出来ません。

Acoustics statement for Germany (Geräuschemission)

Schalldruckpegel $L_{pA} < 70$ dB(A)

Zuschauerpositionen (bystander positions), Normaler Betrieb (normal operation)

Nach ISO 7779:1999 (Typprüfung)

Electrostatic discharge

Preventing electrostatic discharge

To prevent damaging the system, be aware of the precautions you need to follow when setting up the system or handling parts. A discharge of static electricity from a finger or other conductor may damage system boards or other static-sensitive devices. This type of damage may reduce the life expectancy of the device.

To prevent electrostatic damage:

- Avoid hand contact by transporting and storing products in static-safe containers.
- Keep electrostatic-sensitive parts in their containers until they arrive at static-free workstations.
- Place parts on a grounded surface before removing them from their containers.
- Avoid touching pins, leads, or circuitry.
- Always be properly grounded when touching a static-sensitive component or assembly.

Grounding methods to prevent electrostatic discharge

Several methods are used for grounding. Use one or more of the following methods when handling or installing electrostatic-sensitive parts:

- Use a wrist strap connected by a ground cord to a grounded workstation or computer chassis. Wrist straps are flexible straps with a minimum of 1 megohm ± 10 percent resistance in the ground cords. To provide proper ground, wear the strap snug against the skin.
- Use heel straps, toe straps, or boot straps at standing workstations. Wear the straps on both feet when standing on conductive floors or dissipating floor mats.
- Use conductive field service tools.
- Use a portable field service kit with a folding static-dissipating work mat.

If you do not have any of the suggested equipment for proper grounding, have an authorized reseller install the part.

For more information on static electricity or assistance with product installation, contact an authorized reseller.

Specifications

Environmental specifications

Specification	Value
Temperature range*	
Operating	10°C to 35°C (50°F to 95°F)
Shipping	-40°C to 70°C (-40°F to 158°F)
Maximum wet bulb temperature	28°C (82.4°F)
Relative humidity (noncondensing)**	
Operating	10% to 90%
Non-operating	5% to 95%

* All temperature ratings shown are for sea level. An altitude derating of 1°C per 300 m (1.8°F per 1,000 ft) to 3048 m (10,000 ft) is applicable. No direct sunlight allowed.

** Storage maximum humidity of 95% is based on a maximum temperature of 45°C (113°F). Altitude maximum for storage corresponds to a pressure minimum of 70 kPa.

Server specifications

Specification	Value
Height	4.32 cm (1.70 in)
Depth (chassis with SFF drive cage)	69.9 cm (27.5 in)
Depth (chassis with LFF drive cage)	75.0 cm (29.5 in)
Width	43.46 cm (17.11 in)
Weight (maximum SFF: two processors, one power supply, eight drives)	16.9 kg (37.25 lb)
Weight (maximum LFF: two processors, one power supply, four drives)	17.6 kg (38.80 lb)

Power supply specifications

Depending on installed options, the server is configured with one of the following power supplies:

- HP 460 W CS Power Supply (94%) specifications
- HP 750 W CS Power Supply (94%) specifications
- HP 500 W Multi-output Power Supply specifications

HP 460 W CS Power Supply (94%) specifications

Specification	Value
Input requirements	
Rated input voltage	100 to 240 VAC
Rated input frequency	50 Hz or 60 Hz
Rated input current	6 to 3 A
Rated input power	509 W at 115V AC input 495 W at 230V AC input
BTUs per hour	1764 at 100V AC 1736 at 115V AC 1694 at 200V AC 1687 at 230V AC
Power supply output	
Rated steady-state power	460 W at 100V to 120V AC input 460 W at 200V to 240V AC input
Maximum peak power	460 W at 100V to 120V AC input 460 W at 200V to 240V AC input


HP 750 W CS Power Supply (94%) specifications


Specification	Value
Input requirements	
Rated input voltage	100 to 240 VAC
Rated input frequency	50 Hz to 60 Hz
Rated input current	9 to 4.5 A
Maximum rated input power	831 W at 115 V AC input 808 W at 230V AC input
BTUs per hour	2878 at 100 V AC 2834 at 115 V AC 2769 at 200 V AC 2758 at 230 V AC
Power supply output	
Rated steady-state power	750 W at 100V to 120V AC input 750 W at 200V to 240V AC input
Maximum peak power	750 W at 100V to 120V AC input 750 W at 200V to 240V AC input

HP 500 W Multi-output Power Supply specifications


Specification	Value
Input requirements	
Rated input voltage	100 to 120 VAC, 200 to 240 VAC
Rated input frequency	47 HZ to 63 HZ

Rated input current	10 A to 5 A
Rated input power	556 W at 115V AC input 542 W at 230V AC input
BTUs per hour	1917 at 100 V AC 1898 at 115 V AC 1856 at 200 V AC 1850 at 230 V AC
Power supply output	
Rated steady-state power	500 W at 100V to 120V AC input 500 W at 200V to 240V AC input
Maximum peak power	500 W at 100V to 120V AC input 500 W at 200V to 240V AC input

 **CAUTION:** This equipment is designed to permit the connection of the earthed conductor of the DC supply circuit to the earthing conductor at the equipment. See installation instructions.

 **CAUTION:** If the DC connection between the earthed conductor of the DC supply circuit and the earthing conductor at the server equipment, the following conditions must be met:

- This equipment must be connected directly to the DC supply system earthing electrode conductor or to a bonding jumper from an earthing terminal bar or bus to which the DC supply system earthing electrode conductor is connected.
- This equipment should be located in the same immediate area (such as adjacent cabinets) as any other equipment that has a connection between the earthed conductor of the same DC supply circuit and the earthing conductor, and also the point of earthing of the DC system. The DC system should be earthed elsewhere.
- The DC supply source is to be located within the same premises as the equipment.
- Switching or disconnecting devices should not be in the earthed circuit conductor between the DC source and the point of connection of the earthing electrode conductor.

 **CAUTION:** To reduce the risk of electric shock or energy hazards:

- This equipment must be installed by trained service personnel, as defined by the NEC and IEC 60950-1, Second Edition, the standard for Safety of Information Technology Equipment.
- Connect the equipment to a reliably grounded safety extra low voltage (SELV) source. An SELV source is a secondary circuit that is designed so normal and single fault conditions do not cause the voltages to exceed a safe level (60 V direct current).
- The branch circuit overcurrent protection must be rated 20A.

Power supply calculations

For power supply specifications and calculators to determine electrical and heat loading for the server, refer to the HP Enterprise Configurator website (<http://h30099.www3.hp.com/configurator/>).

Technical support

Before you contact HP

Be sure to have the following information available before you call HP:

- Active Health System log
Download and have available an Active Health System log for 3 days before the failure was detected. For more information, see the *HP iLO 4 User Guide* or *HP Intelligent Provisioning User Guide* on the HP website (<http://www.hp.com/go/ilo/docs>).
- Onboard Administrator SHOW ALL report (for HP BladeSystem products only)
For more information on obtaining the Onboard Administrator SHOW ALL report, see the HP website (<http://h20000.www2.hp.com/bizsupport/TechSupport/Document.jsp?lang=en&cc=us&objectID=c02843807>).
- Technical support registration number (if applicable)
- Product serial number
- Product model name and number
- Product identification number
- Applicable error messages
- Add-on boards or hardware
- Third-party hardware or software
- Operating system type and revision level

HP contact information

For United States and worldwide contact information, see the Contact HP website (<http://www.hp.com/go/assistance>).

In the United States:

- To contact HP by phone, call 1-800-334-5144. For continuous quality improvement, calls may be recorded or monitored.
- If you have purchased a Care Pack (service upgrade), see the Support & Drivers website (<http://www8.hp.com/us/en/support-drivers.html>). If the problem cannot be resolved at the website, call 1-800-633-3600. For more information about Care Packs, see the HP website (<http://pro-aq-sama.houston.hp.com/services/cache/10950-0-0-225-121.html>).

Customer Self Repair

HP products are designed with many Customer Self Repair (CSR) parts to minimize repair time and allow for greater flexibility in performing defective parts replacement. If during the diagnosis period HP (or HP service

providers or service partners) identifies that the repair can be accomplished by the use of a CSR part, HP will ship that part directly to you for replacement. There are two categories of CSR parts:

- **Mandatory**—Parts for which customer self repair is mandatory. If you request HP to replace these parts, you will be charged for the travel and labor costs of this service.
- **Optional**—Parts for which customer self repair is optional. These parts are also designed for customer self repair. If, however, you require that HP replace them for you, there may or may not be additional charges, depending on the type of warranty service designated for your product.

NOTE: Some HP parts are not designed for customer self repair. In order to satisfy the customer warranty, HP requires that an authorized service provider replace the part. These parts are identified as "No" in the Illustrated Parts Catalog.

Based on availability and where geography permits, CSR parts will be shipped for next business day delivery. Same day or four-hour delivery may be offered at an additional charge where geography permits. If assistance is required, you can call the HP Technical Support Center and a technician will help you over the telephone. HP specifies in the materials shipped with a replacement CSR part whether a defective part must be returned to HP. In cases where it is required to return the defective part to HP, you must ship the defective part back to HP within a defined period of time, normally five (5) business days. The defective part must be returned with the associated documentation in the provided shipping material. Failure to return the defective part may result in HP billing you for the replacement. With a customer self repair, HP will pay all shipping and part return costs and determine the courier/carrier to be used.

For more information about HP's Customer Self Repair program, contact your local service provider. For the North American program, refer to the HP website (<http://www.hp.com/go/selfrepair>).

Réparation par le client (CSR)

Les produits HP comportent de nombreuses pièces CSR (Customer Self Repair = réparation par le client) afin de minimiser les délais de réparation et faciliter le remplacement des pièces défectueuses. Si pendant la période de diagnostic, HP (ou ses partenaires ou mainteneurs agréés) détermine que la réparation peut être effectuée à l'aide d'une pièce CSR, HP vous l'envoie directement. Il existe deux catégories de pièces CSR:

Obligatoire - Pièces pour lesquelles la réparation par le client est obligatoire. Si vous demandez à HP de remplacer ces pièces, les coûts de déplacement et main d'œuvre du service vous seront facturés.

Facultatif - Pièces pour lesquelles la réparation par le client est facultative. Ces pièces sont également conçues pour permettre au client d'effectuer lui-même la réparation. Toutefois, si vous demandez à HP de remplacer ces pièces, l'intervention peut ou non vous être facturée, selon le type de garantie applicable à votre produit.

REMARQUE: Certaines pièces HP ne sont pas conçues pour permettre au client d'effectuer lui-même la réparation. Pour que la garantie puisse s'appliquer, HP exige que le remplacement de la pièce soit effectué par un Mainteneur Agréé. Ces pièces sont identifiées par la mention "Non" dans le Catalogue illustré.

Les pièces CSR sont livrées le jour ouvré suivant, dans la limite des stocks disponibles et selon votre situation géographique. Si votre situation géographique le permet et que vous demandez une livraison le jour même ou dans les 4 heures, celle-ci vous sera facturée. Pour bénéficier d'une assistance téléphonique, appelez le Centre d'assistance technique HP. Dans les documents envoyés avec la pièce de rechange CSR, HP précise s'il est nécessaire de lui retourner la pièce défectueuse. Si c'est le cas, vous devez le faire dans le délai indiqué, généralement cinq (5) jours ouvrés. La pièce et sa documentation doivent être retournées dans l'emballage fourni. Si vous ne retournez pas la pièce défectueuse, HP se réserve le droit de vous facturer les coûts de remplacement. Dans le cas d'une pièce CSR, HP supporte l'ensemble des frais d'expédition et de retour, et détermine la société de courses ou le transporteur à utiliser.

Pour plus d'informations sur le programme CSR de HP, contactez votre Mainteneur Agrée local. Pour plus d'informations sur ce programme en Amérique du Nord, consultez le site Web HP (<http://www.hp.com/go/selfrepair>).

Riparazione da parte del cliente

Per abbreviare i tempi di riparazione e garantire una maggiore flessibilità nella sostituzione di parti difettose, i prodotti HP sono realizzati con numerosi componenti che possono essere riparati direttamente dal cliente (CSR, Customer Self Repair). Se in fase di diagnostica HP (o un centro di servizi o di assistenza HP) identifica il guasto come riparabile mediante un ricambio CSR, HP lo spedisce direttamente al cliente per la sostituzione. Vi sono due categorie di parti CSR:

Obbligatorie – Parti che devono essere necessariamente riparate dal cliente. Se il cliente ne affida la riparazione ad HP, deve sostenere le spese di spedizione e di manodopera per il servizio.

Opzionali – Parti la cui riparazione da parte del cliente è facoltativa. Si tratta comunque di componenti progettati per questo scopo. Se tuttavia il cliente ne richiede la sostituzione ad HP, potrebbe dover sostenere spese aggiuntive a seconda del tipo di garanzia previsto per il prodotto.

NOTA: alcuni componenti HP non sono progettati per la riparazione da parte del cliente. Per rispettare la garanzia, HP richiede che queste parti siano sostituite da un centro di assistenza autorizzato. Tali parti sono identificate da un "No" nel Catalogo illustrato dei componenti.

In base alla disponibilità e alla località geografica, le parti CSR vengono spedite con consegna entro il giorno lavorativo seguente. La consegna nel giorno stesso o entro quattro ore è offerta con un supplemento di costo solo in alcune zone. In caso di necessità si può richiedere l'assistenza telefonica di un addetto del centro di supporto tecnico HP. Nel materiale fornito con una parte di ricambio CSR, HP specifica se il cliente deve restituire dei componenti. Qualora sia richiesta la resa ad HP del componente difettoso, lo si deve spedire ad HP entro un determinato periodo di tempo, generalmente cinque (5) giorni lavorativi. Il componente difettoso deve essere restituito con la documentazione associata nell'imballo di spedizione fornito. La mancata restituzione del componente può comportare la fatturazione del ricambio da parte di HP. Nel caso di riparazione da parte del cliente, HP sostiene tutte le spese di spedizione e resa e sceglie il corriere/vettore da utilizzare.

Per ulteriori informazioni sul programma CSR di HP contattare il centro di assistenza di zona. Per il programma in Nord America fare riferimento al sito Web HP (<http://www.hp.com/go/selfrepair>).

Customer Self Repair

HP Produkte enthalten viele CSR-Teile (Customer Self Repair), um Reparaturzeiten zu minimieren und höhere Flexibilität beim Austausch defekter Bauteile zu ermöglichen. Wenn HP (oder ein HP Servicepartner) bei der Diagnose feststellt, dass das Produkt mithilfe eines CSR-Teils repariert werden kann, sendet Ihnen HP dieses Bauteil zum Austausch direkt zu. CSR-Teile werden in zwei Kategorien unterteilt:

Zwingend – Teile, für die das Customer Self Repair-Verfahren zwingend vorgegeben ist. Wenn Sie den Austausch dieser Teile von HP vornehmen lassen, werden Ihnen die Anfahrt- und Arbeitskosten für diesen Service berechnet.

Optional – Teile, für die das Customer Self Repair-Verfahren optional ist. Diese Teile sind auch für Customer Self Repair ausgelegt. Wenn Sie jedoch den Austausch dieser Teile von HP vornehmen lassen möchten, können bei diesem Service je nach den für Ihr Produkt vorgesehenen Garantiebedingungen zusätzliche Kosten anfallen.

HINWEIS: Einige Teile sind nicht für Customer Self Repair ausgelegt. Um den Garantieanspruch des Kunden zu erfüllen, muss das Teil von einem HP Servicepartner ersetzt werden. Im illustrierten Teilekatalog sind diese Teile mit „No“ bzw. „Nein“ gekennzeichnet.

CSR-Teile werden abhängig von der Verfügbarkeit und vom Lieferziel am folgenden Geschäftstag geliefert. Für bestimmte Standorte ist eine Lieferung am selben Tag oder innerhalb von vier Stunden gegen einen Aufpreis verfügbar. Wenn Sie Hilfe benötigen, können Sie das HP technische Support Center anrufen und sich von einem Mitarbeiter per Telefon helfen lassen. Den Materialien, die mit einem CSR-Ersatzteil geliefert werden, können Sie entnehmen, ob das defekte Teil an HP zurückgeschickt werden muss. Wenn es erforderlich ist, das defekte Teil an HP zurückzuschicken, müssen Sie dies innerhalb eines vorgegebenen Zeitraums tun, in der Regel innerhalb von fünf (5) Geschäftstagen. Das defekte Teil muss mit der zugehörigen Dokumentation in der Verpackung zurückgeschickt werden, die im Lieferumfang enthalten ist. Wenn Sie das defekte Teil nicht zurückschicken, kann HP Ihnen das Ersatzteil in Rechnung stellen. Im Falle von Customer Self Repair kommt HP für alle Kosten für die Lieferung und Rücksendung auf und bestimmt den Kurier-/Frachtdienst.

Weitere Informationen über das HP Customer Self Repair Programm erhalten Sie von Ihrem Servicepartner vor Ort. Informationen über das CSR-Programm in Nordamerika finden Sie auf der HP Website unter (<http://www.hp.com/go/selfrepair>).

Reparaciones del propio cliente

Los productos de HP incluyen muchos componentes que el propio usuario puede reemplazar (*Customer Self Repair*, CSR) para minimizar el tiempo de reparación y ofrecer una mayor flexibilidad a la hora de realizar sustituciones de componentes defectuosos. Si, durante la fase de diagnóstico, HP (o los proveedores o socios de servicio de HP) identifica que una reparación puede llevarse a cabo mediante el uso de un componente CSR, HP le enviará dicho componente directamente para que realice su sustitución. Los componentes CSR se clasifican en dos categorías:

- **Obligatorio:** componentes para los que la reparación por parte del usuario es obligatoria. Si solicita a HP que realice la sustitución de estos componentes, tendrá que hacerse cargo de los gastos de desplazamiento y de mano de obra de dicho servicio.
- **Opcional:** componentes para los que la reparación por parte del usuario es opcional. Estos componentes también están diseñados para que puedan ser reparados por el usuario. Sin embargo, si precisa que HP realice su sustitución, puede o no conllevar costes adicionales, dependiendo del tipo de servicio de garantía correspondiente al producto.

NOTA: Algunos componentes no están diseñados para que puedan ser reparados por el usuario. Para que el usuario haga valer su garantía, HP pone como condición que un proveedor de servicios autorizado realice la sustitución de estos componentes. Dichos componentes se identifican con la palabra "No" en el catálogo ilustrado de componentes.

Según la disponibilidad y la situación geográfica, los componentes CSR se enviarán para que lleguen a su destino al siguiente día laborable. Si la situación geográfica lo permite, se puede solicitar la entrega en el mismo día o en cuatro horas con un coste adicional. Si precisa asistencia técnica, puede llamar al Centro de asistencia técnica de HP y recibirá ayuda telefónica por parte de un técnico. Con el envío de materiales para la sustitución de componentes CSR, HP especificará si los componentes defectuosos deberán devolverse a HP. En aquellos casos en los que sea necesario devolver algún componente a HP, deberá hacerlo en el periodo de tiempo especificado, normalmente cinco días laborables. Los componentes defectuosos deberán devolverse con toda la documentación relacionada y con el embalaje de envío. Si no enviara el componente defectuoso requerido, HP podrá cobrarle por el de sustitución. En el caso de todas

sustituciones que lleve a cabo el cliente, HP se hará cargo de todos los gastos de envío y devolución de componentes y escogerá la empresa de transporte que se utilice para dicho servicio.

Para obtener más información acerca del programa de Reparaciones del propio cliente de HP, póngase en contacto con su proveedor de servicios local. Si está interesado en el programa para Norteamérica, visite la página web de HP siguiente (<http://www.hp.com/go/selfrepair>).

Customer Self Repair

Veel onderdelen in HP producten zijn door de klant zelf te repareren, waardoor de reparatieduur tot een minimum beperkt kan blijven en de flexibiliteit in het vervangen van defecte onderdelen groter is. Deze onderdelen worden CSR-onderdelen (Customer Self Repair) genoemd. Als HP (of een HP Service Partner) bij de diagnose vaststelt dat de reparatie kan worden uitgevoerd met een CSR-onderdeel, verzendt HP dat onderdeel rechtstreeks naar u, zodat u het defecte onderdeel daarmee kunt vervangen. Er zijn twee categorieën CSR-onderdelen:

Verplicht: Onderdelen waarvoor reparatie door de klant verplicht is. Als u HP verzoekt deze onderdelen voor u te vervangen, worden u voor deze service reiskosten en arbeidsloon in rekening gebracht.

Optioneel: Onderdelen waarvoor reparatie door de klant optioneel is. Ook deze onderdelen zijn ontworpen voor reparatie door de klant. Als u echter HP verzoekt deze onderdelen voor u te vervangen, kunnen daarvoor extra kosten in rekening worden gebracht, afhankelijk van het type garanteservice voor het product.

OPMERKING: Sommige HP onderdelen zijn niet ontwikkeld voor reparatie door de klant. In verband met de garantievoorwaarden moet het onderdeel door een geautoriseerde Service Partner worden vervangen. Deze onderdelen worden in de geïllustreerde onderdelencatalogus aangemerkt met "Nee".

Afhankelijk van de leverbaarheid en de locatie worden CSR-onderdelen verzonden voor levering op de eerstvolgende werkdag. Levering op dezelfde dag of binnen vier uur kan tegen meerkosten worden aangeboden, indien dit mogelijk is gezien de locatie. Indien assistentie gewenst is, belt u een HP Service Partner om via de telefoon technische ondersteuning te ontvangen. HP vermeldt in de documentatie bij het vervangende CSR-onderdeel of het defecte onderdeel aan HP moet worden geretourneerd. Als het defecte onderdeel aan HP moet worden teruggezonden, moet u het defecte onderdeel binnen een bepaalde periode, gewoonlijk vijf (5) werkdagen, retourneren aan HP. Het defecte onderdeel moet met de bijbehorende documentatie worden geretourneerd in het meegeleverde verpakkingsmateriaal. Als u het defecte onderdeel niet terugzendt, kan HP u voor het vervangende onderdeel kosten in rekening brengen. Bij reparatie door de klant betaalt HP alle verzendkosten voor het vervangende en geretourneerde onderdeel en kiest HP zelf welke koerier/transportonderneming hiervoor wordt gebruikt.

Neem contact op met een Service Partner voor meer informatie over het Customer Self Repair programma van HP. Informatie over Service Partners vindt u op de HP website (<http://www.hp.com/go/selfrepair>).

Reparo feito pelo cliente

Os produtos da HP são projetados com muitas peças para reparo feito pelo cliente (CSR) de modo a minimizar o tempo de reparo e permitir maior flexibilidade na substituição de peças com defeito. Se, durante o período de diagnóstico, a HP (ou fornecedores/parceiros de serviço da HP) concluir que o reparo pode ser efetuado pelo uso de uma peça CSR, a peça de reposição será enviada diretamente ao cliente. Existem duas categorias de peças CSR:

Obrigatória – Peças cujo reparo feito pelo cliente é obrigatório. Se desejar que a HP substitua essas peças, serão cobradas as despesas de transporte e mão-de-obra do serviço.

Opcional – Peças cujo reparo feito pelo cliente é opcional. Essas peças também são projetadas para o reparo feito pelo cliente. No entanto, se desejar que a HP as substitua, pode haver ou não a cobrança de taxa adicional, dependendo do tipo de serviço de garantia destinado ao produto.

OBSERVAÇÃO: Algumas peças da HP não são projetadas para o reparo feito pelo cliente. A fim de cumprir a garantia do cliente, a HP exige que um técnico autorizado substitua a peça. Essas peças estão identificadas com a marca "No" (Não), no catálogo de peças ilustrado.

Conforme a disponibilidade e o local geográfico, as peças CSR serão enviadas no primeiro dia útil após o pedido. Onde as condições geográficas permitirem, a entrega no mesmo dia ou em quatro horas pode ser feita mediante uma taxa adicional. Se precisar de auxílio, entre em contato com o Centro de suporte técnico da HP para que um técnico o ajude por telefone. A HP especifica nos materiais fornecidos com a peça CSR de reposição se a peça com defeito deve ser devolvida à HP. Nos casos em que isso for necessário, é preciso enviar a peça com defeito à HP dentro do período determinado, normalmente cinco (5) dias úteis. A peça com defeito deve ser enviada com a documentação correspondente no material de transporte fornecido. Caso não o faça, a HP poderá cobrar a reposição. Para as peças de reparo feito pelo cliente, a HP paga todas as despesas de transporte e de devolução da peça e determina a transportadora/serviço postal a ser utilizado.

Para obter mais informações sobre o programa de reparo feito pelo cliente da HP, entre em contato com o fornecedor de serviços local. Para o programa norte-americano, visite o site da HP

(<http://www.hp.com/go/selfrepair>).

顧客自己修理保証サービス

修理時間を短縮し、故障部品の交換における高い柔軟性を確保するために、HP製品には多数の顧客自己修理（CSR）部品があります。診断の際に、CSR部品を使用すれば修理ができるとHP（HPまたはHP正規保守代理店）が判断した場合、HPはその部品を直接、お客様に発送し、お客様に交換していただきます。CSR部品には以下の2通りがあります。

- **必須** - 顧客自己修理が必須の部品。当該部品について、もしもお客様がHPに交換作業を依頼される場合には、その修理サービスに関する交通費および人件費がお客様に請求されます。
- **任意** - 顧客自己修理が任意である部品。この部品も顧客自己修理用です。当該部品について、もしもお客様がHPに交換作業を依頼される場合には、お買い上げの製品に適用される保証サービス内容の範囲内においては、別途費用を負担していただくことなく保証サービスを受けることができます。

注：HP製品の一部の部品は、顧客自己修理用ではありません。製品の保証を継続するためには、HPまたはHP正規保守代理店による交換作業が必須となります。部品カタログには、当該部品が顧客自己修理除外品である旨が記載されています。

部品供給が可能な場合、地域によっては、CSR部品を翌営業日に届くように発送します。また、地域によっては、追加費用を負担いただくことにより同日または4時間以内に届くように発送することも可能な場合があります。サポートが必要なときは、HPの修理受付窓口に電話していただければ、技術者が電話でアドバイスします。交換用のCSR部品または同梱物には、故障部品をHPに返送する必要があるかどうかが表示されています。故障部品をHPに返送する必要がある場合は、指定期限内（通常は5営業日以内）に故障部品をHPに返送してください。故障部品を返送する場合は、届いた時の梱包箱に関連書類とともに入れてください。故障部品を返送しない場合、HPから部品費用が請求されます。顧客自己修理の際には、HPは送料および部品返送費を全額負担し、使用する宅配便会社や運送会社を指定します。

客户自行维修

HP 产品提供许多客户自行维修 (CSR) 部件，以尽可能缩短维修时间和在更换缺陷部件方面提供更大的灵活性。如果在诊断期间 HP（或 HP 服务提供商或服务合作伙伴）确定可以通过使用 CSR 部件完成维修，HP 将直接把该部件发送给您进行更换。有两类 CSR 部件：

- **强制性的** — 要求客户必须自行维修的部件。如果您请求 HP 更换这些部件，则必须为该服务支付差旅费和人工费用。
- **可选的** — 客户可以选择是否自行维修的部件。这些部件也是为客户自行维修设计的。不过，如果您要求 HP 为您更换这些部件，则根据您的产品指定的保修服务类型，HP 可能收取或不再收取任何附加费用。

注：某些 HP 部件的设计并未考虑客户自行维修。为了满足客户保修的需要，HP 要求授权服务提供商更换相关部件。这些部件在部件图解目录中标记为“否”。

CSR 部件将在下一个工作日发运（取决于备货情况和允许的地理范围）。在允许的地理范围内，可在当天或四小时内发运，但要收取额外费用。如果需要帮助，您可以致电 HP 技术支持中心，将会有技术人员通过电话为您提供帮助。HP 会在随更换的 CSR 部件发运的材料中指明是否必须将有缺陷的部件返还给 HP。如果要求您将有缺陷的部件返还给 HP，那么您必须在指定期限内（通常是五 (5) 个工作日）将缺陷部件发给 HP。有缺陷的部件必须随所提供的发运材料中的相关文件一起返还。如果未能送还有缺陷的部件，HP 可能会要求您支付更换费用。客户自行维修时，HP 将承担所有相关运输和部件返回费用，并指定快递商/承运商。

有关 HP 客户自行维修计划的详细信息，请与您当地的服务提供商联系。有关北美地区的计划，请访问 HP 网站 (<http://www.hp.com/go/selfrepair>)。

客戶自行維修

HP 產品設計了許多「客戶自行維修」(CSR) 的零件以減少維修時間，並且使得更換瑕疵零件時能有更大的彈性。如果在診斷期間 HP (或 HP 服務供應商或維修夥伴) 辨認出此項維修工作可以藉由使用 CSR 零件來完成，則 HP 將直接寄送該零件給您作更換。CSR 零件分為兩種類別：

- **強制的** — 客戶自行維修所使用的零件是強制的。如果您要求 HP 更換這些零件，HP 將會向您收取此服務所需的外出費用與勞動成本。
- **選購的** — 客戶自行維修所使用的零件是選購的。這些零件也設計用於客戶自行維修之用。不過，如果您要求 HP 為您更換，則可能需要也可能不需要負擔額外的費用，端視針對此產品指定的保固服務類型而定。

備註：某些 HP 零件沒有消費者可自行維修的設計。為符合客戶保固，HP 需要授權的服務供應商更換零件。這些零件在圖示的零件目錄中，被標示為「否」。

基於材料取得及環境允許的情況下，CSR 零件將於下一個工作日以快遞寄送。在環境的允許下當天或四小時內送達，則可能需要額外的費用。若您需要協助，可致電「HP 技術支援中心」，會有一位技術人員透過電話來協助您。不論損壞的零件是否必須退回，HP 皆會在與 CSR 替換零件一起運送的材料中註明。若要將損壞的零件退回 HP，您必須在指定的一段時間內（通常為五 (5) 個工作天），將損壞的零件寄回 HP。損壞的零件必須與寄送資料中隨附的相關技術文件一併退還。如果無法退還損壞的零件，HP 可能要向您收取替換費用。針對客戶自行維修情形，HP 將負責所有運費及零件退還費用並指定使用何家快遞/貨運公司。

如需 HP 的「客戶自行維修」方案詳細資訊，請連絡您當地的服務供應商。至於北美方案，請參閱 HP 網站 (<http://www.hp.com/go/selfrepair>)。

고객 셀프 수리

HP 제품은 수리 시간을 최소화하고 결함이 있는 부품 교체 시 더욱 융통성을 발휘할 수 있도록 하기 위해 고객 셀프 수리(CSR) 부품을 다량 사용하여 설계되었습니다. 진단 기간 동안 HP(또는 HP 서비스 공급업체 또는 서비스 협력업체)에서 CSR 부품을 사용하여 수리가 가능하다고 판단되면 HP는 해당 부품을 바로 사용자에게 보내어 사용자가 교체할 수 있도록 합니다. CSR 부품에는 두 가지 종류가 있습니다.

- **고객 셀프 수리가 의무 사항인 필수 부품.** 사용자가 HP에 이 부품의 교체를 요청할 경우 이 서비스에 대한 출장비 및 작업비가 청구됩니다.
- **고객 셀프 수리가 선택 사항인 부품.** 이 부품들도 고객 셀프 수리가 가능하도록 설계되었습니다. 하지만 사용자가 HP에 이 부품의 교체를 요청할 경우 사용자가 구입한 제품에 해당하는 보증 서비스 유형에 따라 추가 비용 없이 교체가 가능할 수 있습니다.

참고: 일부 HP 부품은 고객 셀프 수리가 불가능하도록 설계되었습니다. HP는 만족스러운 고객 보증을 위해 공인 서비스 제공업체를 통해 부품을 교체하도록 하고 있습니다. 이러한 부품들은 Illustrated Parts Catalog에 "No"라고 표시되어 있습니다.

CSR 부품은 재고 상태와 지리적 조건이 허용하는 경우 다음 영업일 납품이 가능하도록 배송이 이루어집니다. 지리적 조건이 허용하는 경우 추가 비용이 청구되는 조건으로 당일 또는 4시간 배송이 가능할 수도 있습니다. 도움이 필요하시면 HP 기술 지원 센터로 전화하십시오. 전문 기술자가 전화로 도움을 줄 것입니다. HP는 결함이 발생한 부품을 HP로 반환해야 하는지 여부를 CSR 교체 부품과 함께 배송된 자료에 지정합니다. 결함이 발생한 부품을 HP로 반환해야 하는 경우에는 지정된 기간 내(통상 영업일 기준 5일)에 HP로 반환해야 합니다. 이 때 결함이 발생한 부품은 제공된 포장 재료에 넣어 관련 설명서와 함께 반환해야 합니다. 결함이 발생한 부품을 반환하지 않는 경우 HP가 교체 부품에 대해 비용을 청구할 수 있습니다. 고객 셀프 수리의 경우, HP는 모든 운송 및 부품 반환 비용을 부담하며 이용할 운송업체 및 택배 서비스를 결정합니다.

HP 고객 셀프 수리 프로그램에 대한 자세한 내용은 가까운 서비스 제공업체에 문의하십시오. 북미 지역의 프로그램에 대해서는 HP 웹 사이트(<http://www.hp.com/go/selfrepair>)를 참조하십시오.

Acronyms and abbreviations

ABEND

abnormal end

ACU

Array Configuration Utility

AMP

Advanced Memory Protection

ASR

Automatic Server Recovery

BBWC

battery-backed write cache

CSR

Customer Self Repair

DPC

DIMMs per channel

ESD

electrostatic discharge

FBWC

flash-backed write cache

HP SIM

HP Systems Insight Manager

HP SUM

HP Smart Update Manager

IEC

International Electrotechnical Commission

iLO

Integrated Lights-Out

IML

Integrated Management Log

KVM

keyboard, video, and mouse

NMI

non-maskable interrupt

NVRAM

non-volatile memory

ORCA

Option ROM Configuration for Arrays

PCIe

peripheral component interconnect express

PCI-X

peripheral component interconnect extended

PDU

power distribution unit

POST

Power-On Self Test

PSP

ProLiant Support Pack

RBSU

ROM-Based Setup Utility

RDIMM

Registered Dual In-line Memory Module

RDP

Rapid Deployment Pack

SAN

storage area network

SAS

serial attached SCSI

SATA

serial ATA

SD

Secure Digital

SFF

small form-factor

TMRA

recommended ambient operating temperature

TPM

trusted platform module

UDIMM

Unregistered Dual In-Line Memory Module

UID

unit identification

VCA

Version Control Agent

VCRM

Version Control Repository Manager

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Index

A

- access panel 19
- acoustics statement for Germany 92
- Active Health System 71, 72
- ACU (Array Configuration Utility) 71, 78
- Advanced ECC memory 40, 41, 77
- air baffle 19, 20
- airflow requirements 24
- AMP (Advanced Memory Protection) 77
- AMP modes 77
- Array Configuration Utility (ACU) 78
- ASR (Automatic Server Recovery) 80
- authorized reseller 97
- auto-configuration process 76
- Automatic Server Recovery (ASR) 80

B

- Basic Input/Output System (BIOS) 71, 79
- battery 91
- bezel 59, 60
- BIOS (Basic Input/Output System) 71, 79
- BIOS upgrade 71, 79
- boot options 77
- BSMI notice 89
- buttons 8

C

- cables 60, 61, 66, 87
- cabling 66, 67, 68, 69
- Canadian notice 87
- Care Pack 23, 82
- Change Control 82
- Chinese notice 90
- compliance 86
- components 8
- configuration of system 27, 71
- configuring AMP modes 77
- connectors 8
- contacting HP 97
- controller 49

D

- Declaration of Conformity 87
- default settings 40
- diagnosing problems 83
- diagnostic tools 71, 74, 79, 80
- diagnostics utility 74
- DIMM installation guidelines 40
- DIMM slots 12
- DIMMs 37
- DIMMs, installation 43
- DIMMs, single- and dual-rank 37
- disposal, waste 88
- downloading files 97
- drive blank 44
- drivers 13, 81
- DVD-ROM drive 45

E

- electrical grounding requirements 25
- electrostatic discharge 93
- environmental requirements 23, 94
- Erase Utility 71, 74
- error messages 83
- European Union notice 88
- European Union regulatory notice 88
- expansion boards 56

F

- fan module locations 14
- FBWC cabling 68
- FBWC capacitor pack 51
- FCC (Federal Communications Commission)
 - notice 86, 87
- FCC rating label 86
- features 7, 8, 78
- Federal Communications Commission (FCC)
 - notice 86, 87
- firmware update 75, 81
- firmware upgrade utility, troubleshooting 83
- FlexibleLOM 54
- front panel buttons 9
- front panel components 8

G

graphics card cabling 60
grounding methods 93
grounding requirements 25

H

hard drives 8, 13, 14, 44
hard drives, installing 29, 44
hardware options 29
hardware options installation 26, 29
health driver 80
help resources 97
HP contact information 97
HP iLO Management Engine 71
HP Insight Diagnostics 74
HP Insight Diagnostics survey functionality 74
HP Insight Remote Support software 82
HP Smart memory 35
HP Smart Update Manager overview 71, 75
HP Support Pack for ProLiant 71, 75
HP website 97

I

identification number 86
identifying components 8
iLO (Integrated Lights-Out) 71
IML (Integrated Management Log) 71, 73
Insight Diagnostics 74, 81
installation services 23
installation, server options 26, 29
installing hardware 29
installing operating system 28
installing server options 26, 29
Integrated Lights-Out (iLO) 71
Integrated Management Log (IML) 73
Intelligent Provisioning 71, 73
internal cables 66

J

Japanese notice 89

K

Korean notices 89

L

laser devices 90
LEDs 8

LEDs, hard drive 14
LEDs, troubleshooting 83
lockstep memory 40, 41, 42

M

maintenance guidelines 81
memory 35, 37, 38, 40
memory configurations 38, 40
memory subsystem architecture 36
memory, Advanced ECC 40, 77
memory, configuration requirements 41
memory, configuring 39, 40
memory, lockstep 40, 41
memory, mirrored 78
memory, online spare 40, 42, 77
mirrored memory 78
multi-processor Advanced ECC population order 41

N

NMI jumper 13

O

online spare memory 40, 42, 77
online spare population guidelines 42
online spare population order, multi-processor 42
online spare population order, single-processor 42
operating systems 82
optimum environment 23
Option ROM Configuration for Arrays (ORCA) 71, 79
options installation 26, 29
ORCA (Option ROM Configuration for Arrays) 71, 79

P

PCI riser cage 20, 21
PDU (power distribution unit) 25
phone numbers 97
population guidelines, online spare 42
power cord 91
power distribution unit (PDU) 25
Power On button 17, 27
power supplies, removing 57
powering down 17
powering up 17, 76
preparation procedures 17
problem diagnosis 83
processors 29, 35

Q

QuickSpecs 71

R

rack installation 17, 18, 23, 25, 26
rack mounting hardware 26
rack resources 23
rack warnings 25
RBSU (ROM-Based Setup Utility) 76, 77
RBSU configuration 76
RDIMM configuration 39
rear panel buttons 10
rear panel components 9
recommended ambient operating temperature (TMRA) 24
recovery key 65
redundant ROM 80
registering the server 28
regulatory compliance notices 86, 88
required information 97
requirements, airflow 24
requirements, electrical grounding 25
requirements, environmental 23, 94
requirements, site 24
requirements, space 24
requirements, temperature 24
ROM redundancy 80
ROM-Based Setup Utility (RBSU) 65, 71, 76
ROMPaq utility 71, 79, 80

S

safety considerations 25
safety information 80
scripted installation 75
serial number 77
series number 86
server features and options 7, 29
Server mode 71
server options, installing 26, 29
server specifications 94
shipping carton contents 26
site requirements 24
Smart Update Manager 71, 75
space requirements 24
specifications 94
specifications, power 95
specifications, server 94
standards 86
static electricity 93

support 97
supported operating systems 82
supported targets 83
system battery 84
system board battery 91
system board components 11
system components 8
System Erase Utility 74
system maintenance switch 12
system, keeping current 81

T

T-10/T-15 Torx screwdriver 16
Taiwan battery recycling notice 91
technical support 82, 97
telephone numbers 97
temperature requirements 24
TMRA (recommended ambient operating temperature) 24
TPM (Trusted Platform Module) 62, 65
troubleshooting 83
troubleshooting resources 83
troubleshooting, firmware upgrade utility 83
Trusted Platform Module (TPM) 62, 63, 65

U

UDIMM configuration 39
Ukraine notice 90
updating the system ROM 80
USB support 80
utilities 71, 78
utilities, deployment 71, 75, 76

V

ventilation 23
Version Control Agent (VCA) 81
Version Control Repository Manager (VCRM) 81
Vietnam compliance marking notice 90

W

warnings 25
website, HP 97